# 21(+1) Channel High-Density E1 Line Interface Unit IDT82P2521

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2. A critical component is any components of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



## **Table of Contents**

TABLE OF CONTENTS	3
LIST OF TABLES	7
LIST OF FIGURES	8
FEATURES	
APPLICATIONS	
DESCRIPTION	
BLOCK DIAGRAM	
1 PIN ASSIGNMENT	
2 PIN DESCRIPTION	
3 FUNCTIONAL DESCRIPTION	
3.1 RECEIVE PATH	
3.1 RECEIVE PATH	
3.1.1 Receive Differential Mode	
3.1.1.2 Receive Single Ended Mode	
3.1.2 Equalizer	
3.1.2.1 Line Monitor	32
3.1.2.2 Receive Sensitivity	
3.1.3 Slicer	
3.1.4 Rx Clock & Data Recovery	
3.1.5 Decoder	
3.1.6 Receive System Interface	
3.1.7 Receiver Power Down	
3.2 TRANSMIT PATH	
3.2.1 Transmit System Interface	
3.2.2 Tx Clock Recovery	
3.2.3 Encoder	
3.2.4 Waveform Shaper	
3.2.4.1 Preset Waveform Template	
3.2.4.2 User-Programmable Arbitrary Waveform	
3.2.5 Line Driver	
3.2.5.1 Transmit Over Current Protection	
3.2.6 Tx Termination	
3.2.6.1 Transmit Differential Mode	
3.2.6.2 Transmit Single Ended Mode	
3.2.7 Transmitter Power Down	
3.2.8 Output High-Z on TTIP and TRING	
3.3 JITTER ATTENUATOR (RJA & TJA)	
3.4 DIAGNOSTIC FACILITIES	42

	3.4.1	Bipolar Violation (BPV) / Code Violation (CV) Detection and BPV Insertion	42
		3.4.1.1 Bipolar Violation (BPV) / Code Violation (CV) Detection	42
		3.4.1.2 Bipolar Violation (BPV) Insertion	
	3.4.2	Excessive Zeroes (EXZ) Detection	
	3.4.3	Loss of Signal (LOS) Detection	
		3.4.3.1 Line LOS (LLOS)	
		3.4.3.2 System LOS (SLOS)	
		3.4.3.3 Transmit LOS (TLOS)	
	3.4.4	Alarm Indication Signal (AIS) Detection and Generation	
		3.4.4.1 Alarm Indication Signal (AIS) Detection	
	o 4 -	3.4.4.2 (Alarm Indication Signal) AIS Generation	
	3.4.5	PRBS, QRSS, ARB and IB Pattern Generation and Detection	
		3.4.5.1 Pattern Generation	
		3.4.5.2 Pattern Detection	
	3.4.6	Error Counter	
		3.4.6.1 Automatic Error Counter Updating	
	0 4 7	3.4.6.2 Manual Error Counter Updating	
	3.4.7	Receive /Transmit Multiplex Function (RMF / TMF) Indication	
		3.4.7.1 RMFn Indication	
	3.4.8	3.4.7.2 TMFn Indication	
	3.4.0	3.4.8.1 Analog Loopback	
		3.4.8.2 Remote Loopback	
		3.4.8.3 Digital Loopback	
		3.4.8.4 Dual Loopback	
	3.4.9	Channel 0 Monitoring	
	0.4.0	3.4.9.1 G.772 Monitoring	
		3.4.9.2 Jitter Measurement (JM)	
35	CLOCK	(INPUTS AND OUTPUTS	
0.0	3.5.1	Free Running Clock Outputs on CLKE1	
	3.5.2	Clock Outputs on REFA/REFB	
	••••		61
		3.5.2.2 Frequency Synthesizer for REFA Clock Output	61
		3.5.2.3 Free Run Mode for REFA Clock Output	
		3.5.2.4 REFA/REFB Driven by External CLKA/CLKB Input	
		3.5.2.5 REFA and REFB in Loss of Signal (LOS) or Loss of Clock Condition	
	3.5.3	MCLK, Master Clock Input	
	3.5.4	XCLK, Internal Reference Clock Input	65
3.6	INTER	RUPT SUMMARY	66
MIS	CELLAN	NEOUS	68
4.1	RESET	-	68
	4.1.1	Power-On Reset	
	4.1.2	Hardware Reset	
	4.1.3	Global Software Reset	69
	4.1.4	Per-Channel Software Reset	69

4

4.3       POWER UP       70         4.4       HITLESS PROTECTION SWITCHING (HPS) SUMMARY       71         5       PROGRAMMING INFORMATION       72         5.1       REGISTER MAP       72         5.1.1       Global Register       72         5.1.2       Per-Channel Register       72         5.2.2       REGISTER DESCRIPTION       77         5.2.2       Per-Channel Register       76         6       JTAG       111         6.1       JTAG INSTRUCTION REGISTER (IR)       111         6.2       JTAG DATA REGISTER       111         6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BSP)       111         6.2.3       Boundary Scan Register (IDR)       111         6.2.4       Bypass Register (BSP)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7       THERMAL MANAGEMENT       111         7.3       HEATSINK EVALUATION       111         7.4       HAWPLE OF JUNCTION TEMPERATURE CALCULATION       111         7.4       HAWNLE OF JUNCTION TEMPERATURE CALCULATION       112         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       122		4.2	MICROPROCESSOR INTERFACE	. 69
5         PROGRAMMING INFORMATION         77           5.1         REGISTER MAP         77           5.1.1         Global Register         77           5.1.2         Per-Channel Register         77           5.2.2         REGISTER DESCRIPTION         77           5.2.1         Global Register         76           5.2.2         Per-Channel Register         76           6         JTAG         77           6.1         JTAG INSTRUCTION REGISTER (IR)         111           6.1         JTAG DATA REGISTER         111           6.2.1         Device Identification Register (IDR)         111           6.2.1         Device Identification Register (IDR)         111           6.2.1         Boundary Scan Register (BSR)         111           6.3         TEST ACCESS PORT (TAP) CONTROLLER         111           7.1         JUNCTION TEMPERATURE         111           7.2         EXAMPLE OF JUNCTION TEMPERATURE CALCULATION         111           7.3         HEATSINK EVALUATION         111           7.4         JUNCTION TEMPERATURE         122           8.1         ABSOLUTE MAXIMUM RATINGS         122           8.1         ABSOLUTE MAXIMUM RATINGS         122		4.3	POWER UP	. 70
5.1       REGISTER MAP       77         5.1.1       Global Register       77         5.1.2       Per-Channel Register       77         5.2       REGISTER DESCRIPTION       77         5.2.1       Global Register       77         5.2.2       Per-Channel Register       76         6       JTAG       111         6.1       JTAG INSTRUCTION REGISTER (IR)       111         6.2       JTAG DATA REGISTER       111         6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BYP)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7       THERMAL MANAGEMENT       111         7.3       HEATSINK EVALUATION       111         7.4       THERMAL MANAGEMENT       112         7.5       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       112         7.4       HEATSINK EVALUATION       111         7.5       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       112         7.4       HEATSINK EVALUATION       112         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       122         8.1       ABSOLUTE MAXIMUM RATINGS       122         <		4.4	HITLESS PROTECTION SWITCHING (HPS) SUMMARY	70
5.1.1       Global Register       77         5.1.2       Per-Channel Register       77         5.2       REGISTER DESCRIPTION       77         5.2.1       Global Register       77         5.2.2       Per-Channel Register       76         6       JTAG       111         6.1       JTAG INSTRUCTION REGISTER (IR)       111         6.2       JTAG DATA REGISTER       111         6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BYP)       111         6.2.3       Boundary Scan Register (IDR)       111         6.2.4       Bypass Register (BYP)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7       THERMAL MANAGEMENT       111         7.1       JUNCTION TEMPERATURE       111         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       111         7.3       HEATSINK EVALUATION       111         7.4       JUNCTION TEMPERATURE       1120         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       1220         8.1       ABSOLUTE MAXIMUM RATINGS       1220         8.1       ABSOLUTE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1	5	PRO	OGRAMMING INFORMATION	73
5.1.2       Per-Channel Register       74         5.2       REGISTER DESCRIPTION       77         5.2.1       Global Register       77         5.2.2       Per-Channel Register       88         6       JTAG       111         6.1       JTAG INSTRUCTION REGISTER (IR)       111         6.2       JTAG DATA REGISTER       111         6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BYP)       111         6.2.3       Boundary Scan Register (BSR)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7       HERMAL MANAGEMENT       111         7.1       JUNCTION TEMPERATURE       111         7.2       EXAMPLE OF JUNCTION TEMPERATURE       111         7.3       HEATSINK EVALUATION       112         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.2       RECOMMENDED OPERATING CONDITIONS       120         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1		5.1	REGISTER MAP	. 73
5.2       REGISTER DESCRIPTION       77         5.2.1       Global Register       78         5.2.2       Per-Channel Register       88         6       JTAG       111         6.1       JTAG INSTRUCTION REGISTER (IR)       111         6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BYP)       111         6.2.3       Boundary Scan Register (IDR)       111         6.2.3       Boundary Scan Register (BSR)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7.1       JUNCTION TEMPERATURE       111         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       112         7.3       HEATSINK EVALUATION       112         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       122         8.1       ABSOLUTE MAXIMUM RATINGS       122         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.7       F 1 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS			5.1.1 Global Register	. 73
5.2.1       Global Register       77         5.2.2       Per-Channel Register       88         6       JTAG       111         6.1       JTAG INSTRUCTION REGISTER (IR)       111         6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BYP)       111         6.2.3       Boundary Scan Register (BSR)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7       HERMAL MANAGEMENT       119         7.1       JUNCTION TEMPERATURE       111         7.3       HEATSINK EVALUATION       119         7.4       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       119         7.3       HEATSINK EVALUATION       119         7.4       HEATSINK EVALUATION       112         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       122         8.1       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECRIVER ELECTRICAL CHARACTERISTICS       122			5.1.2 Per-Channel Register	. 74
5.2.2       Per-Channel Register       88         6       JTAG       111         6.1       JTAG INSTRUCTION REGISTER (IR)       111         6.2       JTAG DATA REGISTER       111         6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BYP)       111         6.2.3       Boundary Scan Register (BSR)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7.1       JUNCTION TEMPERATURE       111         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       111         7.3       HEATSINK EVALUATION       112         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       122         8.1       ABSOLUTE MAXIMUM RATINGS       122         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.7       E1 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.9       CLKE1 TIMING CHARACTERISTICS		5.2		
6       JTAG       11         6.1       JTAG INSTRUCTION REGISTER (IR)       11         6.2       JTAG DATA REGISTER       11         6.2.1       Device Identification Register (IDR)       11         6.2.2       Bypass Register (BYP)       11         6.2.3       Boundary Scan Register (BSR)       11         6.3       TEST ACCESS PORT (TAP) CONTROLLER       11         7       THERMAL MANAGEMENT       119         7.1       JUNCTION TEMPERATURE       111         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       119         7.3       HEATSINK EVALUATION       111         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       124         8.6       E1 RECEIVER AND RECEIVER TIMING CHARACTERISTICS       122         8.6       TRANSMITTER AND RECEIVER TIMING CHARACTERIS				
6.1       JTAG INSTRUCTION REGISTER (IR)       111         6.2       JTAG DATA REGISTER       111         6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BYP)       111         6.2.3       Boundary Scan Register (BSR)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7       THERMAL MANAGEMENT       111         7.1       JUNCTION TEMPERATURE       111         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       111         7.3       HEATSINK EVALUATION       111         7.4       JUNCTION TEMPERATURE       111         7.3       HEATSINK EVALUATION       111         7.4       JUNCTION TEMPERATURE       111         7.5       HEATSINK EVALUATION       112         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       122         8.1       ABSOLUTE MAXIMUM RATINGS       122         8.1       ABSOLUTE MAXIMUM RATINGS       122         8.1       ABSOLUTE MAXIMUM RATINGS       122         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.2       RECOMMENDED OPERATING CONDITION AND DISSIPATION (TYPICAL) 1       122         8.5				
6.2 JTAG DATA REGISTER       111         6.2.1 Device Identification Register (IDR)       111         6.2.2 Bypass Register (BYP)       111         6.2.3 Boundary Scan Register (BSR)       111         6.3 TEST ACCESS PORT (TAP) CONTROLLER       111         7 <b>THERMAL MANAGEMENT</b> 112         7.1 JUNCTION TEMPERATURE       113         7.2 EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       113         7.3 HEATSINK EVALUATION       114         8 <b>PHYSICAL AND ELECTRICAL SPECIFICATIONS</b> 122         8.1 ABSOLUTE MAXIMUM RATINGS       122         8.2 RECOMMENDED OPERATING CONDITIONS       122         8.3 DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5 D.C. CHARACTERISTICS       122         8.6 E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.7 E1 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.8 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.1 TANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.1 O JITTER ATTENUATION CHARACTERISTICS       122         8.10 JITTER ATTENUATION CHARACTERISTICS <th>6</th> <th></th> <th></th> <th></th>	6			
6.2.1       Device Identification Register (IDR)       111         6.2.2       Bypass Register (BYP)       111         6.2.3       Boundary Scan Register (BSR)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7 <b>THERMAL MANAGEMENT</b> 119         7.1       JUNCTION TEMPERATURE       119         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       119         7.3       HEATSINK EVALUATION       119         7.3       HEATSINK EVALUATION       119         7.3       HEATSINK EVALUATION       119         7.4       ABSOLUTE MAXIMUM RATINGS       120         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.2       RECOMMENDED OPERATING CONDITIONS       120         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.5       D.C. CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RENSMITTER AND RECEIVER TIMING CHARACTERISTICS </td <td></td> <td></td> <td></td> <td></td>				
6.2.2       Bypass Register (BYP)       111         6.2.3       Boundary Scan Register (BSR)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7       THERMAL MANAGEMENT       111         7.1       JUNCTION TEMPERATURE       111         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       111         7.3       HEATSINK EVALUATION       111         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       122         8.1       ABSOLUTE MAXIMUM RATINGS       122         8.1       ABSOLUTE MAXIMUM RATINGS       122         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.7       E1 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122		6.2		
6.2.3       Boundary Scan Register (BSR)       111         6.3       TEST ACCESS PORT (TAP) CONTROLLER       111         7       THERMAL MANAGEMENT       111         7.1       JUNCTION TEMPERATURE       113         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       119         7.3       HEATSINK EVALUATION       119         7.3       HEATSINK EVALUATION       119         7.3       HEATSINK EVALUATION       119         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.1       ABSOLUTE MAXIMUM RATINGS       122         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECEIVER AND RECEIVER TIMING CHARACTERISTICS       122         8.7       F1 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.8       <				
6.3 TEST ACCESS PORT (TAP) CONTROLLER       111         7 THERMAL MANAGEMENT       112         7.1 JUNCTION TEMPERATURE       113         7.2 EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       114         7.3 HEATSINK EVALUATION       115         7 PHYSICAL AND ELECTRICAL SPECIFICATIONS       112         8 PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1 ABSOLUTE MAXIMUM RATINGS       120         8.2 RECOMMENDED OPERATING CONDITIONS       122         8.3 DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5 D.C. CHARACTERISTICS       124         8.6 E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.7 E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       122         8.8 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.9 CLKE1 TIMING CHARACTERISTICS       122         8.10 LITER AND RECEIVER TIMING CHARACTERISTICS       122         8.11 MICROPROCESSOR INTERFACE TIMING       133         8.11.1 Serial Microprocessor Interface       133         8.11.2 Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1 Read Cycle Specification       134			6.2.2 Bypass Register (BYP)	11/
7       THERMAL MANAGEMENT       119         7.1       JUNCTION TEMPERATURE       119         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       119         7.3       HEATSINK EVALUATION       119         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       126         8.7       E1 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       126         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.10       JITTER ATTENUATION CHARACTERISTICS       122         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       133         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Inte		63		
7.1       JUNCTION TEMPERATURE       113         7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       113         7.3       HEATSINK EVALUATION       114         7.3       HEATSINK EVALUATION       115         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       122         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.9       CLKE1 TIMING CHARACTERISTICS       122         8.10       JITTER ATTENUATION CHARACTERISTICS       122         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       133         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134<	7			
7.2       EXAMPLE OF JUNCTION TEMPERATURE CALCULATION       119         7.3       HEATSINK EVALUATION       119         8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.2       RECOMMENDED OPERATING CONDITIONS       122         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       122         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.9       CLKE1 TIMING CHARACTERISTICS       122         8.10       JITTER ATTENUATION CHARACTERISTICS       122         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       133         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	1			
7.3 HEATSINK EVALUATION       119         8 PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1 ABSOLUTE MAXIMUM RATINGS       120         8.2 RECOMMENDED OPERATING CONDITIONS       122         8.3 DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5 D.C. CHARACTERISTICS       122         8.6 E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.7 E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       122         8.8 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       122         8.9 CLKE1 TIMING CHARACTERISTICS       122         8.10 JITTER ATTENUATION CHARACTERISTICS       122         8.11 MICROPROCESSOR INTERFACE TIMING       132         8.11.1 Serial Microprocessor Interface       133         8.11.2.1 Read Cycle Specification       134		1.1		
8       PHYSICAL AND ELECTRICAL SPECIFICATIONS       120         8.1       ABSOLUTE MAXIMUM RATINGS       120         8.2       RECOMMENDED OPERATING CONDITIONS       121         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       124         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       126         8.7       E1 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       126         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       127         8.9       CLKE1 TIMING CHARACTERISTICS       129         8.10       JITTER ATTENUATION CHARACTERISTICS       129         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       132         8.11.2.1       Read Cycle Specification       134				
8.1       ABSOLUTE MAXIMUM RATINGS       120         8.2       RECOMMENDED OPERATING CONDITIONS       121         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       126         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       126         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       126         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       127         8.9       CLKE1 TIMING CHARACTERISTICS       122         8.10       JITTER ATTENUATION CHARACTERISTICS       129         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134				
8.2       RECOMMENDED OPERATING CONDITIONS       12'         8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       12'         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       12'         8.5       D.C. CHARACTERISTICS       12'         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       12'         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       12'         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       12'         8.9       CLKE1 TIMING CHARACTERISTICS       12'         8.10       JITTER ATTENUATION CHARACTERISTICS       12'         8.11       MICROPROCESSOR INTERFACE TIMING       13'         8.11.1       Serial Microprocessor Interface       13'         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       13'         8.11.2.1       Read Cycle Specification       13'	•			400
8.3       DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1       122         8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       122         8.5       D.C. CHARACTERISTICS       122         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       122         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       126         8.7       F1 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       126         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       127         8.9       CLKE1 TIMING CHARACTERISTICS       129         8.10       JITTER ATTENUATION CHARACTERISTICS       129         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	PH		
8.4       DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1       123         8.5       D.C. CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       125         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       126         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       126         8.9       CLKE1 TIMING CHARACTERISTICS       125         8.10       JITTER ATTENUATION CHARACTERISTICS       126         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	8.1	ABSOLUTE MAXIMUM RATINGS	120
8.5       D.C. CHARACTERISTICS       124         8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       126         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       126         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       126         8.9       CLKE1 TIMING CHARACTERISTICS       127         8.9       CLKE1 TIMING CHARACTERISTICS       129         8.10       JITTER ATTENUATION CHARACTERISTICS       129         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	8.1 8.2	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS	120 121
8.6       E1 RECEIVER ELECTRICAL CHARACTERISTICS       129         8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       120         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       121         8.9       CLKE1 TIMING CHARACTERISTICS       122         8.10       JITTER ATTENUATION CHARACTERISTICS       122         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	8.1 8.2 8.3	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1	120 121 122
8.7       E1 TRANSMITTER ELECTRICAL CHARACTERISTICS       126         8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       127         8.9       CLKE1 TIMING CHARACTERISTICS       129         8.10       JITTER ATTENUATION CHARACTERISTICS       129         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	8.1 8.2 8.3	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1	120 121 122 123
8.8       TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS       127         8.9       CLKE1 TIMING CHARACTERISTICS       129         8.10       JITTER ATTENUATION CHARACTERISTICS       129         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	8.1 8.2 8.3	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS	120 121 122 123 124
8.9       CLKE1 TIMING CHARACTERISTICS       129         8.10       JITTER ATTENUATION CHARACTERISTICS       129         8.11       MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	8.1 8.2 8.3	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS	120 121 122 123 124 125
8.10 JITTER ATTENUATION CHARACTERISTICS       129         8.11 MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS	120 121 122 123 124 125 126
8.11 MICROPROCESSOR INTERFACE TIMING       132         8.11.1       Serial Microprocessor Interface       132         8.11.2       Parallel Motorola Non-Multiplexed Microprocessor Interface       134         8.11.2.1       Read Cycle Specification       134	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS	120 121 122 123 124 125 126 127
8.11.2 Parallel Motorola Non-Multiplexed Microprocessor Interface	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS CLKE1 TIMING CHARACTERISTICS	120 121 122 123 124 125 126 127 129
8.11.2.1 Read Cycle Specification 134	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS CLKE1 TIMING CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS	120 121 122 123 124 125 126 127 129 129
	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS CLKE1 TIMING CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS 1 MICROPROCESSOR INTERFACE TIMING	120 121 122 123 124 125 126 127 129 129 132
	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS O JITTER AND RECEIVER TIMING CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS 1 MICROPROCESSOR INTERFACE TIMING 8.11.1 Serial Microprocessor Interface 8.11.2 Parallel Motorola Non-Multiplexed Microprocessor Interface	120 121 122 123 124 125 126 127 129 129 132 132 134
	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS CLKE1 TIMING CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS 1 MICROPROCESSOR INTERFACE TIMING 8.11.1 Serial Microprocessor Interface 8.11.2 Parallel Motorola Non-Multiplexed Microprocessor Interface 8.11.2.1 Read Cycle Specification	120 121 122 123 124 125 126 127 129 129 132 132 132 134 134
	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS CLKE1 TIMING CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS 1 MICROPROCESSOR INTERFACE TIMING 8.11.1 Serial Microprocessor Interface 8.11.2 Parallel Motorola Non-Multiplexed Microprocessor Interface 8.11.2.1 Read Cycle Specification	120 121 122 123 124 125 126 127 129 129 132 132 132 134 134
	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS CLKE1 TIMING CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS AND RECEIVER TIMING A11.1 Serial Microprocessor Interface 8.11.2 Parallel Motorola Non-Multiplexed Microprocessor Interface 8.11.3 Parallel Intel Non-Multiplexed Microprocessor Interface 8.11.3 Parallel Intel Non-Multiplexed Microprocessor Interface 8.11.3 Parallel Intel Non-Multiplexed Microprocessor Interface	120 121 122 123 124 125 126 127 129 129 132 132 132 134 135 136
	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS CLKE1 TIMING CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS 1 MICROPROCESSOR INTERFACE TIMING 8.11.1 Serial Microprocessor Interface 8.11.2 Parallel Motorola Non-Multiplexed Microprocessor Interface 8.11.2 Write Cycle Specification 8.11.3 Parallel Intel Non-Multiplexed Microprocessor Interface 8.11.3 Parallel Intel Non-Multiplexed Microprocessor Interface 8.11.3 Read Cycle Specification	120 121 122 123 124 125 126 127 129 129 132 132 132 134 134 135 136 136
8.11.4.1 Read Cycle Specification	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS	120 121 122 123 124 125 126 127 129 129 132 132 134 134 135 136 136
8.11.4.2 Write Cycle Specification	8	8.1 8.2 8.3 8.4 8.5 8.6 8.7 8.8 8.9 8.10	ABSOLUTE MAXIMUM RATINGS RECOMMENDED OPERATING CONDITIONS DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL) 1 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) 1 D.C. CHARACTERISTICS E1 RECEIVER ELECTRICAL CHARACTERISTICS E1 TRANSMITTER ELECTRICAL CHARACTERISTICS TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS CLKE1 TIMING CHARACTERISTICS D JITTER ATTENUATION CHARACTERISTICS MICROPROCESSOR INTERFACE TIMING 8.11.2 Parallel Motorola Non-Multiplexed Microprocessor Interface 8.11.2.1 Read Cycle Specification	120 121 122 123 124 125 126 127 129 129 132 132 134 135 136 136 137 138



8.11.5 Parallel Intel Multiplexed Microprocessor Interface	140
8.11.5.1 Read Cycle Specification	
8.11.5.2 Write Cycle Specification	141
8.12 JTAG TIMING CHARACTERISTICS	
GLOSSARY	143
INDEX	145
ORDERING INFORMATION	

# Renesas



## **List of Tables**

Table-1 Table-2	Impedance Matching Value in Receive Differential Mode Multiplex Pin Used in Receive System Interface	30 33
Table-3	Multiplex Pin Used in Transmit System Interface	35
Table-4	PULS[3:0] Setting	36
Table-5	Transmit Waveform Value for E1 75 ohm	
Table-6	Transmit Waveform Value for E1 120 ohm	37
Table-7	Impedance Matching Value in Transmit Differential Mode	38
Table-8	EXZ Definition	42
Table-9	LLOS Criteria	43
Table-10	SLOS Criteria	44
		45
Table-12	AIS Criteria	46
Table-13	RMFn Indication	51
Table-14	TMFn Indication	52
Table-15	Clock Output on CLKE1	60
Table-16	Interrupt Summary	66
Table-17	After Reset Effect Summary	68
Table-18	Microprocessor Interface	69



## **List of Figures**

	Functional Block Diagram	
	640-Pin TEPBGA (Top View) - Outline	
•	640-Pin TEPBGA (Top View) - Top Left	
	640-Pin TEPBGA (Top View) - Top Right	
Figure-5 6	640-Pin TEPBGA (Top View) - Bottom Left	16
	640-Pin TEPBGA (Top View) - Bottom Right	
Figure-7	Switch between Impedance Matching Modes	29
Figure-8 I	Receive Differential Line Interface with Twisted Pair Cable (with transformer)	30
	Receive Differential Line Interface with Coaxial Cable (with transformer)	
Figure-10	Receive Differential Line Interface with Twisted Pair Cable (transformer-less, non standard compliant)	30
Figure-11	Receive Single Ended Line Interface with Coaxial Cable (with transformer)	31
	Receive Single Ended Line Interface with Coaxial Cable (transformer-less, non standard compliant)	
•	Receive Path Monitoring	
	Transmit Path Monitoring	
	E1 Waveform Template	
	E1 Waveform Template Measurement Circuit	
	Transmit Differential Line Interface with Twisted Pair Cable (with Transformer)	
	Transmit Differential Line Interface with Coaxial Cable (with transformer)	
	Transmit Differential Line Interface with Twisted Pair Cable (transformer-less, non standard compliant)	
	Transmit Single Ended Line Interface with Coaxial Cable (with transformer)	
•	Jitter Attenuator	
	LLOS Indication on Pins	
•	TLOS Detection Between Two Channels	
•	Pattern Generation (1)	
	Pattern Generation (2)	
0	PRBS / ARB Detection	
	IB Detection	
	Automatic Error Counter Updating	
-	Manual Error Counter Updating	
	Priority Of Diagnostic Facilities During Analog Loopback	
Figure-31	Priority Of Diagnostic Facilities During Manual Remote Loopback	54
	Priority Of Diagnostic Facilities During Digital Loopback	
Figure-33	Priority Of Diagnostic Facilities During Manual Remote Loopback + Manual Digital Loopback	57
Figure-34	Priority Of Diagnostic Facilities During Manual Remote Loopback + Automatic Digital Loopback	57
Figure-35	G.772 Monitoring	58
Figure-36	Automatic JM Updating	59
Figure-37	Manual JM Updating	59
Figure-38	REFA Output Options in Normal Operation	62
Figure-39	REFB Output Options in Normal Operation	63
	REFA Output in LLOS Condition (When RCLKn Is Selected)	
	REFA Output in No CLKA Condition (When CLKA Is Selected)	
	Interrupt Service Process	
	Reset	
	1+1 HPS Scheme, Differential Interface (Shared Common Transformer)	
•	1:1 HPS Scheme, Differential Interface (Individual Transformer)	
	1+1 HPS Scheme, E1 75 ohm Single-Ended Interface (Shared Common Transformer)	
-	JTAG Architecture	
•	JTAG Alcinecture	

Figure-49	Transmit Clock Timing Diagram	128
Figure-50	Receive Clock Timing Diagram	128
Figure-51	CLKE1 Clock Timing Diagram	129
Figure-52	E1 Jitter Tolerance Performance	130
Figure-53	E1 Jitter Transfer Performance	131
	Read Operation in Serial Microprocessor Interface	132
Figure-55	Write Operation in Serial Microprocessor Interface	132
Figure-56	Timing Diagram	133
	Parallel Motorola Non-Multiplexed Microprocessor Interface Read Cycle	134
Figure-58	Parallel Motorola Non-Multiplexed Microprocessor Interface Write Cycle	135
Figure-59	Parallel Intel Non-Multiplexed Microprocessor Interface Read Cycle	136
Figure-60	Parallel Intel Non-Multiplexed Microprocessor Interface Write Cycle	137
Figure-61	Parallel Motorola Multiplexed Microprocessor Interface Read Cycle	138
Figure-62	Parallel Motorola Multiplexed Microprocessor Interface Write Cycle	139
Figure-63	Parallel Intel Multiplexed Microprocessor Interface Read Cycle	140
Figure-64	Parallel Intel Multiplexed Microprocessor Interface Write Cycle	141
Figure-65	JTAG Timing	142



### 21(+1) Channel High-Density E1 Line Interface Unit

#### **FEATURES**

- Integrates 21+1 channels E1 short haul line interface units for 120 Ω E1 twisted pair cable and 75 Ω E1 coaxial cable applications
- Per-channel configurable Line Interface options
  - Supports various line interface options
    - Differential and Single Ended line interfaces
    - true Single Ended termination on primary and secondary side of transformer for E1 75  $\Omega$  coaxial cable applications
    - transformer-less for Differential interfaces
  - Fully integrated and software selectable receive and transmit termination
    - Option 1: Fully Internal Impedance Matching with integrated receive termination resistor
    - Option 2: Partially Internal Impedance Matching with common external resistor for improved device power dissipation
    - Option 3: External impedance Matching termination
  - Supports global configuration and per-channel configuration to E1 mode

#### • Per-channel programmable features

- Provides E1 short haul waveform templates and userprogrammable arbitrary waveform templates
- Provides two JAs (Jitter Attenuator) for each channel of receiver and transmitter
- · Supports AMI/HDB3 encoding and decoding

#### Per-channel System Interface options

- Supports Single Rail, Dual Rail with clock or without clock and sliced system interface
- Integrated Clock Recovery for the transmit interface to recover transmit clock from system transmit data

#### • Per-channel system and diagnostic functions

- Provides transmit driver over-current detection and protection with optional automatic high impedance of transmit interface
- Detects and generates PRBS (Pseudo Random Bit Sequence), ARB (Arbitrary Pattern) and IB (Inband Loopback) in either receive or transmit direction
- Provides defect and alarm detection in both receive and transmit directions.
- Defects include BPV (Bipolar Violation) /CV (Code Violation) and EXZ (Excessive Zeroes)
- Alarms include LLOS (Line LOS), SLOS (System LOS), TLOS (Transmit LOS) and AIS (Alarm Indication Signal)
- Programmable LLOS detection /clear levels. Compliant with ITU and ANSI specifications
- Various pattern, defect and alarm reporting options
  - Serial hardware LLOS reporting (LLOS, LLOS0) for all 22 channels
  - Configurable per-channel hardware reporting with RMF/TMF (Receive /Transmit Multiplex Function)
  - Register access to individual registers or 16-bit error counters

- Supports Analog Loopback, Digital Loopback and Remote Loopback
- Supports T1.102 line monitor
- Channel 0 monitoring options
  - Channel 0 can be configured as monitoring channel or regular channel to increase capacity
  - Supports all internal G.772 Monitoring for Non-Intrusive Monitoring of any of the 21 channels of receiver or transmitter
  - Jitter Measurement per ITU 0.171
- ◆ Hitless Protection Switching (HPS) without external Relays
  - · Supports 1+1 and 1:1 hitless protection switching
  - Asynchronous hardware control (OE, RIM) for fast global high impedance of receiver and transmitter (hot switching between working and backup board)
  - · High impedance transmitter and receiver while powered down
  - Per-channel register control for high impedance, independent for receiver and transmitter

#### Clock Inputs and Outputs

- Flexible master clock (N x 2.048 MHz) (1  $\leq$  N  $\leq$  8, N is an integer number)
- Two selectable reference clock outputs
  - from the recovered clock of any of the 22 channels
  - from external clock input
  - from device master clock
- Integrated clock synthesizer can multiply or divide the reference clock to a wide range of frequencies: 8 KHz, 64 KHz, 2.048 MHz, 4.096 MHz, 8.192 MHz, 19.44 MHz and 32.768 MHz
- Cascading is provided to select a single reference clock from multiple devices without the need for any external logic

#### Microprocessor Interface

 Supports Serial microprocessor interface and Parallel Intel / Motorola Non-Multiplexed /Multiplexed microprocessor interface

#### Other Key Features

- IEEE1149.1 JTAG boundary scan
- Two general purpose I/O pins
- 3.3 V I/O with 5 V tolerant inputs
- 3.3 V and 1.8 V power supply
- Package: 640-pin TEPBGA (31 mm X 31 mm)

#### ♦ Applicable Standards

- AT&T Pub 62411 Accunet T1.5 Service
- ANSI T1.102 and T1.403
- · Bellcore TR-TSY-000009, GR-253-CORE and GR-499-CORE
- ETSI CTR12/13
- ETS 300166 and ETS 300 233
- + G.703, G.735, G.736, G.742, G.772, G.775, G.783 and G.823
- 0.161
- ITU I.431 and ITU O.171

#### APPLICATIONS

- SDH/SONET multiplexers
- Central office or PBX (Private Branch Exchange)
- Digital access cross connects
- Remote wireless modules
- Microwave transmission systems

#### DESCRIPTION

The IDT82P2521 is a 21+1 channels high-density E1 short haul Line Interface Unit. Each channel of the IDT82P2521 can be independently configured. The configuration is performed through a Serial or Parallel Intel/Motorola Non-Multiplexed /Multiplexed microprocessor interface.

In the receive path, through a Single Ended or Differential line interface, the received signal is processed by an adaptive Equalizer and then sent to a Slicer. Clock and data are recovered from the digital pulses output from the Slicer. After passing through an enabled or disabled Receive Jitter Attenuator, the recovered data is decoded using AMI/ HDB3 line code rule in Single Rail NRZ Format mode and output to the system, or output to the system without decoding in Dual Rail NRZ Format mode and Dual Rail RZ Format mode. In the transmit path, the data to be transmitted is input on TDn in Single Rail NRZ Format mode or TDPn/TDNn in Dual Rail NRZ Format mode and Dual Rail RZ Format mode, and is sampled by a transmit reference clock. The clock can be supplied externally from TCLKn or recovered from the input transmit data by an internal Clock Recovery. A selectable JA in Tx path is used to de-jitter gapped clocks. To meet E1 waveform standards, two E1 templates, as well as an arbitrary waveform generator are provided. The data through the Waveform Shaper, the Line Driver and the Tx Transmitter is output on TTIPn and TRINGn.

Alarms (including LOS, AIS) and defects (including BPV, EXZ) are detected in both receive line side and transmit system side. AIS alarm, PRBS, ARB and IB patterns can be generated /detected in receive / transmit direction for testing purpose. Analog Loopback, Digital Loopback and Remote Loopback are all integrated for diagnostics.

Channel 0 is a special channel. Besides normal operation as the other 21 channels, channel 0 also supports G.772 Monitoring and Jitter Measurement per ITU O.171.

A line monitor function per T1.102 is available to provide a Non-Intrusive Monitoring of channels of other devices.

JTAG per IEEE 1149.1 is also supported by the IDT82P2521.

#### **BLOCK DIAGRAM**



Figure-1 Functional Block Diagram



#### **1 PIN ASSIGNMENT**

Figure-2 shows the outline of the pin assignment. For a clearer description, four segments are divided in this figure and the details of each are shown from Figure-3 to Figure-6.



Figure-2 640-Pin TEPBGA (Top View) - Outline







Figure-4 640-Pin TEPBGA (Top View) - Top Right

IDT82P2521



Figure-5 640-Pin TEPBGA (Top View) - Bottom Left



Figure-6 640-Pin TEPBGA (Top View) - Bottom Right

#### **2 PIN DESCRIPTION**

Name I / O Pin No. <sup>1</sup> Description		Description			
Line Interface					
RTIPn RRINGn (n=0~21)	Input	P3, R5, V4, W5, AA4, AB5, AE28, AE26, AA26, W28, T28, R26, L28, L26, G26, F28, D6, D4, D3, G4, H5, M5 N3, P5, U4, V5, Y4, AA5, AD28, AD26, Y26, W27, R28, P26, K28, K26, F26, E28, E6, D5, E3, F4, G5, L5	<ul> <li>RTIPn / RRINGn: Receive Bipolar Tip/Ring for Channel 0 ~ 21</li> <li>The receive line interface supports both Receive Differential mode and Receive Single Ended mode.</li> <li>In Receive Differential mode, the received signal is coupled into RTIPn and RRINGn via a 1:1 transformer or without a transformer (transformer-less).</li> <li>In Receive Single Ended mode, RRINGn should be left open. The received signal is input on RTIPn via a 2:1 (step down) transformer or without a transformer (transformer (transformer-less).</li> <li>These pins will become High-Z globally or channel specific in the following conditions: <ul> <li>Global High-Z:</li> <li>Connecting the RIM pin to low;</li> <li>Loss of MCLK</li> <li>During and after power-on reset, hardware reset or global software reset;</li> <li>Per-channel High-Z</li> <li>Receiver power down by writing '1' to the R_OFF bit (b5, RCF0,)</li> </ul> </li> </ul>		
TTIPn TRINGn (n=0~21)	Output	L1, M1, R1, U1, Y1, AA1, AF30, AD30, AA30, W30, T30, P30, L30, J30, F30, D30, A5, A4, A3, C1, F1, J1 K1, M2, R2, T1, W1, AA2, AE30, AC30, Y30, V30, R30, N30, K30, H30, E30, C30, A6, B4, B3, D1, E1, J2	<ul> <li>TTIPn / TRINGn: Transmit Bipolar Tip /Ring for Channel 0 ~ 21</li> <li>The transmit line interface supports both Transmit Differential mode and Transmit Single Ended mode.</li> <li>In Transmit Differential mode, TTIPn outputs a positive differential pulse while TRINGn outputs a negative differential pulse. The pulses are coupled to the line side via a 1:2 (step up) transformer or without a transformer (transformer-less).</li> <li>In Transmit Single Ended mode, TRINGn should be left open (it is shorted to ground internally). The signal presented at TTIPn is output to the line side via a 1:2 (step up) transformer.</li> <li>These pins will become High-Z globally or channel specific in the following conditions:</li> <li>Global High-Z:</li> <li>Connecting the OE pin to low;</li> <li>Loss of MCLK;</li> <li>During and after power-on reset, hardware reset or global software reset;</li> <li>Per-channel High-Z</li> <li>Writing '0' to the OE bit (b6, TCF0,)<sup>2</sup>;</li> <li>Loss of TCLKn in Transmit Single Rail NRZ Format mode or Transmit Dual Rail NRZ Format mode, except that the channel is in Remote Loopback or transmit internal pattern with XCLK<sup>3</sup>;</li> <li>Transmitter power down by writing '1' to the T_OFF bit (b5, TCF0,);</li> <li>Per-channel software reset;</li> <li>The THZ_OC bit (b4, TCF0,) is set to '1' and the transmit driver over-current is detected.</li> </ul>		

Note:

1. The pin number of the pins with the footnote 'n' is listed in order of channel (CH0 ~ CH21).

2. The content in the brackets indicates the position and the register name of the preceding bit. After the register name, if the punctuation ',...' is followed, this bit is in a per-channel register. If there is no punctuation following the address, this bit is in a global register or in a channel 0 only register. The addresses and details are included in Chapter 5 Programming Information.

3. XCLK is derived from MCLK. It is 2.048 MHz.

RENESAS	
IDT82P2521	

Name	I / O	Pin No.	Description		
	System Interface				
RDn / RDPn (n=0~21)	Output	AH9, AC4, AG1, AH3, AH6, AK8, AK20, AH21, AH24, AK26, AH29, A27, A24, C23, C20, A18, C17, B15, D14, B12, D11, D8	RDn: Receive Data for Channel 0 ~ 21 When the receive system interface is configured to Single Rail NRZ Format mode, this multi- plex pin is used as RDn. The decoded NRZ data is updated on the active edge of RCLKn. The active level on RDn is selected by the RD_INV bit (b3, RCF1,). When the receiver is powered down, RDn will be in High-Z state or low, as selected by the RHZ bit (b6, RCF0,).		
			<ul> <li>RDPn: Positive Receive Data for Channel 0 ~ 21</li> <li>When the receive system interface is configured to Dual Rail NRZ Format mode, Dual Rail RZ Format mode or Dual Rail Sliced mode, this multiplex pin is used as RDPn.</li> <li>In Receive Dual Rail NRZ Format mode, the un-decoded NRZ data is output on RDPn and RDNn and updated on the active edge of RCLKn.</li> <li>In Receive Dual Rail RZ Format mode, the un-decoded RZ data is output on RDPn and RDNn and updated on the active edge of RCLKn.</li> <li>In Receive Dual Rail Sliced mode, the raw RZ sliced data is output on RDPn and RDNn and updated on the active edge of RCLKn.</li> <li>In Receive Dual Rail Sliced mode, the raw RZ sliced data is output on RDPn and RDNn.</li> <li>For Receive Differential line interface, an active level on RDPn indicates the receipt of a positive pulse on RTIPn and a negative pulse on RRINGn; while an active level on RDNn indicates the receipt of a negative pulse on RTIPn and a positive pulse on RRINGn.</li> <li>For Receive Single Ended line interface, an active level on RDPn indicates the receipt of a positive pulse on RTIPn; while an active level on RDPn indicates the receipt of a negative pulse on RTIPn.</li> <li>The active level on RDPn and RDNn is selected by the RD_INV bit (b3, RCF1,).</li> <li>When the receiver is powered down, RDPn and RDNn will be in High-Z state or low, as selected by the RHZ bit (b6, RCF0,).</li> </ul>		
RDNn / RMFn (n=0~21)	Output	AG9, AD1, AH1, AG3, AG6, AJ8, AJ20, AG21, AG24, AJ26, AH30, B28, D25, B23, B20, D19, B17, A15, C14, A12, C11, C8	RDNn: Negative Receive Data for Channel 0 ~ 21When the receive system interface is configured to Dual Rail NRZ Format mode, Dual Rail RZFormat mode or Dual Rail Sliced mode, this multiplex pin is used as RDNn.(Refer to the description of RDPn for details).RMFn: Receive Multiplex Function for Channel 0 ~ 21		
			When the receive system interface is configured to Single Rail NRZ Format mode, this multiplex pin is used as RMFn. RMFn is configured by the RMF_DEF[2:0] bits (b7~5, RCF1,) and can indicate PRBS/ARB, LAIS, LEXZ, LBPV, LEXZ+LBPV, LLOS, output recovered clock (RCLK) or XOR output of positive and negative sliced data. Refer to Section 3.4.7.1 RMFn Indication for details. The output on RMFn is updated on the active edge of RCLKn. The active level of RMFn is always high. When the receiver is powered down, RMFn will be in High-Z state or low, as selected by the RHZ bit (b6, RCF0,).		



Name	I/O	Pin No.	Description
RCLKn / RMFn (n=0~21)	Output	AK10, AD2, AH2, AK4, AK7, AH8, AH20, AK22, AK25, AH26, AG29, A28, C25, A23, A20, C19, A17, C16, B14, D13, B11, B8	<ul> <li>RCLKn: Receive Clock for Channel 0 ~ 21</li> <li>When the receive system interface is configured to Single Rail NRZ Format mode, Dual Rail NRZ Format mode or Dual Rail RZ Format mode, this multiplex pin is used as RCLKn.</li> <li>RCLKn outputs a 2.048 MHz clock which is recovered from the received signal.</li> <li>The data output on RDn and RMFn (in Receive Single Rail NRZ Format mode) or RDPn/RDNn (in Receive Dual Rail NRZ Format mode, Receive Dual Rail RZ Format mode and Receive Dual Rail Sliced) is updated on the active edge of RCLKn. The active edge is selected by the RCK_ES bit (b4, RCF1,).</li> <li>In LLOS condition, RCLKn output high or XCLK, as selected by the RCKH bit (b7, RCF0,) (refer to Section 3.4.3.1 Line LOS (LLOS) for details).</li> <li>When the receiver is powered down, RCLKn will be in High-Z state or low, as selected by the RHZ bit (b6, RCF0,).</li> <li>RMFn: Receive Multiplex Function for Channel 0 ~ 21</li> <li>When the receive system interface is configured to Dual Rail Sliced mode, this multiplex pin is used as RMFn.</li> </ul>
			(Refer to the description of RMFn of the RDNn/RMFn multiplex pin for details).
LLOS	Output	AF17	LLOS: Receive Line Loss Of Signal LLOS synchronizes with the output of CLKE1 and can indicate the LLOS (Line LOS) status of all 22 channels in a serial format. When the clock output on CLKE1 is enabled, LLOS indicates the LLOS status of the 22 chan- nels in a serial format and repeats every twenty-two cycles. Channel 0 is positioned by LLOS0. Refer to the description of LLOS0 below for details. The last 7 redundant clock cycles are low and should be ignored. LLOS is updated on the rising edge of CLKE1 and is always active high. When the clock output of CLKE1 is disabled, LLOS will be held in High-Z state. (Refer to Section 3.4.3.1 Line LOS (LLOS) for details.)
LLOS0	Output	AF18	<b>LLOS0:</b> Receive Line Loss Of Signal for Channel 0 LLOS0 can indicate the position of channel 0 on the LLOS pin. When the clock output on CLKE1 is enabled, LLOS0 pulses high for one CLKE1 clock cycle to indicate the position of channel 0 on the LLOS pin. When CLKE1 outputs 8 KHz clock, LLOS0 pulses high for one 8 KHz clock cycle (125 $\mu$ s) every twenty-nine 8 KHz clock cycles; when CLKE1 outputs 2.048 MHz clock, LLOS0 pulses high for one 2.048 MHz clock cycle (488 ns) every twenty-nine 2.048 MHz clock cycles. LLOS0 is updated on the rising edge of CLKE1. When the clock output on CLKE1 is disabled, LLOS0 will be held in High-Z state. (Refer to Section 3.4.3.1 Line LOS (LLOS) for details.)

Name	I/O	Pin No.	Description				
TDn / TDPn (n=0~21)	Input	AG8, AC1, AF1, AG2, AG5, AJ7, AJ19, AG20, AG23, AJ25, AJ28, D27, D24, B22, B19, D18, B16, A14, C13, A11, C10, C7	<ul> <li>TDn: Transmit Data for Channel 0 ~ 21</li> <li>When the transmit system interface is configured to Single Rail NRZ Format mode, this multiplex pin is used as TDn.</li> <li>TDn accepts Single Rail NRZ data. The data is sampled into the device on the active edge of TCLKn.</li> <li>The active level on TDn is selected by the TD_INV bit (b3, TCF1,).</li> <li>TDPn: Positive Transmit Data for Channel 0 ~ 21</li> <li>When the transmit system interface is configured to Dual Rail NRZ Format mode or Dual Rail RZ Format mode, this multiplex pin is used as TDPn.</li> <li>In Transmit Dual Rail NRZ Format mode, the pre-encoded NRZ data is input on TDPn and TDNn and sampled on the active edge of TCLKn.</li> <li>In Transmit Dual Rail RZ Format mode, the pre-encoded RZ data is input on TDPn and TDNn.</li> <li>The line code is as follows (when the TD_INV bit (b3, TCF1,) is '0'):</li> </ul>				
			TDPn TDNn Output Pulse on TTIPn Output Pulse on TRINGn *				
			0	0	Space	Space	
			0	1	Negative Pulse	Positive Pulse	
			1	0	Positive Pulse	Negative Pulse	
			1	1	Space	Space	
TDNn / TMFn (n=0~21)	Input / Output	AK9, AC2, AF2, AK3, AK6, AH7, AH19, AK21, AK24, AH25, AH28, C27, C24, A22, A19, C18, A16, D15, B13, D12, B10, B7	-				
TCLKn / TDNn	Input	AJ9, AC3, AF3, AJ3, AJ6, AG7,	SAIS, TOC, TLOS, SEXZ, SBPV, SEXZ+SBPV, SLOS. Refer to Section 3.4.7.2 TMFn Indica- tion for details. The output on TMFn is updated on the active edge of TCLKn (if available). The active level of TMFn is always high.				
(n=0~21)	nput	AG19, AJ21, AJ24, AG25, AG28, B27, B24, D23, D20, B18, D17, C15, A13, C12, A10, A7	<ul> <li>Rail NRZ Format mode, this multiplex pin is used as TCLKn.</li> <li>TCLKn inputs a 2.048 MHz clock.</li> <li>The data input on TDn (in Transmit Single Rail NRZ Format mode) or TDPn/TDNn (in Transmit Dual Rail NRZ Format mode) is sampled on the active edge of TCLKn. The data output on TMFn (in Transmit Single Rail NRZ Format mode) is updated on the active edge of TCLKn.</li> <li>The active edge is selected by the TCK_ES bit (b4, TCF1,).</li> <li>TDNn: Negative Transmit Data for Channel 0 ~ 21</li> </ul>				
			When the transmit system interface is configured to Dual Rail RZ Format mode, this multiple pin is used as TDNn. (Refer to the description of TDPn for details).				

Name	I/O	Pin No.		Description
	· I		Clock	
MCLK	Input	AK19	clock with ±50 ppm accuracy MCKSEL[3:0].	rence timing for the IDT82P2521. MCLK should be a jitter-free y. The clock frequency of MCLK is informed to the device be less than 30% for 10 $\mu$ s) and then recovers, the device will be
MCKSEL[0]	Input	AF19	MCKSEL[3:0]: Master Clock These four pins inform the dev	<b>Selection</b> vice of the clock frequency input on MCLK:
MCKSEL[1]		AF20	MCKSEL[3	[3:0] <sup>*</sup> Frequency (MHz)
MCKSEL[2]		AF21	1000	2.048
MCKSEL[3]		AF22	1001	2.048 X 2
			1010	2.048 X 3
			1011	2.048 X 4
			1100	2.048 X 5
			1101	2.048 X 6
			1110	2.048 X 7
			1111	2.048 X 8
			others	s don't care
			Note: 0: GNDD 1: VDDIO	
CLKE1	Output	AG18	CLKG). When the output is enabled, C CLKE1 bit (b2, CLKG). The ou	e enabled or disabled, as determined by the CLKE1_EN bit (b CLKE1 outputs an 8 KHz or 2.048 MHz clock, as selected by th utput is locked to MCLK.
REFA	Output	AK18	CLKE1 bit (b2, CLKG). The output is locked to MCLK. When the output is disabled, CLKE1 is in High-Z state. <b>REFA: Reference Clock Output A</b> REFA can output three kinds of clocks: a recovered clock of one of the 22 channels, an ex- nal clock input on CLKA or a free running clock. The clock frequency is programmable. R to Section 3.5.2 Clock Outputs on REFA/REFB for details. The output on REFA can also be disabled, as determined by the REFA_EN bit (b6, REFA When the output is disabled, REFA is in High-Z state.	

Note:

**1.** jitter is no more than 0.001 UI.

Name	1/0	Pin No.	Description	
REFB	Output	AJ18	REFB: Reference Clock Output B         REFB can output a recovered clock of one of the 22 channels, an external clock input on CLKB or a free running clock. Refer to Section 3.5.2 Clock Outputs on REFA/REFB for details.         The output on REFB can also be disabled, as determined by the REFB_EN bit (b6, REFB).         When the output is disabled, REFB is in High-Z state.	
CLKA	Input	AH17	CLKA: External E1 Clock Input A External E1 clock is input on this pin. The CKA_E1 bit (b5, REFA) should be set to matc clock frequency. When not used, this pin should be connected to GNDD.	
CLKB	Input	AG17	CLKB: External E1 Clock Input B External E1 clock is input on this pin. The CKB_E1 bit (b5, REFB) should be set to match the clock frequency. When not used, this pin should be connected to GNDD.	
	I I		Common Control	
VCOM[0] VCOM[1]	Output	R4 P28	VCOM: Voltage Common Mode [1:0] These pins are used only when the receive line interface is in Receive Differential mode and connected without a transformer (transformer-less). To enable these pins, the VCOMEN pin must be connected high. Refer to Figure-10 for the connection. When these pins are not used, they should be left open.	
VCOMEN	Input (Pull-Down)	AF26	VCOMEN: Voltage Common Mode Enable This pin should be connected high only when the receive line interface is in Receive Differential mode and connected without a transformer (transformer-less). When not used, this pin should be left open.	
REF	-	D29	<b>REF: Reference Resistor</b> An external resistor (10 K $\Omega$ , ±1%) is used to connect this pin to ground to provide a standar reference current for internal circuit. This resistor is required to ensure correct device oper tion.	
RIM	Input (Pull-Down)	AH10	<ul> <li>tion.</li> <li>RIM: Receive Impedance Matching         In Receive Differential mode, when RIM is low, all 22 receivers become High-Z and only on al impedance matching is supported. In this case, the per-channel impedance matching figuration bits - the R_TERM[2:0] bits (b2~0, RCF0,) and the R120IN bit (b4, RCF0,) ignored.     In Receive Differential mode, when RIM is high, impedance matching is configured on a channel basis by the R_TERM[2:0] bits (b2~0, RCF0,) and the R120IN bit (b4, RCF0,) This pin can be used to control the receive impedance state for Hitless Protection ap tions. Refer to Section 4.4 Hitless Protection Switching (HPS) Summary for details. In Receive Single Ended mode, this pin should be left open.     </li> </ul>	
OE	Input	AJ10	OE: Output Enable OE enables or disables all Line Drivers globally. A high level on this pin enables all Line Drivers while a low level on this pin places all Line Drivers in High-Z state and independent from related register settings. Note that the functionality of the internal circuit is not affected by OE. If this pin is not used, it should be tied to VDDIO. This pin can be used to control the transmit impedance state for Hitless protection applica- tions. Refer to Section 4.4 Hitless Protection Switching (HPS) Summary for details.	

Name	I/O	Pin No.	Description	
GPIO[0] GPIO[1]	Output / Input	AF9 AF10	GPIO: General Purpose I/O [1:0] These two pins can be defined as input pins or output pins by the DIR[1:0] bits (b1~0, GPIO) respectively. When the pins are input, their polarities are indicated by the LEVEL[1:0] bits (b3~2, GPIO) respectively. When the pins are output, their polarities are controlled by the LEVEL[1:0] bits (b3~2, GPIO) respectively.	
RST	Input	AG10	<b>RST: Reset (Active Low)</b> A low pulse on this pin resets the device. This hardware reset process completes in 2 µs maximum. Refer to Section 4.1 Reset for an overview on reset options.	
	· · ·		MCU Interface	
ĪNT	Output	AK16	INT: Interrupt Request           This pin indicates interrupt requests for all unmasked interrupt sources.           The output characteristics (open drain or push-pull internally) and the active level are mined by the INT_PIN[1:0] bits (b3~2, GCF).	
CS	Input	AJ17	CS: Chip Select (Active Low)         This pin must be asserted low to enable the microprocessor interface.         A transition from high to low must occur on this pin for each Read/Write operation and CS should remain low until the operation is over.	
P/S	Input	AG16	P/S: Parallel or Serial Microprocessor Interface Select         P/S selects Serial or Parallel microprocessor interface for the device:         GNDD - Serial microprocessor interface.         VDDIO - Parallel microprocessor interface.         Serial microprocessor interface consists of the CS, SCLK, SDI, SDO pins.         Parallel microprocessor interface consists of the CS, INT/MOT, IM, DS/RD, ALE/AS, R/W/WR, ACK/RDY, D[7:0], A[10:0] pins.	
INT/MOT	Input (Pull-Up)	AF14	INT/MOT: Intel or Motorola Microprocessor Interface Select         In Parallel microprocessor interface, INT/MOT selects Intel or Motorola microprocessor face for the device:         GNDD - Parallel Motorola microprocessor interface.         Open - Parallel Intel microprocessor interface.         In Serial microprocessor interface, this pin should be left open.	
IM	Input (Pull-Up)	AF15	IM: Interface Mode Selection In Parallel Motorola or Intel microprocessor interface, IM selects multiplexed bus or non-multi- plexed bus for the device: GNDD - Parallel Motorola /Intel Non-Multiplexed microprocessor interface. Open - Parallel Motorola /Intel Multiplexed microprocessor interface. In Serial microprocessor interface, this pin should be connected to GNDD.	
ALE / AS	Input	AG15	<ul> <li>ALE: Address Latch Enable In Parallel Intel Multiplexed microprocessor interface, this multiplex pin is used as ALE. The address on A[10:8] and D[7:0] (A[7:0] are ignored) is sampled into the device on the fall- ing edges of ALE.</li> <li>AS: Address Strobe In Parallel Motorola Multiplexed microprocessor interface, this multiplex pin is used as AS.</li> </ul>	
			The address on A[10:8] and D[7:0] (A[7:0] are ignored) is latched into the device on the falling edges of AS. In Parallel Motorola /Intel Non-Multiplexed microprocessor interface, this pin should be pulled high. In Serial microprocessor interface, this pin should be connected to GNDD.	



Name	I/O	Pin No.	Description
SCLK / DS / RD	Input	AK17	SCLK: Shift ClockIn Serial microprocessor interface, this multiplex pin is used as SCLK.SCLK inputs the shift clock for the Serial microprocessor interface. Data on SDI is sampled by the device on the rising edge of SCLK. Data on SDO is updated on the falling edge of SCLK. $\overline{DS}$ : Data Strobe (Active Low)In Parallel Motorola microprocessor interface, this multiplex pin is used as $\overline{DS}$ .During a write operation ( $R/\overline{W} = 0$ ), data on D[7:0] is sampled into the device. During a read operation ( $R/\overline{W} = 1$ ), data is driven to D[7:0] by the device. $\overline{RD}$ : Read Strobe (Active Low)In Parallel Intel microprocessor interface, this multiplex pin is used as $\overline{RD}$ . $\overline{RD}$ is asserted low by the microprocessor to initiate a read operation. Data is driven to D[7:0]
			by the device during the read operation.
SDI / R/W / WR	Input	AH16	<b>SDI: Serial Data Input</b> In Serial microprocessor interface, this multiplex pin is used as SDI. Address and data on this pin are serially clocked into the device on the rising edge of SCLK.
			<b>R/<math>\overline{W}</math>: Read / Write Select</b> In Parallel Motorola microprocessor interface, this multiplex pin is used as R/ $\overline{W}$ . R/ $\overline{W}$ is asserted low for write operation or high for read operation.
			WR: Write Strobe (Active Low) In Parallel Intel microprocessor interface, this multiplex pin is used as WR. WR is asserted low by the microprocessor to initiate a write operation. Data on D[7:0] is sam- pled into the device during a write operation.
SDO / ACK / RDY	Output	AJ16	<b>SDO: Serial Data Output</b> In Serial microprocessor interface, this multiplex pin is used as SDO. Data on this pin is serially clocked out of the device on the falling edge of SCLK.
			<b>ACK</b> : Acknowledge Output (Active Low) In Parallel Motorola microprocessor interface, this multiplex pin is used as ACK. A low level on ACK indicates that valid information on the data bus is ready for a read opera- tion or acknowledges the acceptance of the written data during a write operation.
			<b>RDY: Ready Output</b> In Parallel Intel microprocessor interface, this multiplex pin is used as RDY. A high level on RDY reports to the microprocessor that a read/write cycle can be completed. A low level on RDY reports that wait states must be inserted.
D[0] D[1] D[2] D[3] D[4] D[5] D[6] D[7]	Output / Input	AG12 AH12 AJ12 AK12 AG11 AH11 AJ11 AK11	D[7:0]: Bi-directional Data Bus In Parallel Motorola /Intel Non-Multiplexed microprocessor interface, these pins are the bi- directional data bus of the microprocessor interface. In Parallel Motorola /Intel Multiplexed microprocessor interface, these pins are the multiplexed bi-directional address /data bus. In Serial microprocessor interface, these pins should be connected to GNDD.



Name	I/O	Pin No.	Description	
A[0] A[1] A[2] A[3] A[4] A[5] A[6] A[7] A[8] A[9] A[10]	Input	AH15 AJ15 AK15 AG14 AH14 AJ14 AK14 AG13 AH13 AJ13 AK13	A[10:0]: Address Bus In Parallel Motorola /Intel Non-Multiplexed microprocessor interface, these pins are the address bus of the microprocessor interface. In Parallel Motorola /Intel Multiplexed microprocessor interface, A[10:8], together with D[7:0], are the address bus; while A[7:0] should be connected to GNDD. In Serial microprocessor interface, these pins should be connected to GNDD.	
		L	JTAG (per IEEE 1149.1)	
TRST	Input Pull-Down	AF4	<b>TRST: JTAG Test Reset (Active Low)</b> A low signal on this pin resets the JTAG test port. To ensure deterministic operation of the test logic, TMS should be held high when the signal on TRST changes from low to high. This pin may be left unconnected when JTAG is not used. This pin has an internal pull-down resistor.	
TMS	Input Pull-up	AE5	TMS: JTAG Test Mode Select The signal on this pin controls the JTAG test performance and is sampled on the rising edge of TCK. To ensure deterministic operation of the test logic, TMS should be held high when the signal on TRST changes from low to high. This pin may be left unconnected when JTAG is not used. This pin has an internal pull-up resistor.	
TCK	Input	AF6	<ul> <li>TCK: JTAG Test Clock</li> <li>The clock for the JTAG test is input on this pin. TDI and TMS are sampled on the rising e of TCK and TDO is updated on the falling edge of TCK.</li> <li>When TCK is idle at low state, all stored-state devices contained in the test logic shall retheir state indefinitely.</li> <li>This pin should be connected to GNDD when JTAG is not used.</li> </ul>	
TDI	Input Pull-up	AF5	<b>TDI: JTAG Test Data Input</b> The test data is input on this pin. It is clocked into the device on the rising edge of TCK. This pin has an internal pull-up resistor. This pin may be left unconnected when JTAG is not used.	
TDO	Output	AF7	<b>TDO: JTAG Test Data Output</b> The test data is output on this pin. It is clocked out of the device on the falling edge of TCK. TDO is a High-Z output signal except during the process of data scanning.	
			Power & Ground	
VDDIO		E7, E8, E10, E11, E12, E21, E22, E23, E24, E25, AE9, AE10, AE15, AE16, AE17, AE18, AE22, AE23, AE24	VDDIO: 3.3 V I/O Power Supply	
VDDA		A2, B2, J26, K27, L4, L27, M4, M26, T4, W4, Y5, Y27, Y28, AA27, AA28, AD5, AJ2, AK2		
VDDD		E14, E15, E16, E17, E18, E19, AE11, AE14, AE19, AE20, AE21	VDDD: 1.8 V Digital Core Power Supply	
VDDRn (N=0~21)		N4, N5, T5, U5, AB4, AC5, AF28, AF27, AD27, U27, T27, R27, N26, G27, E26, E27, E5, E4, F3, F5, G3, H3	VDDRn: 3.3 V Power Supply for Receiver	



Name	I/O	Pin No.	Description
VDDTn (N=0~21)		K2, L2, P2, R3, W2, Y2, AF29, AC29, AA29, Y29, R29, P29, K29, J29, F29, E29, C6, C4, C3, C2, F2, H2	VDDTn: 3.3 V Power Supply for Transmitter Driver
GNDA		A1, A29, A30, B1, B29, B30, F6, F7, F8, F25, G6, G25, H6, H25, J6, J25, K6, K25, L6, L25, M6, M25, N6, N25, P6, P25, R6, R25, T6, T25, U6, U25, V6, V25, W6, W25, W26, Y6, Y25, AA6, AA25, AB1, AB6, AB25, AB26, AC6, AC25, AC26, AD6, AD25, AE6, AE25, AJ1, AJ29, AJ30, AK1, AK29, AK30	GNDA: GND for Analog Core / Receiver
GNDD		<ul> <li>F10, F11, F12, F13, F14, F15, F16,</li> <li>F17, F18, F19, F20, F21, F22, F23,</li> <li>F24, M12, M13, M14, M15, M16,</li> <li>M17, M18, M19, N12, N13, N14,</li> <li>N15, N16, N17, N18, N19, P12,</li> <li>P13, P14, P15, P16, P17, P18, P19,</li> <li>R12, R13, R14, R15, R16, R17,</li> <li>R18, R19, T12, T13, T14, T15, T16,</li> <li>T17, T18, T19, U12, U13, U14,</li> <li>U15, U16, U17, U18, U19, V12,</li> <li>V13, V14, V15, V16, V17, V18, V19,</li> <li>W12, W13, W14, W15, W16, W17,</li> <li>W18, W19, AE7, AE8, AE12, AE13,</li> <li>AF23, AF24</li> </ul>	GNDD: Digital GND
GNDT		B5, B6, C5, D2, D28, E2, H28, H29, J3, J5, J28, K3, K5, L3, M3, M28, N28, N29, T2, U2, U28, V28, V29, W29, AA3, AB2, AB28, AD29, AE29	GNDT: Analog GND for Transmitter Driver
			TEST
IC	-	AF13, AF12	IC: Internal Connected This pin is for IDT use only and should be connected to GNDD.
IC	-	AH18, AF11	IC: Internal Connected This pin is for IDT use only and should be left open.



Name	Ι/Ο	Pin No.	Description
			Others
NC	-	A8, A9, A21, A25, A26, B9, B21, B25, B26, C9, C21, C22, C26, C28, C29, D7, D9, D10, D16, D21, D22, D26, E9, E13, E20, F9, F27, G1, G2, G28, G29, G30, H1, H4, H26, H27, J4, J27, K4, L29, M27, M29, M30, N1, N2, N27, P1, P4, P27, T3, T26, T29, U3, U26, U29, U30, V1, V2, V3, V26, V27, W3, Y3, AB3, AB27, AB29, AB30, AC27, AC28, AD3, AD4, AE1, AE2, AE3, AE4, AE27, AF8, AF16, AF25, AG4, AG22, AG26, AG27, AG30, AH4, AH5, AH22, AH23, AH27, AJ4, AJ5, AJ22, AJ23, AJ27, AK5, AK23, AK27, AK28	NC: Not Connected

#### **3 FUNCTIONAL DESCRIPTION**

#### 3.1 RECEIVE PATH

#### 3.1.1 R<sub>X</sub> TERMINATION

The receive line interface supports Receive Differential mode and Receive Single Ended mode, as selected by the R\_SING bit (b3, RCF0,...). In Receive Differential mode, both RTIPn and RRINGn are used to receive signal from the line side. In Receive Single Ended mode, only RTIPn is used to receive signal.

In Receive Differential mode, the line interface can be connected with E1 120  $\Omega$  twisted pair cable or E1 75  $\Omega$  coaxial cable. In Receiver Single Ended mode, the line interface can only be connected with 75  $\Omega$  coaxial cable.

The receive impedance matching is realized by using internal impedance matching or external impedance matching for each channel in different applications.

#### 3.1.1.1 Receive Differential Mode

In Receive Differential mode, three kinds of impedance matching are supported: Fully Internal Impedance Matching, Partially Internal Impedance Matching and External Impedance Matching. Figure-7 shows an overview of how these Impedance Matching modes are switched.

Fully Internal Impedance Matching circuit uses an internal programmable resistor (IM) only and does not use an external resistor. This configuration saves external components and supports 1:1 Hitless Protection Switching (HPS) applications without relays. Refer to Section 4.4 Hitless Protection Switching (HPS) Summary.

Partially Internal Impedance Matching circuit consists of an internal programmable resistor (IM) and a value-fixed 120  $\Omega$  external resistor (Rr). Compared with Fully Internal Impedance Matching, this configuration provides considerable savings in power dissipation of the device. For example, In E1 120  $\Omega$  PRBS mode, the power savings would be 0.57 W. For power savings in other modes, please refer to Chapter 8 Physical And Electrical Specifications.

External Impedance Matching circuit uses an external resistor (Rr) only.



Figure-7 Switch between Impedance Matching Modes

To support some particular applications, such as hot-swap or Hitless Protection Switch (HPS) hot-switchover, RTIPn/RRINGn must be forced to enter high impedance state (i.e., External Impedance Matching). For hot-swap, RTIPn/RRINGn must be always held in high impedance state during /after power up; for HPS hot-switchover, RTIPn/RRINGn must enter high impedance state immediately after switchover. Though each channel can be individually configured to External Impedance Matching through register access, it is too slow for hitless switch. Therefore, a hardware pin - RIM - is provided to globally control the high impedance for all 22 receivers.

When RIM is low, only External Impedance Matching is supported for all 22 receivers and the per-channel impedance matching configuration bits - the R\_TERM[2:0] bits (b2~0, RCF0,...) and the R120IN bit (b4, RCF0,...) - are ignored.

When RIM is high, impedance matching is configured on a perchannel basis. Three kinds of impedance matching are all supported and selected by the R\_TERM[2:0] bits (b2~0, RCF0,...) and the R120IN bit (b4, RCF0,...). The R\_TERM[2] bit (b2, RCF0,...) should be set to match internal or external impedance. If the R\_TERM[2] bit (b2, RCF0,...) is '0', internal impedance matching is enabled. The R120IN bit (b4, RCF0,...) should be set to select Partially Internal Impedance Matching or Fully Internal Impedance Matching. The internal programmable resistor (IM) is determined by the R\_TERM[1:0] bits (b1~0, RCF0,...). If the R\_TERM[2] bit (b2, RCF0,...) is '1', external impedance matching is enabled. The configuration of the R120IN bit (b4, RCF0,...) and the R\_TERM[1:0] bits (b1~0, RCF0,...) is ignored.

A twisted pair cable can be connected with a 1:1 transformer or without a transformer (transformer-less), while a coaxial cable must be connected with a 1:1 transformer. Table 1 lists the recommended impedance matching value in different applications. Figure-8 to Figure-10 show the connection for one channel.

The transformer-less connection will offer a termination option with reduced cost and board space. However, the waveform amplitude is not standard compliant, and surge protection and common mode depression should be enhanced depending on equipment environment.

#### Table-1 Impedance Matching Value in Receive Differential Mode

Cable Condition	Partially Internal Im (R1201	•	Fully Internal Impedance Matching (R120IN = 1) <sup>1, 2</sup>		External Impedance Matching	
	R_TERM[2:0]	Rr	R_TERM[2:0]	Rr	R_TERM[2:0] <sup>3</sup>	Rr
E1 120 $\Omega$ twisted pair (with transformer)	010		010	(0000)		120 Ω
E1 75 $\Omega$ coaxial (with transformer)	011	120 Ω	011	(open)	1XX	75 Ω
E1 120 $\Omega$ twisted pair (transformer-less <sup>4</sup> )	010		(not supported)			120 Ω
Note:						

1. Partially Internal Impedance Matching and Fully Internal Impedance Matching are not supported when RIM is low.

2. Fully Internal Impedance Matching is not supported in transformer-less applications.

3. When RIM is low, the setting of the R\_TERM[2:0] bits is ignored.

4. In transformer-less applications, the device should be protected against overvoltage. There are three important standards for overvoltage protection:

• UL1950 and FCC Part 68;

Telcordia (Bellcore) GR-1089

• ITU-T K.20, K.21 and K.41



Figure-8 Receive Differential Line Interface with Twisted Pair Cable (with transformer)



Figure-9 Receive Differential Line Interface with Coaxial Cable (with transformer)



Note: 1. Two Rr/2 resistors should be connected to VCOM[1:0] that are coupled to ground via a 10 μF capacitor, which provide 60 Ω common mode input resistance.
2. In this mode, lightning protection should be enhanced.
3. The maximum input dynamic range of RTIP/TRING pin is -0.3 V ~3.6 V (in line monitor mode it is -0.3 V ~ 2 V)

Figure-10 Receive Differential Line Interface with Twisted Pair Cable (transformer-less, non standard compliant)

#### 21(+1) CHANNEL HIGH-DENSITY E1 LINE INTERFACE UNIT

#### 3.1.1.2 Receive Single Ended Mode

Receive Single Ended mode can only be used in 75  $\Omega$  coaxial cable applications.

In Receive Single Ended mode, only External Impedance Matching is supported. External Impedance Matching circuit uses an external resistor (Rr) only. The value of the resistor is 18.75  $\Omega$  (see Figure-11 for details) when the single end is connected with a 2:1 transformer or is 75  $\Omega$  (see Figure-12 for details) when the single end is connected without a transformer.

In Receive Single Ended mode, the RIM pin should be left open and the configuration of the R\_TERM[2:0] bits (b2~0, RCF0,...) is ignored.



Figure-11 Receive Single Ended Line Interface with Coaxial Cable (with transformer)



Note: In this mode, port protection should be enhanced.

Figure-12 Receive Single Ended Line Interface with Coaxial Cable (transformer-less, non standard compliant)

#### 3.1.2 EQUALIZER

The equalizer compensates high frequency attenuation to enhance receive sensitivity.

#### 3.1.2.1 Line Monitor

In E1 short haul applications, the Protected Non-Intrusive Monitoring per T1.102 can be performed between two devices. The monitored channel of one device is in normal operation, and the monitoring channel of the other device taps the monitored one through a high impedance bridging circuit (refer to Figure-13 and Figure-14).

After the high resistance bridging circuit, the signal arriving at RTIPn/ RRINGn of the monitoring channel is dramatically attenuated. To compensate this bridge resistive attenuation, Monitor Gain can be used to boost the signal by 20 dB, 26 dB or 32 dB, as selected by the MG[1:0] bits (b1~0, RCF2,...). For normal operation, the Monitor Gain should be set to 0 dB, i.e., the Monitor Gain of the monitored channel should be 0 dB.

The monitoring channel can be configured to any of the External, Partially Internal or Fully Internal Impedance Matching mode. Here the external r or internal IM is used for voltage division, not for impedance matching. That is, the r (IM) and the two R make up of a resistance bridge. The resistive attenuation of this bridge is 20lg(r/(2R+r)) dB.

Note that line monitor is only available in differential line interface.

A channel 0 monitoring function is provided (refer to Section 3.4.9 Channel 0 Monitoring). If multiple High-Density LIUs are used in an application, The G.772 function of channel 0 can be used to route the signals of channel 1~21 Receive and Transmit to channel 0 of the same device. This channel 0 Transmit TTIP and TTRING could then be monitored by another device through the Line Monitor function.

#### 3.1.2.2 Receive Sensitivity

The receive sensitivity is the minimum range of receive signal level for which the receiver recovers data error-free with -18 dB interference signal added.

For Receive Differential line interface, the receive sensitivity is -15 dB.

For Receive Single Ended line interface, the receive sensitivity is -12 dB.



#### Figure-13 Receive Path Monitoring



Figure-14 Transmit Path Monitoring

#### 3.1.3 SLICER

The Slicer is used to generate a standard amplitude mark or a space according to the amplitude of the input signals. The input signal is sliced at 50% of the peak value.

#### 3.1.4 R<sub>X</sub> CLOCK & DATA RECOVERY

The Rx Clock & Data Recovery is used to recover the clock signal from the received data. It is accomplished by an integrated Digital Phase Locked Loop (DPLL). The recovered clock tracks the jitter in the data output from the Slicer and keeps the phase relationship between data and clock during the absence of the incoming pulse.

Note that the IDT82P2521 also provides programmable REFA and REFB pins to output any of the 22 recovered line clocks. Refer to Section 3.5 Clock Inputs and Outputs for details.

#### 3.1.5 DECODER

The Decoder is used only when the receive system interface is in Single Rail NRZ Format mode. When the receive system interface is in other modes, the Decoder is bypassed automatically. (Refer to Section 3.1.6 Receive System Interface for the description of the receive system interface).

The received signal is decoded by AMI or HDB3 line code rule. The line code rule is selected by the R\_CODE bit (b2, RCF1,...).

#### 3.1.6 RECEIVE SYSTEM INTERFACE

The received data can be output to the system side in four modes: Single Rail NRZ Format mode, Dual Rail NRZ Format mode, Dual Rail RZ Format mode and Dual Rail Sliced mode, as selected by the  $R_MD[1:0]$  bits (b1~0, RCF1).

If data is output on RDn in NRZ format and the recovered clock is output on RCLKn, the receive system interface is in Single Rail NRZ Format mode. In this mode, the data is decoded and updated on the active edge of RCLKn. RCLKn outputs a 2.048 MHz clock. The Receive Multiplex Function (RMFn) signal is updated on the active edge of RCLKn and can be selected to indicate PRBS/ARB, LAIS, LEXZ, LBPV, LEXZ + LBPV, LLOS, output recovered clock (RCLK) or XOR output of positive and negative sliced data. Refer to Section 3.4.7.1 RMFn Indication for the description of RMFn.

If data is output on RDPn and RDNn in NRZ format and the recovered clock is output on RCLKn, the receive system interface is in Dual Rail NRZ Format mode. In this mode, the data is un-decoded and updated on the active edge of RCLKn. RCLKn outputs a 2.048 MHz clock.

If data is output on RDPn and RDNn in RZ format and the recovered clock is output on RCLKn, the receive system interface is in Dual Rail RZ Format mode. In this mode, the data is un-decoded and updated on the active edge of RCLKn. RCLKn outputs a 2.048 MHz clock.

If data is output on RDPn and RDNn in RZ format directly after passing through the Slicer, the receive system interface is in Dual Rail Sliced mode. In this mode, the data is raw sliced and un-decoded. RMFn can be selected to indicate PRBS/ARB, LAIS, LEXZ, LBPV, LEXZ + LBPV, LLOS, output recovered clock (RCLK) or XOR output of positive and negative sliced data. Refer to Chapter 3.4.7.1 RMFn Indication for the description of RMFn.

Table-2 summarizes the multiplex pin used in different receive system interface.

Table-2 Multiplex Pin Used in Receive System Interface

Receive System	Multiplex Pin Used On Receive System Interface				
Interface	RDn / RDPn	RDNn / RMFn	RCLKn / RMFn		
Single Rail NRZ Format	RDn <sup>1</sup>	RMFn <sup>2</sup>	RCLKn <sup>3</sup>		
Dual Rail NRZ Format	RDPn <sup>1</sup>	RDNn <sup>1</sup>	RCLKn <sup>3</sup>		
Dual Rail RZ Format	RDPn <sup>1</sup>	RDNn <sup>1</sup>	RCLKn <sup>3</sup>		
Dual Rail Sliced	RDPn <sup>1</sup>	RDNn <sup>1</sup>	RMFn <sup>2</sup>		
Note:					

1. The active level on RDn, RDPn and RDNn is selected by the RD\_INV bit (b3, RCF1,...).

2. RMFn is always active high.

3. The active edge of RCLKn is selected by the RCK\_ES bit (b4, RCF1,...).

#### 3.1.7 RECEIVER POWER DOWN

Set the R\_OFF bit (b5, RCF0,...) to '1' will power down the corresponding receiver.

In this way, the corresponding receive circuit is turned off and the RTIPn/RRINGn pins are forced to High-Z state. The pins on receive system interface (including RDn/RDPn, RDNn/RMFn, RCLKn/RMFn) will be in High-Z state if the RHZ bit (b6, RCF0,...) is '1' or in low level if the RHZ bit (b6, RCF0,...) is '0'.

After clearing the R\_OFF bit (b5, RCF0,...), it will take 1 ms for the receiver to achieve steady state, i.e., to return to the previous configuration and performance.

#### 3.2 TRANSMIT PATH

#### 3.2.1 TRANSMIT SYSTEM INTERFACE

The data from the system side is input to the device in three modes: Single Rail NRZ Format mode, Dual Rail NRZ Format mode and Dual Rail RZ Format mode, as selected by the T\_MD[1:0] bits (b1~0, TCF1,...).

If data is input on TDn in NRZ format and a 2.048 MHz clock is input on TCLKn, the transmit system interface is in Single Rail NRZ Format mode. In this mode, the data is encoded and sampled on the active edge of TCLKn. TMFn is updated on the active edge of TCLKn and can be selected to indicate PRBS/ARB, SAIS, TOC, TLOS or SEXZ. Refer to Section 3.4.7.2 TMFn Indication for the description of TMFn.

If data is input on TDPn and TDNn in NRZ format and a 2.048 MHz clock is input on TCLKn, the transmit system interface is in Dual Rail NRZ Format mode. In this mode, the data is pre-encoded and sampled on the active edge of TCLKn.

If data is input on TDPn and TDNn in RZ format and no transmit clock is input, the transmit system interface is in Dual Rail RZ Format mode. In this mode, the data is pre-encoded. TMFn can be selected to indicate PRBS/ARB, SAIS, TOC, TLOS, SEXZ, SBPV, SEXZ + SBPV or SLOS. Refer to Section 3.4.7.2 TMFn Indication for the description of TMFn. The Tx Clock Recovery block is used to recover the clock signal from the data input on TDPn and TDNn. Refer to Section 3.2.2 Tx Clock Recovery.

Table-3 summarizes the multiplex pin used in different transmit system interface.

#### Table-3 Multiplex Pin Used in Transmit System Interface

Transmit System Interface	Multiplex Pin Used On Transmit System Interface			
interface	TDn / TDPn	TDNn / TMFn	TCLKn / TDNn	
Single Rail NRZ Format	TDn <sup>1</sup>	TMFn <sup>2</sup>	TCLKn <sup>3</sup>	
Dual Rail NRZ Format	TDPn <sup>1</sup>	TDNn <sup>1</sup>	TCLKn <sup>3</sup>	
Dual Rail RZ Format	TDPn <sup>1</sup>	TMFn <sup>2</sup>	TDNn <sup>1</sup>	

#### Note:

1. The active level on TDn, TDPn and TDNn is selected by the TD\_INV bit (b3, TCF1,...).

2. TMFn is always active high.

**3.** The active edge of TCLKn is selected by the TCK\_ES bit (b4, TCF1,...). If TCLKn is missing, i.e., no transition for more than 64 E1 clock cycles, the TCKLOS\_S bit (b3, STAT0,...) will be set. A transition from '0' to '1' on the TCKLOS\_S bit (b3, STAT0,...) or any transition (from '0' to '1' or from '1' to '0') on the TCKLOS\_S bit (b3, STAT0,...) will set the TCKLOS\_IS bit (b3, INTS0,...) to '1', as selected by the TCKLOS\_IES bit (b3, INTES,...). When the TCKLOS\_IS bit (b3, INTS0,...) is '1', an interrupt will be reported by INT if not masked by the TCKLOS\_IM bit (b3, INTM0,...).

#### 3.2.2 T<sub>X</sub> CLOCK RECOVERY

The Tx Clock Recovery is used only when the transmit system interface is in Dual Rail RZ Format mode. When the transmit system interface is in other modes, the Tx Clock Recovery is bypassed automatically.

The Tx Clock Recovery is used to recover the clock signal from the data input on TDPn and TDNn.

#### 3.2.3 ENCODER

The Encoder is used only when the transmit system interface is in Single Rail NRZ Format mode. When the transmit system interface is in other modes, the Encoder is bypassed automatically.

The data to be transmitted is encoded by AMI or HDB3 line code rule. The line code rule is selected by the T\_CODE bit (b2, TCF1,...).

#### 3.2.4 WAVEFORM SHAPER

The IDT82P2521 provides two ways to manipulate the pulse shape before data is transmitted:

- · Preset Waveform Template;
- User-Programmable Arbitrary Waveform.

#### 3.2.4.1 Preset Waveform Template

The waveform template meets G.703, as shown in Figure-15. It is measured in the near end line side, as shown in Figure-16.

The PULS[3:0] should be set to '0000' if differential signals (output from TTIP and TRING) are coupled to a 75  $\Omega$  coaxial cable using Internal Impedance matching mode; the PULS[3:0] should be set to '0001' for other E1 interfaces. Refer to Table-4 for details.



Figure-15 E1 Waveform Template



Figure-16 E1 Waveform Template Measurement Circuit

#### Table-4 PULS[3:0] Setting

Interface Conditions	PULS[3:0]
E1 75 $\Omega$ differential interface, Internal Impedance matching mode	0000
Other E1 interface	0001

After one of the preset waveform templates is selected, the preset waveform amplitude can be adjusted to get the desired waveform.

The SCAL[5:0] bits (b5~0, SCAL,...) should be set to '100001' to get the standard amplitude. The adjusting is made by increasing or decreasing by '1' from the standard value to scale up or down at a percentage ratio of 3%.

In summary, do the following step by step, the desired waveform will be got based on the preset waveform template:

- Select one preset waveform template by setting the PULS[3:0] bits (b3~0, PULS,...);
- Write '100001 to the SCAL[5:0] bits (b5~0, SCAL,...).
- Write the scaling value to the SCAL[5:0] bits (b5~0, SCAL,...) to scale the amplitude of the selected preset waveform template (this step is optional).

#### 3.2.4.2 User-Programmable Arbitrary Waveform

When the PULS[3:0] bits (b3~0, PULS,...) are set to '1XXX', userprogrammable arbitrary waveform will be used in the corresponding channel.

Each waveform shape can extend up to  $1\frac{1}{4}$  UIs (Unit Interval), and is

divided into 20 sub-phases that are addressed by the SAMP[4:0] bits (b4~0, AWG0,...). The waveform amplitude of each phase is represented by a binary byte, within the range from +63 to -63, stored in the WDAT[6:0] bits (b6~0, AWG1,...) in signed magnitude form. The maximum number +63 (D) represents the maximum positive amplitude of the transmit pulse while the most negative number -63 (D) represents the maximum negative amplitude of the transmit pulse. Therefore, up to 20 bytes are used.

There are eight standard templates which are stored in a local ROM. One of them can be selected as reference and made some changes to get the desired waveform.

To do this, the first step is to choose a set of waveform value from the standard templates. The selected waveform value should be the most similar to the desired waveform shape. Table-5 and Table-6 list the sample data of each template.

Then modify the sample data to get the desired transmit waveform shape. By increasing or decreasing by '1' from the standard value in the SCAL[5:0] bits (b5~0, SCAL,...), the waveform amplitude will be scaled up or down.

In summary, do the following for the write operation:

- Modify the sample data in the AWG1 register;
- Write the AWG0 register to implement the write operation, including:
  - Write the sample address to the SAMP[4:0] bits (b4~0, AWG0,...);
  - Write '0' to the RW bit (b5, AWG0,...);
  - Write '1' to the DONE bit (b6, AWG0,...).

Do the following for the read operation:

- · Write the AWG0 register, including:
  - Write sample address to the SAMP[4:0] bits (b4~0, AWG0,...);
  - Write '1' to the RW bit (b5, AWG0,...);
  - Write '1' to the DONE bit (b6, AWG0,...);
- · Read the AWG1 register to get the sample data.

When the write operation is completed, write the scaling value to the SCAL[5:0] bits (b5~0, SCAL,...) to scale the amplitude of the selected standard waveform (- this step is optional).

When more than one UI is used to compose the waveform template and the waveform amplitude is not set properly, the overlap of the two consecutive waveforms will make the waveform amplitude overflow (i.e., exceed the maximum limitation). This overflow is captured by the DAC\_IS bit (b7, INTS0,...) and will be reported by the INT pin if enabled by the DAC\_IM bit (b7, INTM0,...).
Refer to application note AN-513 'User-Programmable Arbitrary Waveform for DSX1' for more details.

#### Table-5 Transmit Waveform Value for E1 75 ohm

SAMP[4:0]	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
WDAT[6:0]	00H	00H	00H	0CH	30H	00H														

### Table-6 Transmit Waveform Value for E1 120 ohm

SAMP[4:0]	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
WDAT[6:0]	00H	00H	00H	0FH	3CH	00H														

#### 3.2.5 LINE DRIVER

The Line Driver can be set to High-Z for protection or in redundant applications.

The following two ways will set the Line Driver to High-Z:

- Setting the OE pin to low will globally set all the Line Drivers to High-Z;
- Setting the OE bit (b6, TCF0,...) to '0' will set the corresponding Line Driver to High-Z.

By these ways, the functionality of the internal circuit is not affected and TTIPn and TRINGn will enter High-Z state immediately.

#### 3.2.5.1 Transmit Over Current Protection

The Line Driver monitors the Transmit Over Current (TOC) on the line interface. When TOC is detected, the driver's output (i.e., output on TTIPn/TRINGn) is determined by the THZ\_OC bit (b4, TCF0,...). If the THZ\_OC bit (b4, TCF0,...) is '0', the driver's output current (peak to peak) is limited to 100 mA; if the THZ\_OC bit (b4, TCF0,...) is '1', the driver's output will enter High-Z. TOC is indicated by the TOC\_S bit (b4, STAT0,...) or any transition (from '0' to '1' on the TOC\_S bit (b4, STAT0,...) will set the TOC\_IS bit (b4, INTS0,...) to '1', as selected by the TOC\_IES bit (b4, INTES,...). When the TOC\_IS bit (b4, INTS0,...) is '1', an interrupt will be reported by INT if not masked by the TOC\_IM bit (b4, INTM0,...).

TOC may be indicated by the TMFn pin. Refer to Section 3.4.7.2 TMFn Indication for details.

#### 3.2.6 T<sub>X</sub> TERMINATION

The transmit line interface supports Transmit Differential mode and Transmit Single Ended mode, as selected by the T\_SING bit (b3, TCF0,...). In Transmit Differential mode, both TTIPn and TRINGn are used to transmit signals to the line side. In Transmit Single Ended mode, only TTIPn is used to transmit signal.

The line interface can be connected with E1 120  $\Omega$  twisted pair cable or E1 75  $\Omega$  coaxial cable.

The transmit impedance matching is realized by using internal impedance matching or external impedance matching for each channel in different applications.

#### 3.2.6.1 Transmit Differential Mode

In Transmit Differential mode, different applications have different impedance matching. For E1 applications, both Internal and External Impedance Matching are supported.

Internal Impedance Matching circuit uses an internal programmable resistor (IM) only.

External Impedance Matching circuit uses an external resistor (Rt) only.

A twisted pair cable can be connected with a 1:2 (step up) transformer or without a transformer (transformer-less), while a coaxial cable must be connected with a 1:2 transformer.

The T\_TERM[2:0] bits (b2~0, TCF0,...) should be set according to different cable conditions, whether a transformer is used, and what kind of Impedance Matching is selected.

Table-7 lists the recommended impedance matching value in different applications. Figure-17 to Figure-19 show the connection for one channel in different applications.

The transformer-less connection will offer a termination option with reduced cost and board space. However, the waveform amplitude is not standard compliant, and surge protection and common mode depression should be enhanced depending on equipment environment.

Table-7 Impedance Matching Value in Transmit Differential Mode

Cable Condition	Internal Imped	ance Matching	External Impedance Matching		
	T_TERM[2:0]	Rt	T_TERM[2:0]	Rt	
E1 120 $\Omega$ twisted pair (with transformer), PULS[3:0]=0001	010		111	10 Ω	
E1 75 $\Omega$ coaxial (with transformer), PULS[3:0]=0000	011	0	111	10 22	
E1 120 $\Omega$ twisted pair (transformer-less), PULS[3:0]=0001	110		(not supported)		



Figure-17 Transmit Differential Line Interface with Twisted Pair Cable (with Transformer)



Figure-18 Transmit Differential Line Interface with Coaxial Cable (with transformer)



Note: In this mode, port protection should be enhanced.

Figure-19 Transmit Differential Line Interface with Twisted Pair Cable (transformer-less, non standard compliant)

### 3.2.6.2 Transmit Single Ended Mode

Transmit Single Ended mode can only be used in 75  $\Omega$  coaxial cable applications.

In Transmit Single Ended mode, only Internal Impedance Matching is supported. Internal Impedance Matching circuit uses an internal programmable resistor (IM) only. The T\_TERM[2:0] bits (b2~0, TCF0,...) should be set to '011'. The output amplitude is 4.74 Vpp when PULS[3:0]

is '0001' and the SCAL[5:0] bits (b5~0, SCAL,...) is '100001'.<sup>1</sup>

In Single Ended mode, special care has to be taken for termination and overall setup. Refer to separate application note for details.

A 1:2 (step up) transformer should be used in application.

Figure-20 shows the connection for one channel.



Figure-20 Transmit Single Ended Line Interface with Coaxial Cable (with transformer)

1. The waveform in this mode is not standard. However, if the arbitrary waveform generator is used, the waveform could pass the template marginally.

#### 3.2.7 TRANSMITTER POWER DOWN

Set the T\_OFF bit (b5, TCF0,...) to '1' will power down the corresponding transmitter.

In this way, the corresponding transmit circuit is turned off. The pins on the transmit line interface (including TTIPn and TRINGn) will be in High-Z state. The input on the transmit system interface (including TDn, TDPn, TDNn and TCLK) is ignored. The output on the transmit system interface (i.e. TMFn) will be in High-Z state.

After clearing the T\_OFF bit (b5, TCF0,...), it will take 1 ms for the transmitter to achieve steady state, i.e., return to the previous configuration and performance.

#### 3.2.8 OUTPUT HIGH-Z ON TTIP AND TRING

TTIPn and TRINGn can be set to High-Z state globally or on a perchannel basis.

The following three conditions will set TTIPn and TRINGn to High-Z state globally:

- · Connecting the OE pin to low;
- · Loss of MCLK (i.e., no transition on MCLK for more than 1 ms);
- Power on reset, hardware reset by pulling RST to low for more than 2 µs or global software reset by writing the RST register.

The following six conditions will set TTIPn and TRINGn to High-Z state on a per-channel basis:

- Writing '0' to the OE bit (b6, TCF0,...);
- Loss of TCLKn in Transmit Single Rail NRZ Format mode or Transmit Dual Rail NRZ Format mode (i.e., no transition on TCLKn for more than 64 XCLK<sup>1</sup> cycles) except that the channel is in Remote Loopback or transmit internal pattern with XCLK;
- Transmitter power down;
- Per-channel software reset by writing '1' to the CHRST bit (b1, CHCF,...);
- Setting the THZ\_OC bit (b4, TCF0,...) to '1' when transmit driver over-current is detected.

1. XCLK is derived from MCLK. It is 2.048 MHz .

# 3.3 JITTER ATTENUATOR (RJA & TJA)

Two Jitter Attenuators are provided for each channel of receiver and transmitter. Each Jitter Attenuator can be enabled or disabled, as determined by the RJA\_EN/TJA\_EN bit (b3, RJA/TJA,...) respectively.

Each Jitter Attenuator consists of a FIFO and a DPLL, as shown in Figure-21.



Figure-21 Jitter Attenuator

The FIFO is used as a pool to buffer the jittered input data, then the data is clocked out of the FIFO by a de-jittered clock. The depth of the FIFO can be 32 bits, 64 bits or 128 bits, as selected by the RJA\_DP[1:0]/ TJA\_DP[1:0] bits (b2~1, RJA/TJA,...). Accordingly, the typical delay produced by the Jitter Attenuator is 16 bits, 32 bits or 64 bits. The 128bit FIFO is used when large jitter tolerance is expected, while the 32-bit FIFO is used in delay sensitive applications. The DPLL is used to generate a de-jittered clock to clock out the data stored in the FIFO. The DPLL can only attenuate the incoming jitter whose frequency is above Corner Frequency (CF) by 20 dB per decade falling off. The jitter whose frequency is lower than the CF passes through the DPLL without any attenuation. The CF of the DPLL is 6.77 Hz or 0.87 Hz. The CF is selected by the RJA\_BW/TJA\_BW bit (b0, RJA/TJA,...). The lower the CF is, the longer time is needed to achieve synchronization.

If the incoming data moves faster than the outgoing data, the FIFO will overflow. If the incoming data moves slower than the outgoing data, the FIFO will underflow. The overflow and underflow are both captured by the RJA\_IS/TJA\_IS bit (b5/6, INTS0,...). The occurrence of overflow or underflow will be reported by the INT pin if enabled by the RJA\_IM/TJA\_IM bit (b5/6, INTM0,...).

To avoid overflow or underflow, the JA-Limit function can be enabled by setting the RJA\_LIMT/TJA\_LIMT bit (b4, RJA/TJA,...). When the JA-Limit function is enabled, the speed of the outgoing data will be adjusted automatically if the FIFO is 2-bit close to its full or emptiness. Though the JA-Limit function can reduce the possibility of FIFO overflow and underflow, the quality of jitter attenuation is deteriorated.

The performance of the Jitter Attenuator meets ITUT I.431, G.703, G.736-739, G.823, G.824, ETSI 300011, ETSI TBR12/13, AT&T TR62411, TR43802, TR-TSY 009, TR-TSY 253 and TR-TRY 499. Refer to Section 8.10 Jitter Attenuation Characteristics for the jitter performance.

# 3.4 DIAGNOSTIC FACILITIES

The diagnostic facilities include:

- BPV (Bipolar Violation) / CV (Code Violation) detection and BPV insertion;
- · EXZ (Excessive Zero) detection;
- · LOS (Loss Of Signal) detection;
- · AIS (Alarm Indication Signal) detection and generation;
- Pattern generation and detection, including PRBS (Pseudo Random Bit Sequence), ARB (Arbitrary Pattern) and IB (Inband Loopback).

The above defects, alarms or patterns can be counted by an internal Error Counter, indicated by the respective interrupt bit and indicated by RMFn or TMFn.

For diagnostic purposes, loopbacks and channel 0 monitoring can also be implemented.

# 3.4.1 BIPOLAR VIOLATION (BPV) / CODE VIOLATION (CV) DETECTION AND BPV INSERTION

#### 3.4.1.1 Bipolar Violation (BPV) / Code Violation (CV) Detection

BPV/CV is monitored in both the receive path and the transmit path. BPV is detected when the data is AMI coded and CV is detected when the data is HDB3 coded. If the transmit system interface is in Transmit Single Rail NRZ Format mode, the BPV/CV detection is disabled in the transmit path automatically.

A BPV is detected when two consecutive pulses of the same polarity are received.

A CV is detected when two consecutive BPVs of the same polarity that are not a part of the HDB3 zero substitution are received.

When BPV/CV is detected in the receive path, the Line Bipolar Violation LBPV\_IS bit (b4, INTS2,...) will be set and an interrupt will be reported by INT if not masked by the LBPV\_IM bit (b4, INTM2,...).

When BPV/CV is detected in the transmit path, the System Bipolar Violation SBPV\_IS bit (b5, INTS2,...) will be set and an interrupt will be reported by INT if not masked by the SBPV\_IM bit (b5, INTM2,...).

BPV/CV may be counted by an internal Error Counter or may be indicated by the RMFn or TMFn pin. Refer to Section 3.4.6 Error Counter and Section 3.4.7 Receive /Transmit Multiplex Function (RMF / TMF) Indication respectively.

#### 3.4.1.2 Bipolar Violation (BPV) Insertion

The BPV can only be inserted in the transmit path.

A BPV will be inserted on the next available mark in the data stream to be transmitted by writing a '1' to the BPV\_INS bit (b6, ERR,...). This bit will be reset once BPV insertion is done.

#### 3.4.2 EXCESSIVE ZEROES (EXZ) DETECTION

EXZ is monitored in both the receive path and the transmit path.

Different line code has different definition of the EXZ. The IDT82P2521 provides two standards of EXZ definition for each kind of line code rule. The standards are ANSI and FCC, as selected by the EXZ\_DEF bit (b7, ERR,...). Refer to Table-8 for details.

#### Table-8 EXZ Definition

Line Code	Definition							
Rule	ANSI (EXZ_DEF = 0)	FCC (EXZ_DEF = 1)						
AMI	An EXZ is detected when any string of more than 15 consecutive '0's are received.	An EXZ is detected when any string of more than 15 consecutive '0's are received.						
HDB3	An EXZ is detected when any string of more than 3 consecutive '0's are received.	any string of more than 3						
Note: If the transmit system interface is in Transmit Single Rail NRZ Format mode, the EXZ is detected according to the standard of AMI.								

When EXZ is detected in the receive path, the LEXZ\_IS bit (b2, INTS2,...) will be set and an interrupt will be reported by  $\overline{INT}$  if not masked by the LEXZ\_IM bit (b2, INTM2,...).

When EXZ is detected in the transmit path, the SEXZ\_IS bit (b3, INTS2,...) will be set and an interrupt will be reported by  $\overline{INT}$  if not masked by the SEXZ\_IM bit (b3, INTM2,...).

EXZ may be counted by an internal Error Counter or may be indicated by the RMFn or TMFn pin. Refer to Chapter 3.4.6 Error Counter and Chapter 3.4.7 Receive /Transmit Multiplex Function (RMF / TMF) Indication respectively.

#### 3.4.3 LOSS OF SIGNAL (LOS) DETECTION

The IDT82P2521 detects three kinds of LOS:

- · LLOS: Line LOS, detected in the receive path;
- SLOS: System LOS, detected in the transmit system side;
- TLOS: Transmit LOS, detected in the transmit line side.

#### 3.4.3.1 Line LOS (LLOS)

The amplitude and density of the data received from the line side are monitored. When the amplitude of the data is less than Q Vpp for N consecutive pulse intervals, LLOS is declared. When the amplitude of the data is more than P Vpp and the average density of marks is at least 12.5% for M consecutive pulse intervals starting with a mark, LLOS is cleared. Here Q is defined by the ALOS[2:0] bits (b6~4, LOS,...). P is the sum of Q and 250 mVpp. N and M are defined by the LAC bit (b7, LOS,...). Refer to Table-9 for details.

LLOS detection supports G.775 and ETSI 300233/I.431. The criteria are selected by the LAC bit (b7, LOS,...).

When LLOS is detected, the LLOS\_S bit (b0, STAT0,...) will be set. A transition from '0' to '1' on the LLOS\_S bit (b0, STAT0,...) or any transition (from '0' to '1' or from '1' to '0') on the LLOS\_S bit (b0, STAT0,...) will set the LLOS\_IS bit (b0, INTS0,...) to '1', as selected by the LOS\_IES bit (b1, INTES,...). When the LLOS\_IS bit (b0, INTS0,...) is '1', an interrupt will be reported by INT if not masked by the LLOS\_IM bit (b0, INTM0,...).

Two pins (LLOS0 and LLOS) are dedicated to LLOS indication. Whether LLOS is detected in channel 0 or not, LLOS0 is high for a CLKE1 clock cycle to indicate the channel 0 position on LLOS. LLOS indicates LLOS status of all 22 channels in a serial format and repeats every 22 cycles. Refer to Figure-22. LLOS0 and LLOS are updated on the rising edge of CLKE1. When the clock output on CLKE1 is disabled, LLOS0 and LLOS will be held in High-Z state. The output on CLKE1 is controlled by the CLKE1\_EN bit (b3, CLKG) and the CLKE1 bit (b2, CLKG). Refer to section 8.9 on page 129 for CLKE1 timing characteristics.

LLOS may be counted by an internal Error Counter or may be indicated by the RMFn pin. Refer to Section 3.4.6 Error Counter and Section 3.4.7.1 RMFn Indication respectively.

During LLOS, in Receive Single Rail NRZ Format mode, Receive Dual Rail NRZ Format mode and Receive Dual Rail RZ Format mode, RDn and RDPn/RDNn output low level. In Receive Dual Rail Sliced mode RDPn/RDNn still output sliced data. RCLKn (if available) outputs high level or XCLK<sup>1</sup>, as selected by the RCKH bit (b7, RCF0,...).

During LLOS, if any of AIS, pattern generation in the receive path or Digital Loopback is enabled, RDn, RDPn/RDNn and RCLKn output corresponding data and clock, and the setting of the RCKH bit (b7, RCF0,...) is ignored. Refer to the corresponding chapters for details.

1. XCLK is derived from MCLK. It is 2.048 MHz .

#### Table-9 LLOS Criteria

Operation Mode	LAC	Criteria	LLOS Declaring	LLOS Clearing
	0	G.775	below Q Vpp, N = 32 bits	above P Vpp, 12.5% mark density with less than 16 consecutive zeros, M = 32 bits
E1	1	ETSI 300233/ I.431	below Q Vpp, N = 2048 bits	above P Vpp, 12.5% mark density with less than 16 consecutive zeros, M = 32 bits



Figure-22 LLOS Indication on Pins

#### 3.4.3.2 System LOS (SLOS)

SLOS can only be detected when the transmit system interface is in Dual Rail NRZ Format mode or in Dual Rail RZ Format mode.

The amplitude and density of the data input from the transmit system side are monitored. When the input '0's are equal to or more than N consecutive pulse intervals, SLOS is declared. When the average density of marks is at least 12.5% for M consecutive pulse intervals starting with a mark, SLOS is cleared. Here N and M are defined by the LAC bit (b7, LOS,...). Refer to Table-10 for details.

SLOS detection supports G.775 and ETSI 300233/I.431. The criteria are selected by the LAC bit (b7, LOS,...).

When SLOS is detected, the SLOS\_S bit (b1, STAT0,...) will be set. A transition from '0' to '1' on the SLOS\_S bit (b1, STAT0,...) or any transition (from '0' to '1' or from '1' to '0') on the SLOS\_S bit (b1, STAT0,...) will set the SLOS\_IS bit (b1, INTS0,...) to '1', as selected by the LOS\_IES bit (b1, INTES,...). When the SLOS\_IS bit (b1, INTS0,...) is '1', an interrupt will be reported by INT if not masked by the SLOS\_IM bit (b1, INTM0,...).

SLOS may be counted by an internal Error Counter or may be indicated by the TMFn pin. Refer to Section 3.4.6 Error Counter and Section 3.4.7.2 TMFn Indication respectively.

#### Table-10 SLOS Criteria

Operation Mode	LAC	Criteria	SLOS Declaring <sup>1</sup>	SLOS Clearing <sup>1</sup>
E1	0	G.775	no pulse detected for N consecutive pulse intervals, N = 32 bits	12.5% mark density with less than 16 consecutive zeros for M consecutive pulse intervals, M = 32 bits
	1	ETSI 300233/ I.431	no pulse detected for N consecutive pulse intervals, N = 2048 bits	12.5% mark density with less than 16 consecutive zeros for M consecutive pulse intervals, M = 32 bits

Note:

1. System input ports are schmitt-trigger inputs)

#### 3.4.3.3 Transmit LOS (TLOS)

The amplitude and density of the data output on the transmit line side are monitored. When the amplitude of the data is less than a certain voltage for a certain period, TLOS is declared. The voltage is defined by the TALOS[1:0] bits (b3~2, LOS,...). The period is defined by the TDLOS[1:0] bits (b1~0, LOS,...). When a valid pulse is detected, i.e., the amplitude is above the setting in the TALOS[1:0] bits (b3~2, LOS,...), TLOS is cleared.

When TLOS is detected, the TLOS\_S bit (b2, STAT0,...) will be set. A transition from '0' to '1' on the TLOS\_S bit (b2, STAT0,...) or any transition (from '0' to '1' or from '1' to '0') on the TLOS\_S bit (b2, STAT0,...) will set the TLOS\_IS bit (b2, INTS0,...) to '1', as selected by the TLOS\_IES bit (b2, INTES,...). When the TLOS\_IS bit (b2, INTS0,...) is '1', an interrupt will be reported by INT if not masked by the TLOS\_IM bit (b2, INTM0,...).

TLOS may be counted by an internal Error Counter or may be indicated by the TMFn pin. Refer to Section 3.4.6 Error Counter and Section 3.4.7.2 TMFn Indication respectively.

TLOS can be used to monitor the LOS in the transmit line side between two channels. The connection between the two channels is shown in Figure-23. The two channels can be of the same device or different devices on the premises that the transmit line interfaces are in the same mode and at least the output of one channel is in High-Z state. Table-11 lists each results in this case. In the left two columns, the OE bit (b6, TCF0,...) of the two channels controls the output status in the transmit line side to ensure that at least one channel is in High-Z state. The middle two columns list the internal operation status. In the right two columns, the TLOS\_S bit (b2, STAT0,...) of the two channels indicates the TLOS status in the transmit line side.



Figure-23 TLOS Detection Between Two Channels

Output Status ~ Con	trolled By the OE Bit	Internal Ope	ration Status	TLOS Status ~ Indicated By the TLOS_S Bit			
Channel #1	Channel #2	Channel #1	Channel #2	Channel #1	Channel #2		
Normal ~ 1	High-Z ~ 0	Normal	(don't-care)	No TLOS ~ 0	No TLOS ~ 0		
Normal ~ 1	High-Z ~ 0	Failure	Normal	TLOS Detected ~ 1 *	TLOS Detected ~ 1		
High-Z ~ 0	Normal ~ 1	(don't-care)	Normal	No TLOS ~ 0	No TLOS ~ 0		
High-Z ~ 0	Normal ~ 1	Normal	Failure	TLOS Detected ~ 1	TLOS Detected ~ 1 *		
High-Z ~ 0	High-Z ~ 0	(don't-care)	(don't-care)	TLOS Detected ~ 1	TLOS Detected ~ 1		

#### Table-11 TLOS Detection Between Two Channels

#### 3.4.4 ALARM INDICATION SIGNAL (AIS) DETECTION AND GEN-ERATION

#### 3.4.4.1 Alarm Indication Signal (AIS) Detection

AIS is monitored in both the receive path and the transmit path.

When the mark density in the received data or in the data input from the transmit system side meets certain criteria, AIS is declared or cleared. In E1 mode, the criteria are in compliance with ITU G.775 or ETSI 300233, as selected by the LAC bit (b7, LOS,...). Refer to Table-12 for details.

#### Table-12 AIS Criteria

	ITU G.775 for E1 (LAC = 0)	ETSI 300233 for E1 (LAC = 1)
AIS Declaring	Less than 3 zeros are received in each of two consecutive 512-bit data streams.	Less than 3 zeros are received in a 512-bit data stream.
AIS Clearing	3 or more zeros are received in each of two consecutive 512-bit data streams.	3 or more zeros are received in a 512-bit data stream.

When AIS is detected in the receive path, the LAIS\_S bit (b6, STAT1,...) will be set. A transition from '0' to '1' on the LAIS\_S bit (b6, STAT1,...) or any transition (from '0' to '1' or from '1' to '0') on the LAIS\_S bit (b6, STAT1,...) will set the LAIS\_IS bit (b6, INTS1,...) to '1', as selected by the AIS\_IES bit (b6, INTES,...). When the LAIS\_IS bit (b6, INTS1,...) is '1', an interrupt will be reported by INT if not masked by the LAIS\_IM bit (b6, INTM1,...).

When AIS is detected in the transmit path, the SAIS\_S bit (b7, STAT1,...) will be set. A transition from '0' to '1' on the SAIS\_S bit (b7, STAT1,...) or any transition (from '0' to '1' or from '1' to '0') on the SAIS\_S bit (b7, STAT1,...) will set the SAIS\_IS bit (b7, INTS1,...) to '1', as selected by the AIS\_IES bit (b6, INTES,...). When the SAIS\_IS bit (b7, INTS1,...) is '1', an interrupt will be reported by INT if not masked by the SAIS\_IM bit (b7, INTM1,...).

AIS may be counted by an internal Error Counter or may be indicated by the RMFn or TMFn pin. Refer to Section 3.4.6 Error Counter and Section 3.4.7 Receive /Transmit Multiplex Function (RMF / TMF) Indication respectively.

#### 3.4.4.2 (Alarm Indication Signal) AIS Generation

AIS can be generated automatically in the receive path and the transmit path.

In the receive path, when the ASAIS\_LLOS bit (b2, AISG,...) is set, AIS will be generated automatically once LLOS is detected. When the ASAIS\_SLOS bit (b3, AISG,...) is set, AIS will be generated automatically once SLOS is detected. When AIS is generated, RDn or RDPn/ RDNn output all '1's. RCLKn (if available) outputs XCLK.

In the transmit path, when the ALAIS\_LLOS bit (b0, AISG,...) is set, AIS will be generated automatically once LLOS is detected. When the ALAIS\_SLOS bit (b1, AISG,...) is set, AIS will be generated automatically once SLOS is detected. When AIS is generated, TTIPn/TRINGn output all '1's.

AIS generation uses XCLK<sup>1</sup> as reference clock.

If pattern (including PRBS, ARB and IB) is generated in the same direction, the priority of pattern generation is higher. The generated pattern will overwrite automatic AIS. Refer to Section 3.4.5.1 Pattern Generation for the output data and clock.

<sup>1.</sup> XCLK is derived from MCLK. It is 2.048 MHz .

# 3.4.5 PRBS, QRSS, ARB AND IB PATTERN GENERATION AND DETECTION

The pattern includes: Pseudo Random Bit Sequence (PRBS), Quasi-Random Signal Source (QRSS), Arbitrary Pattern (ARB) and Inband Loopback (IB).

#### 3.4.5.1 Pattern Generation

The pattern can be generated in the receive path or the transmit path, as selected by the PG\_POS bit (b3, PG,...).

The pattern to be generated is selected by the PG\_EN[1:0] bits (b5~4, PG,...).

If PRBS is selected, three kinds of PRBS patterns with maximum zero restriction according to ITU-T 0.151 and AT&T TR62411 are provided. They are:  $(2^{2}0 - 1)$  QRSS per 0.150-4.5,  $(2^{15} - 1)$  PRBS per 0.152 and  $(2^{11} - 1)$  PRBS per 0.150, as selected by the PRBG\_SEL[1:0] bits (b1~0, PG,...).

If ARB is selected, the content is programmed in the ARB[23:0] bits (b7~0, ARBH~ARBM~ARBL,...).

If IB is selected, the IB generation is in compliance with ANSI T1.403. The length of the IB code can be 3 to 8 bits, as determined by the IBGL[1:0] bits (b5~4, IBL,...). The content is programmed in the IBG[7:0] bits (b7~0, IBG,...).

The selected pattern is transmitted repeatedly until the PG\_EN[1:0] bits (b5~4, PG,...) is set to '00'.

When pattern is generated in the receive path, the reference clock is XCLK or the recovered clock from the received signal, as selected by the PG\_CK bit (b6, PG,...). The selected reference clock is also output on RCLKn (if available).

When pattern is generated in the transmit path, the reference clock is XCLK<sup>1</sup> or the transmit clock, as selected by the PG\_CK bit (b6, PG,...). The transmit clock refers to the clock input on TCLKn (in Transmit Single Rail NRZ Format mode and in Transmit Dual Rail NRZ Format mode) or the clock recovered from the data input on TDPn and TDNn (in Transmit Dual Rail RZ Format mode).

In summary, do the followings step by step to generate pattern:

- Select the generation direction by the PG\_POS bit (b3, PG,...);
- Select the reference clock by the PG\_CK bit (b6, PG,...);
- Select the PRBS pattern by the PRBG\_SEL[1:0] bits (b1~0, PG,...) when PRBS is to be generated; program the ARB pattern in the ARB[23:0] bits (b7~0, ARBH~ARBM~ARBL,...) when ARB is to be generated; or set the length and the content of the IB code in the IBGL[1:0] bits (b5~4, IBL,...) and in the IBG[7:0] bits (b7~0, IBG,...) respectively when IB is to be generated;
- Set the PG\_EN[1:0] bits (b5~4, PG,...) to generate the pattern.

If PRBS or ARB is selected to be generated, the following two steps can be optionally implemented after the pattern is generated:

- Insert a single bit error by writing '1' to the ERR\_INS bit (b5, ERR,...);
- Invert the generated pattern by setting the PAG\_INV bit (b2, PG,...).

If pattern is generated in the receive path, the generated pattern should be encoded by using AMI HDB3 in Receive Dual Rail NRZ Format mode, Receive Dual Rail RZ Format mode and Receive Dual Rail Sliced mode. The encoding rule is selected by the R\_CODE bit (b2, RCF1,...).

If pattern is generated in the transmit path, the generated pattern should be encoded by using AMI HDB3. The encoding rule is selected by the T\_CODE bit (b2, TCF1,...).

The pattern generation is shown in Figure-24 and Figure-25.



Figure-24 Pattern Generation (1)



Figure-25 Pattern Generation (2)

The priority of pattern generation is higher than that of AIS generation. If they are generated in the same direction, the generated pattern will overwrite the generated AIS.

<sup>1.</sup> XCLK is derived from MCLK. It is 2.048 MHz .

#### 3.4.5.2 Pattern Detection

Data received from the line side or data input from the transmit system side may be extracted for pattern detection. The direction of data extraction is determined by the PD\_POS bit (b3, PD,...). One of PRBS or ARB pattern is selected for detection and IB detection is always active.

If data is extracted from the receive path, before pattern detection the data should be decoded by using AMI / HDB3. The decoding rule is selected by the R\_CODE bit (b2, RCF1,...).

If data is extracted from the transmit path, before pattern detection the data should be decoded by using AMI HDB3 in Transmit Dual Rail NRZ Format mode and Transmit Dual Rail RZ Format mode. The decoding rule is selected by the T\_CODE bit (b2, TCF1,...).

### <u>Pseudo Random Bit Sequence (PRBS) /Arbitrary Pattern (ARB)</u> <u>Detection</u>

The extracted data can be optionally inverted by the PAD\_INV bit (b2, PD,...) before PRBS/ARB detection.

The extracted data is used to compare with the desired pattern. The desired pattern is re-generated from the extracted data if the desired pattern is (2^20 - 1) QRSS per O.150-4.5, (2^15 - 1) PRBS per O.152 or (2^11 - 1) PRBS per O.150; or the desired pattern is programmed in the ARB[23:0] bits (b7~0, ARBH~ARBM~ARBL,...) if the desired pattern is ARB. The desired pattern is selected by the PAD\_SEL[1:0] bits (b1~0, PD,...).

In summary, do the followings step by step to detect PRBS/ARB:

- Select the detection direction by the PD\_POS bit (b3, PD,...);
- Set the ARB[23:0] bits (b7~0, ARBH~ARBM~ARBL,...) if the ARB pattern is desired - this step is omitted if the PRBS pattern is desired;
- Select the desired PRBS/ARB pattern by the PAD\_SEL[1:0] bits (b1~0, PD,...).

The priority of decoding, data inversion, pattern re-generation, bit programming and pattern comparison is shown in Figure-26.



Figure-26 PRBS / ARB Detection

During comparison, if the extracted data coincides with the re-generated PRBS pattern or the programmed ARB pattern for more than 64-bit hopping window, the pattern is synchronized and the PA\_S bit (b5, STAT1,...) will be set.

In synchronization state, if more than 6 PRBS/ARB errors are detected in a 64-bit hopping window, the pattern is out of synchronization and the PA\_S bit (b5, STAT1,...) will be cleared.

In synchronization state, each mismatched bit will generate a PRBS/ ARB error. When a PRBS/ARB error is detected during the synchronization, the ERR\_IS bit (b1, INTS2,...) will be set and an interrupt will be reported by INT if not masked by the ERR\_IM bit (b1, INTM2,...). The PRBS/ARB error may be counted by an internal Error Counter. Refer to Section 3.4.6 Error Counter.

A transition from '0' to '1' on the PA\_S bit (b5, STAT1,...) or any transition (from '0' to '1' or from '1' to '0') on the PA\_S bit (b5, STAT1,...) will set the PA\_IS bit (b5, INTS1,...) to '1', as selected by the PA\_IES bit (b5, INTES,...). When the PA\_IS bit (b5, INTS1,...) is '1', an interrupt will be reported by INT if not masked by the PA\_IM bit (b5, INTM1,...).

The PRBS/ARB synchronization status may be indicated by the RMFn or TMFn pin. Refer to Section 3.4.7 Receive /Transmit Multiplex Function (RMF / TMF) Indication.

#### Inband Loopback (IB) Detection

The IB detection is in compliance with ANSI T1.403.

The extracted data is used to compare with the target IB code. The length of the target activate/deactivate IB code can be 3 to 8 bits, as determined by the IBAL[1:0]/IBDL[1:0] bits (b3~2/b1~0, IBL,...). The content of the target activate/deactivate IB code is programmed in the IBA[7:0]/IBD[7:0] bits (b7~0, IBDA/IBDD,...). Refer to Figure-27.



Figure-27 IB Detection

During comparison, if the extracted data coincides with the target activate/deactivate IB code with no more than  $10^{-2}$  bit error rate for a certain period, the IB code is detected. The period depends on the setting of the AUTOLP bit (b3, LOOP,...).

If the AUTOLP bit (b3, LOOP,...) is '0', Automatic Digital/Remote Loopback is disabled. In this case, when the activate IB code is detected for more than 40 ms, the IBA\_S bit (b1, STAT1,...) will be set to indicate the activate IB code detection; when the deactivate IB code is detected for more than 30 ms, the IBD\_S bit (b0, STAT1,...) will be set to indicate the deactivate IB code detection.

If the AUTOLP bit (b3, LOOP,...) is '1', Automatic Digital/Remote Loopback is enabled. In this case, when the activate IB code is detected for more than 5.1 seconds, the IBA\_S bit (b1, STAT1,...) will be set to indicate the activate IB code detection. The detection of the activate IB code in the receive path will activate Remote Loopback or the detection of the activate IB code in the transmit path will activate Digital Loopback (refer to Section 3.4.8.2 Remote Loopback & Section 3.4.8.3 Digital Loopback). When the deactivate IB code is detected for more than 5.1 seconds, the IBD\_S bit (b0, STAT1,...) will be set to indicate the deactivate IB code detection. The detection of the detection of the deactivate IB code in the receive path will deactivate Remote Loopback or the detection of the deactivate IB code in the transmit path will be set to indicate the deactivate IB code in the transmit path will deactivate IB code in the receive path will deactivate Remote Loopback or the detection of the deactivate IB code in the transmit path will deactivate IB code in the receive path will deactivate Remote Loopback or the detection of the deactivate IB code in the transmit path will deactivate Digital Loopback (refer to Section 3.4.8.2 Remote Loopback & Section 3.4.8.3 Digital Loopback).

A transition from '0' to '1' on the IBA\_S/IBD\_S bit (b1/b0, STAT1,...) or any transition (from '0' to '1' or from '1' to '0') on the IBA\_S/IBD\_S bit (b1/b0, STAT1,...) will set the IBA\_IS/IBD\_IS bit (b1/b0, INTS1,...) to '1'

respectively, as selected by the IB\_IES bit (b0, INTES,...). When the IBA\_IS/IBD\_IS bit (b1/b0, INTS1,...) is '1', an interrupt will be reported on INT if not masked by the IBA\_IM/IBD\_IM bit (b1/b0, INTM1,...).

#### 3.4.6 ERROR COUNTER

An internal 16-bit Error Counter is used to count one of the following errors:

- LBPV: BPV/CV detected in the receive path (line side);
- LEXZ: EXZ detected in the receive path (line side);
- LBPV + LEXZ: BPV/CV and EXZ detected in the receive path (line side);
- SBPV: BPV/CV detected in the transmit path (system side) (disabled in Transmit Single Rail NRZ Format mode);
- SEXZ: EXZ detected in the transmit path (system side);
- SBPV + SEXZ: BPV/CV and EXZ detected in the transmit path (system side) (disabled in Transmit Single Rail NRZ Format mode);
- PRBS/ARB error.

The CNT\_SEL[2:0] bits (b4~2, ERR,...) select one of the above errors to be counted.

The Error Counter is buffered. It is updated automatically or manually, as determined by the CNT\_MD bit (b1, ERR,...).

The Error Counter is accessed by reading the ERRCH and ERRCL registers.

#### 3.4.6.1 Automatic Error Counter Updating

When the CNT\_MD bit (b1, ERR,...) is '1', the Error Counter is updated every one second automatically.

The one-second timer uses MCLK as clock reference. The expiration of each one second will set the TMOV\_IS bit (b0, INTTM) and induce an interrupt reported by INT if not masked by the TMOV\_IM bit (b0, GCF).

When each one second expires, the Error Counter transfers the accumulated error numbers to the ERRCH and ERRCL registers and the Error Counter will be cleared to start a new round counting. The ERRCH and ERRCL registers should be read in the next second, otherwise they will be overwritten.

When the ERRCH and ERRCL registers are all '1's and there is still error to be accumulated, the registers will be overflowed. The overflow is indicated by the CNTOV\_IS bit (b0, INTS2,...) and will induce an interrupt reported by INT if not masked by the CNTOV\_IM (b0, INTM2,...).

The process of automatic Error Counter updating is illustrated in Figure-28.



Figure-28 Automatic Error Counter Updating

#### 3.4.6.2 Manual Error Counter Updating

When the CNT\_MD bit (b1, ERR,...) is '0', the Error Counter is updated manually.

When there is a transition from '0' to '1' on the CNT\_STOP bit (b0, ERR,...), the Error Counter transfers the accumulated error numbers to the ERRCH and ERRCL registers and the Error Counter will be cleared to start a new round counting. The ERRCH and ERRCL registers should be read in the next round of error counting, otherwise they will be overwritten.

When the ERRCH and ERRCL registers are all '1's and there is still error to be accumulated, the registers will be overflowed. The overflow is indicated by the CNTOV\_IS bit (b0, INTS2,...) and will induce an interrupt reported by INT if not masked by the CNTOV\_IM (b0, INTM2,...).

The process of manual Error Counter updating is illustrated in Figure-29.



Figure-29 Manual Error Counter Updating

# 3.4.7 RECEIVE /TRANSMIT MULTIPLEX FUNCTION (RMF / TMF) INDICATION

#### 3.4.7.1 RMFn Indication

In Receive Single Rail NRZ Format mode, the RDNn/RMFn pin is used as RMFn. In Receive Dual Rail Sliced mode, the RCLKn/RMFn pin is used as RMFn. Refer to Table-2 Multiplex Pin Used in Receive System Interface for details.

#### Table-13 RMFn Indication

RMFn can indicate the status of PRBS/ARB, LAIS, LEXZ, LBPV, LEXZ + LBPV, LLOS, output recovered clock (RCLK) or XOR output of positive and negative sliced data, as selected by the RMF\_DEF[2:0] bits (b7~5, RCF1,...). Refer to Table-13 for details.

RMF_DEF[2:0]	Indication On RMF	Details
000	PRBS/ARB	RMFn is high if PRBS/ARB is detected in synchronization in the receive path. During the synchronization, RMFn goes low for a E1 clock cycle if a PRBS/ARB error is detected. RMFn is low if PRBS/ARB is out of synchronization. Refer to Section 3.4.5 PRBS, QRSS, ARB and IB Pattern Generation and Detection.
001	Line Alarm Indication Signal (LAIS)	RMFn is high if AIS is detected in the receive path and low if it is cleared. This indication corresponds to the LAIS_S bit (b6, STAT1,). Refer to Section 3.4.4 Alarm Indication Signal (AIS) Detection and Generation.
010	XOR result of positive and negative sliced data	RMFn outputs XOR data of positive and negative sliced data.
011	recovered clock (RCLK)	RMFn outputs the recovered clock as RCLKn. All the description about RCLKn is applicable for RMFn.
100	Line Excessive Zeroes (LEXZ)	RMFn goes high for a E1 clock cycle if an EXZ is detected in the receive path, otherwise it is low. Refer to Section 3.4.2 Excessive Zeroes (EXZ) Detection.
101	Line Bipolar Violation (LBPV)	RMFn goes high for a E1 clock cycle if a BPV/CV is detected in the receive path, otherwise it is low. Refer to Section 3.4.1 Bipolar Violation (BPV) / Code Violation (CV) Detection and BPV Insertion.
110	LEXZ + LBPV	RMFn goes high for a E1 clock cycle if an EXZ or a BPV/CV is detected in the receive path, otherwise it is low.
111	Line Loss of Signal (LLOS)	RMFn is high if LOS is detected in the receive path and low if it is cleared. This indication corresponds to the LLOS_S bit (b0, STAT0,). Refer to Section 3.4.3.1 Line LOS (LLOS).

#### 3.4.7.2 TMFn Indication

In Transmit Single Rail NRZ Format mode and Transmit Dual Rail RZ Format mode, the TDNn/TMFn pin is used as TMFn. Refer to Table-3 Multiplex Pin Used in Transmit System Interface for details.

TMFn can indicate the status of PRBS/ARB, SAIS, TOC, TLOS, SEXZ, SBPV, SEXZ + SBPV or SLOS, as selected by the TMF\_DEF[2:0] bits (b7~5, TCF1,...). However, the indication of SBPV, SEXZ + SBPV and SLOS is disabled automatically in Transmit Single Rail NRZ Format mode. Refer to Table-14 for details.

#### Table-14 TMFn Indication

TMF_DEF[2:0]	Indication On TMF	Details
000	PRBS/ARB	TMFn is high if PRBS/ARB is detected in synchronization in the transmit path. During the synchronization, TMFn goes low for a E1 clock cycle if a PRBS/ARB error is detected. TMFn is low if PRBS/ARB is out of synchronization.
001	System Alarm Indication Signal (SAIS)	TMFn is high if AIS is detected in the transmit path and low if it is cleared. This indication corresponds to the SAIS_S bit (b7, STAT1,). Refer to Section 3.4.4 Alarm Indication Signal (AIS) Detection and Generation.
010	Transmit Over Current (TOC)	TMFn is high if transmit over current is detected and low if it is cleared. This indication corresponds to the TOC_S bit (b4, STAT0,). Refer to Section 3.2.5.1 Transmit Over Current Protection.
011	Transmit Loss of Signal (TLOS)	TMFn is high if LOS is detected in the transmit line side and low if it is cleared. This indication corresponds to the TLOS_S bit (b2, STAT0,). Refer to Section 3.4.3.3 Transmit LOS (TLOS).
100	System Excessive Zeroes (SEXZ)	TMFn goes high for a E1 clock cycle if an EXZ is detected in the transmit path, otherwise it is low. Refer to Section 3.4.2 Excessive Zeroes (EXZ) Detection
101	System Bipolar Violation (SBPV) *	TMFn goes high for a E1 clock cycle if a BPV/CV is detected in the transmit path, otherwise it is low. Refer to Section 3.4.1 Bipolar Violation (BPV) / Code Violation (CV) Detection and BPV Insertion.
110	System Excessive Zeroes (SEXZ) + System Bipolar Violation (SBPV) *	TMFn goes high for a E1 clock cycle if an EXZ or a BPV/CV is detected in the transmit path, otherwise it is low.
111	System Loss of Signal (SLOS) *	TMFn is high if LOS is detected in the transmit system side and low if it is cleared. This indication corresponds to the SLOS_S bit (b1, STAT0,). Refer to Section 3.4.3.2 System LOS (SLOS).



### 21(+1) CHANNEL HIGH-DENSITY E1 LINE INTERFACE UNIT

#### 3.4.8 LOOPBACK

There are four kinds of loopback:

- Analog Loopback
- Remote Loopback
- Digital Loopback
- Dual Loopback

Refer to Figure-1 for loopback location.

#### 3.4.8.1 Analog Loopback

Analog Loopback is enabled by the ALP bit (b0, LOOP,...). The data stream to be transmitted on the TTIPn/TRINGn pins is internally looped to the RTIPn/RRINGn pins.

In Analog Loopback mode, the data stream to be transmitted is still output to the line side, while the data stream received from the line side is covered by the Analog Loopback data.

Anytime when Analog Loopback is set, the other loopbacks (i.e., Digital Loopback and Remote Loopback) are disabled.

In Analog Loopback, the priority of the diagnostic facilities in the receive path is: pattern generation > looped data. AIS generation is disabled in both the receive path and the transmit path. Refer to Figure-30.



Figure-30 Priority Of Diagnostic Facilities During Analog Loopback

Remote Loopback can be configured manually or automatically. Either manual Remote Loopback configuration or automatic Remote Loopback configuration will enable Remote Loopback.

Manual Remote Loopback is enabled by the RLP bit (b1, LOOP,...).

Automatic Remote Loopback is enabled when the pattern detection is assigned in the receive path (i.e., the PD\_POS bit (b3, PD,...) is '0') and the AUTOLP bit (b3, LOOP,...) is '1'. The corresponding channel will enter Remote Loopback when the activate IB code is detected in the receive path for more than 5.1 sec.; and will return from Remote Loopback when the deactivate IB code is detected in the receive path for more than 5.1 sec. Refer to section Inband Loopback (IB) Detection on page 49 for details. When automatic Remote Loopback is active, setting the AUTOLP bit (b3, LOOP,...) back to '0' will also stop automatic Remote Loopback. The setting of the PD\_POS bit (b3, PD,...) should not be changed during automatic Remote Loopback. The AUTOLP\_S bit (b7, STAT0,...) indicates the automatic Remote Loopback status.

In Remote Loopback mode, the data stream output from the RJA (if enabled) is internally looped to the Waveform Shaper. The data stream received from the line side is still output to the system side, while the data stream input from the system side is covered by the Remote Loopback data and the status on TCLKn does not affect the Remote Loopback. However, the BPV/CV, EXZ, SLOS, AIS and pattern detection in the transmit path still monitors the data stream input from the system side.

In Remote Loopback mode, the priority of the diagnostic facilities in the receive path is: pattern generation > AIS generation; the priority of the diagnostic facilities in the transmit path is: pattern generation > looped data. AIS generation is disabled in the transmit path. Refer to Figure-31.



Figure-31 Priority Of Diagnostic Facilities During Manual Remote Loopback

The Digital Loopback can be configured manually or automatically. Either manual Digital Loopback configuration or automatic Digital Loopback configuration will enable Digital Loopback.

Manual Digital Loopback is enabled by the DLP bit (b2, LOOP,...).

Automatic Digital Loopback is enabled when the pattern detection is assigned in the transmit path (i.e., the PD\_POS bit (b3, PD,...) is '1') and the AUTOLP bit (b3, LOOP,...) is '1'. The corresponding channel will enter Digital Loopback when the activate IB code is detected in the transmit path for more than 5.1 sec.; and will return from Digital Loopback when the deactivate IB code is detected in the transmit path for more than 5.1 sec. Refer to section Inband Loopback (IB) Detection on page 49 for details. When automatic Digital Loopback is active, setting the AUTOLP bit (b3, LOOP,...) back to '0' will also stop automatic Digital Loopback. The setting of the PD\_POS bit (b3, PD,...) should not be changed during automatic Digital Loopback. The AUTOLP\_S bit (b7, STAT0,...) indicates the automatic Digital Loopback status.

In Digital Loopback mode, the data stream output from the TJA (if enabled) is internally looped to the Decoder (if enabled). The data stream to be transmitted is still output to the line side, while the data stream received from the line side is covered by the Digital Loopback data. However, LLOS and AIS detection in the receive path still monitors the data stream received from the line side.

In Digital Loopback mode, the priority of the diagnostic facilities in the receive path is: pattern generation > looped data; the priority of the diagnostic facilities in the transmit path is: pattern generation > looped data > AIS generation. AIS generation is disabled in the receive path.



Figure-32 Priority Of Diagnostic Facilities During Digital Loopback

#### 3.4.8.4 Dual Loopback

Dual Loopback refers to the simultaneous implementation of Remote Loopback and Digital Loopback. Two kinds of combinations are supported:

- Manual Remote Loopback + Manual Digital Loopback;
- Manual Remote Loopback + Automatic Digital Loopback.

Note that when Digital Loopback is active, automatic Remote Loopback is unavailable as the pattern detection is within the digital loop.

In Dual Loopback mode, the data stream received from the line side outputs from the RJA (if enabled), loops to the Waveform Shaper internally and does not output to the system side. The data stream to be transmitted from the system side outputs from the TJA (if enabled), loops to the Decoder (if enabled) internally and does not output to the line side. LLOS, AIS detection in the receive path monitors the data stream received from the line side. The BPV/CV, EXZ and pattern detection in the receive path monitors the digital looped data. The BPV/CV, EXZ, SLOS, AIS and pattern detection in the transmit path monitors the data stream input from the system side.

#### Manual Remote Loopback + Manual Digital Loopback

This combination of Dual Loopback is enabled when both manual Remote Loopback and manual Digital Loopback are enabled. Manual Remote Loopback is enabled by the RLP bit (b1, LOOP,...). Manual Digital Loopback is enabled by the DLP bit (b2, LOOP,...).

In this condition, the priority of the diagnostic facilities in the receive path is: pattern generation > digital looped data; the priority of the diagnostic facilities in the transmit path is: remote looped data > pattern generation. AIS generation is disabled in both the receive path and the transmit path.

Refer to Figure-33.

#### Manual Remote Loopback + Automatic Digital Loopback

This combination of Dual Loopback is enabled when both manual Remote Loopback and automatic Digital Loopback are enabled. Manual Remote Loopback is enabled by the RLP bit (b1, LOOP,...). Automatic Digital Loopback is enabled when the pattern detection is assigned in the transmit path (i.e., the PD\_POS bit (b3, PD,...) is '1') and the AUTOLP bit (b3, LOOP,...) is '1'. The corresponding channel will enter Digital Loopback when the activate IB code is detected in the transmit path for more than 5.1 sec.; and will return from Digital Loopback when the deactivate IB code is detected in the transmit path for more than 5.1 sec. Refer to section Inband Loopback (IB) Detection on page 49 for details. When automatic Digital Loopback is active, setting the AUTOLP bit (b3, LOOP,...) back to '0' will also stop automatic Digital Loopback. The setting of the PD\_POS bit (b3, PD,...) should not be changed during automatic Digital Loopback. The AUTOLP\_S bit (b7, STAT0,...) indicates the automatic Digital Loopback status.

In this condition, the priority of the diagnostic facilities in the receive path is: pattern generation > digital looped data. AIS generation in both the receive path and the transmit path, the pattern generation in the transmit path are disabled.

Refer to Figure-34.



Figure-33 Priority Of Diagnostic Facilities During Manual Remote Loopback + Manual Digital Loopback



Figure-34 Priority Of Diagnostic Facilities During Manual Remote Loopback + Automatic Digital Loopback

#### 21(+1) CHANNEL HIGH-DENSITY E1 LINE INTERFACE UNIT

#### 3.4.9 CHANNEL 0 MONITORING

Channel 0 is a special channel. It can be used in normal operation as the other 21 channels, or it can be used as a monitoring channel. Channel 0 supports G.772 Monitoring and Jitter Measurement.

#### 3.4.9.1 G.772 Monitoring

Selected by the MON[5:0] bits (b5~0, MON), any receiver or transmitter of the other 21 channels can be monitored by channel 0 (as shown in Figure-35).

When the G.772 Monitoring is implemented (the MON[5:0] bits (b5~0, MON) is not '0'), the registers of the receiver of channel 0 should be the same as those of the selected receiver /transmitter except the line interface related registers.

Once the G.772 Monitoring is implemented, the receiver of channel 0 switches to External Impedance Matching mode automatically, and the setting in the R\_TERM[2:0] bits (b2~0, RCF0,...) of channel 0 is ignored.

During the G.772 Monitoring, channel 0 processes as normal after data is received from the selected path and the operation of the monitored path is not effected.

The signal which is monitored goes through the Clock & Data Recovery of monitoring channel (channel 0). The monitored clock can output on RCLK0. The monitored data can be observed digitally on the output pin of RCLK0, RD0/RDP0 and RDN0. LOS detector is still in use in channel 0 for the monitored signal.

In monitoring mode, channel 0 can be configured to Remote Loopback. The signal which is being monitored will output on TTIP0 and TRING0. The output signal can then be connected to a standard test equipment for non-intrusive monitoring.



Figure-35 G.772 Monitoring

#### 3.4.9.2 Jitter Measurement (JM)

The RJA of channel 0 consists of a Jitter Measurement (JM) module. When the RJA is enabled in channel 0, the JM is used to measure the positive and negative peak value of the demodulated jitter signal of the received data stream. The bandwidth of the measured jitter is selected by the JM\_BW bit (b0, JM).

The greatest positive peak value monitored in a certain period is indicated by the JIT\_PH and JIT\_PL registers, while the greatest negative peak value monitored in the same period is indicated by the JIT\_NH and JIT\_NL registers. The relationship between the greatest positive /negative peak value and the indication in the corresponding registers is:

Positive Peak = [JIT\_PH, JIT\_PL] / 16 (UIpp);

Negative Peak = [JIT\_NH, JIT\_NL] / 16 (Ulpp).

The period is determined by the JM\_MD bit (b1, JM).

When the JM\_MD bit (b1, JM) is '1', the period is one second automatically. The one-second timer uses MCLK as clock reference. The expiration of each one second will set the TMOV\_IS bit (b0, INTTM) and induce an interrupt reported by INT if not masked by the TMOV\_IM bit (b0, GCF). The TMOV\_IS bit (b0, INTTM) is cleared after a '1' is written to this bit. When each one second expires, internal buffers transfer the greatest positive/negative peak value accumulated in this one second to the JIT\_PH and JIT\_PL / JIT\_NH and JIT\_NL registers respectively and the internal buffers will be cleared to start a new round measurement. The registers should be read in the next second, otherwise they will be overwritten. Refer to Figure-36 for the process.

When the JM\_MD bit (b1, JM) is '0', the period is controlled by the JM\_STOP bit (b2, JM) manually. When there is a transition from '0' to '1' on the JM\_STOP bit (b2, JM), the internal buffers transfer the greatest positive/negative peak value accumulated in this period to the JIT\_PH and JIT\_PL / JIT\_NH and JIT\_NL registers respectively and the internal buffers will be cleared to start a new round measurement. The registers should be read in the next round of jitter measurement, otherwise they will be overwritten. Refer to Figure-37 for the process.







Figure-37 Manual JM Updating

# 3.5 CLOCK INPUTS AND OUTPUTS

The IDT82P2521 provides two kinds of clock outputs:

- Free running clock outputs on CLKE1
- · Receiver clock outputs on REFA and REFB
  - selected from any of the 22 recovered line clocks
  - driven by MCLK (free running)
  - driven by external CLKA/CLKB input

A Frequency Synthesizer is also available to scale REFA to 8 different frequencies.

The following Clock Inputs are provided:

- MCLK as programmable reference timing for the IDT82P2521.
- CLKA and CLKB as optional input clock source for REFA and REFB respectively

#### 3.5.1 FREE RUNNING CLOCK OUTPUTS ON CLKE1

An internal clock generator uses MCLK as reference to generate all the clocks required by internal circuits and CLKE1 outputs. MCLK is a stable jitter-free<sup>1</sup> clock input with  $\pm 50$  ppm accuracy. The clock

frequency of MCLK is 2.048 X N MHz (1  $\le$  N  $\le$  8, N is an integer number), as determined by MCKSEL[3:0]. Refer to Chapter 2 Pin Description for details.

The outputs on CLKE1 is free running (locking to MCLK). The output of CLKE1 is determined by the CLKE1\_EN bit (b3, CLKG) and the CLKE1 bit (b2, CLKG). Refer to Table-15.

### Table-15 Clock Output on CLKE1

Contro	ol Bits	Clock Output On CLKE1			
CLKE1_EN	CLKE1				
0	(don't-care)	High-Z			
1	0	8 KHz			
I	1	2.048 KHz			

1. Jitter is no more than 0.001 UI.

#### 3.5.2 CLOCK OUTPUTS ON REFA/REFB

The outputs on REFA and REFB can be enabled or disabled, as determined by the REFA\_EN bit (b6, REFA) and the REFB\_EN bit (b6, REFB) respectively.

When the output is disabled, REFA/REFB is in High-Z state.

When the output is enabled, the output of REFA and REFB varies in different operations. Refer to below for detailed description. Refer to Figure-38 and Figure-39 for an overview of REFA and REFB output options in normal operation.

#### 3.5.2.1 REFA/REFB in Clock Recovery Mode

In this mode (default), the clock of REFA and REFB is derived from the recovered clock of one of the 22 channels as selected by the REFA[4:0] bits (b4~0,REFA) and REFB[4:0] bits (b4~0,REFB). Determined by the FS\_BYPAS bit (b4, REFCF) a Frequency Synthesizer can be enabled for REFA (refer to Section 3.5.2.2 Frequency Synthesizer for REFA Clock Output). If the Frequency Synthesizer is disabled, REFA will output the recovered 2.048 MHz clock depending on the line mode of the selected channel. REFB output the recovered 2.048 MHz clock depending on the line mode of the selected channel.

The recovered line clock can be output to REFA and REFB before or after it passed the receive Jitter Attenuator (RJA) selected by the JA\_BYPAS bit (b6, REFCF).

#### 3.5.2.2 Frequency Synthesizer for REFA Clock Output

For REFA a Frequency Synthesizer can be enabled or bypassed (default) as selected by FS\_BYPASS bit (b4, REFCF). The output frequency is selected by the FREQ[2:0] bits (b2~0, REFCF). Frequencies supported are 8 KHz, 64 KHz, 2.048 MHz, 4.096 MHz, 8.192 MHz, 19.44 MHz or 32.768 MHz.

#### 3.5.2.3 Free Run Mode for REFA Clock Output

REFA can also be selected to provide a free running clock locked to MCLK. To enable this mode the Frequency Synthesizer has to be enabled by setting the FS\_BYPAS bit (b4, REFCF) to '0', and the FREE bit (b3, REFCF) has to be set to '1'. REFA will provide a frequency selected by the FREQ[2:0]<sup>1</sup> bits (b2~0, REFCF) which is a free running clock locked to MCLK.

#### 3.5.2.4 REFA/REFB Driven by External CLKA/CLKB Input

In this mode, the clock of REFA and REFB is driven from an external clock input of CLKA and CLKB respectively. CLKA and CLKB are selected as an input source by setting REFA[4:0] bits (b4~0, REFA) and REFB[4:0] bits (b4~0, REFB) to any value from '11101' to '11111'.

1. '000' and '011' are reserved for FREQ[2:0] in this mode.

CLKA and CLKB are an external E1 (2.048 MHz) Clock Input. The CKA\_E1 bit (b5, REFA) and CKB\_E1 bit (b5, REFB) should be set to match the input clock frequency.

Determined by the FS\_BYPASS bit (b4, REFCF), a Frequency Synthesizer can be enabled for REFA (refer to Section 3.5.2.2 Frequency Synthesizer for REFA Clock Output). If the Frequency Synthesizer is disabled, REFA and REFB will output the 2.048 MHz clock.

# 3.5.2.5 REFA and REFB in Loss of Signal (LOS) or Loss of Clock Condition

If the recovered clock of one of the 22 channels is selected as the clock source for REFA and REFB (refer to Section 3.5.2.1 REFA/REFB in Clock Recovery Mode) and Line LOS (LLOS) is detected in the corresponding channel, the state of output on REFA and REFB can be selected by the REFH bit (b5, REFCF). If REFH is set to '1', REFA and REFB will output a high level in case of LLOS. If REFH is set to '0' and LLOS is detected, REFA and REFB clock outputs will be locked to MCLK while the selected clock frequency will remain unchanged.

LLOS condition is set when LLOS\_S bit (b0, STAT0) is '1'. Refer to Section 3.4.3.1 Line LOS (LLOS).

Refer to Figure-40 for a detailed overview of REFA output in case of LLOS. REFB output option is only determined by the REFH bit (b5, REFCF) to be locked to MCLK or set to high level output.

If CLKA is selected as the clock source for REFA (refer to Section 3.5.2.4 REFA/REFB Driven by External CLKA/CLKB Input) and there is no clock input on CLKA for more than 8 E1 clock cycles if E1 mode is selected (i.e. CKA\_E1 bit (b5, REFA) is '1'), the state of the REFA output is determined by the FS\_BYPAS bit (b4, REFCF) and the FREE bit (b3, REFCF). In case the Frequency Synthesizer is disabled (i.e. FS\_BYPAS bit (b4, REFCF) is '0'). REFA will output a high level. If the Frequency Synthesizer is enabled and the FREE bit (b3, REFCF) is set to '0', REFA will output a high level. If the Frequency Synthesizer is enabled and the FREE bit (b3, REFCF) is set to '1', REFA will be locked to MCLK.

Refer to Figure-41 for a detailed overview of REFA output in case of loss of CLKA.

If CLKB is selected as the clock source for REFB (refer to section Section 3.5.2.4 REFA/REFB Driven by External CLKA/CLKB Input) and there is no clock input on CLKB for more than 8 E1 clock cycles if E1 mode is selected (i.e. CKB\_E1 bit (b5, REFB) is '1'), the output on REFB is determined by the REFH bit (b5, REFCF). If REFH is set to '1', REFB will output a high level. If REFH is set to '0', the REFB clock output will be locked to MCLK.



Note \*: '000' and '011' are reserved for FREQ[2:0] when REFA is free running.

# Figure-38 REFA Output Options in Normal Operation





Figure-39 REFB Output Options in Normal Operation



Note \*: '000' and '011' are reserved for FREQ[2:0] when REFA is free running.

# Figure-40 REFA Output in LLOS Condition (When RCLKn Is Selected)



Note \*: '000' and '011' are reserved for FREQ[2:0] when REFA is free running.

### Figure-41 REFA Output in No CLKA Condition (When CLKA Is Selected)

#### 3.5.3 MCLK, MASTER CLOCK INPUT

MCLK provides a stable reference timing for the IDT82P2521. MCLK should be a jitter-free<sup>1</sup> clock with ±50 ppm accuracy. The clock frequency of MCLK is set by pins MCKSEL[3:0] and can be N x 2.048 MHz with  $1 \le N \le 8$  (N is an integer number). Refer to MCKSEL[3:0] pin description for details.

If there is a loss of MCLK (duty cycle is less than 30% for 10  $\mu$ s), the device will enter power down. In this case, both the receive and transmit circuits are turned off. The pins on the line interface will be in High-Z state. The pins on receive system interface will be in High-Z state or in low level, as selected by the RHZ bit (b6, RCF0,...). The input on the

transmit system interface is ignored and the output on the transmit system interface will be in High-Z state. Refer to Section 3.1.7 Receiver Power Down and Section 3.2.7 Transmitter Power Down for details.

If MCLK recovers after loss of MCLK the device will be reset automatically.

#### 3.5.4 XCLK, INTERNAL REFERENCE CLOCK INPUT

XCLK is derived from MCLK. For the respective channel, it is 2.048 MHz. XCLK is used as selectable reference clock for

- pattern /AIS generation
- RCLKn in LLOS
- · Loss of TCLKn to determine Transmit Output High-Z.

<sup>1.</sup> Jitter is no more than 0.001 UI.

# 3.6 INTERRUPT SUMMARY

There are altogether 20 kinds of interrupt sources as listed in Table-16. Among them, No.1 to No.19 are per-channel interrupt sources, while No. 20 is a global interrupt source.

For interrupt sources from No.1 to No.10, the occurrence of the event will cause the corresponding Status bit to be set to '1'. And selected by the Interrupt Trigger Edges Select bit, either a transition from '0' to '1' or any transition from '0' to '1' or from '1' to '0' of the Status bit will cause the Interrupt Status bit to be set to '1', which indicates the occurrence of an interrupt event.

For interrupt sources from No.11 to No.20, the occurrence of the event will cause the corresponding Interrupt Status Bit to be set to '1'.

All the interrupt can be masked by the GLB\_IM bit (b1, GCF) globally or by the corresponding interrupt mask bit individually. For all the interrupt sources, if not masked, the occurrence of the interrupt event will trigger an interrupt indicated by the INT pin. For per-channel interrupt sources, if not masked, the occurrence of the interrupt event will also cause the corresponding INT\_CHn bit (INTCH1~4) to be set '1'.

An interrupt event is cleared by writing '1' to the corresponding Interrupt Status bit. The INT\_CHn bit (INTCH1~4) will not be cleared until all the interrupts in the corresponding channel are acknowledged. The  $\overline{\rm INT}$  pin will be inactive until all the interrupts are acknowledged. Refer to Figure-42 for interrupt service flow.

#### **Table-16 Interrupt Summary**

No.	Interrupt Source	Status Bit	Interrupt Trigger Edges Select Bit	Interrupt Status Bit	Interrupt Mask Bit
1	TCLKn is missing.	TCKLOS_S (b3, STAT0,)	TCKLOS_IES (b3, INTES,)	TCKLOS_IS (b3, INTS0,)	TCKLOS_IM (b3, INTM0,)
2	LLOS is detected.	LLOS_S (b0, STAT0,)	LOS_IES (b1, INTES,)	LLOS_IS (b0, INTS0,)	LLOS_IM (b0, INTM0,)
3	SLOS is detected.	SLOS_S (b1, STAT0,)	LOS_IES (b1, INTES,)	SLOS _IS (b1, INTS0,)	SLOS_IM (b1, INTM0,)
4	TLOS is detected.	TLOS_S (b2, STAT0,)	TLOS_IES (b2, INTES,)	TLOS_IS (b2, INTS0,)	TLOS_IM (b2, INTM0,)
5	LAIS is detected.	LAIS_S (b6, STAT1,)	AIS_IES (b6, INTES,)	LAIS_IS (b6, INTS1,)	LAIS_IM (b6, INTM1,)
6	SAIS is detected.	SAIS_S (b7, STAT1,)	AIS_IES (b6, INTES,)	SAIS_IS (b7, INTS1,)	SAIS_IM (b7, INTM1,)
7	TOC is detected.	TOC_S (b4, STAT0,)	TOC_IES (b4, INTES,)	TOC_IS (b4, INTS0,)	TOC_IM (b4, INTM0,)
8	The PRBS/ARB pattern is detected syn- chronized.	PA_S (b5, STAT1,)	PA_IES (b5, INTES,)	PA_IS (b5, INTS1,)	PA_IM (b5, INTM1,)
9	Activate IB code is detected.	IBA_S (b1, STAT1,)	IB_IES (b0, INTES,)	IBA_IS (b1, INTS1,)	IBA_IM (b1, INTM1,)
10	Deactivate IB code is detected.	IBD_S (b0, STAT1,)	IB_IES (b0, INTES,)	IBD_IS (b0, INTS1,)	IBD_IM (b0, INTM1,)
11	The FIFO of the RJA is overflow or underflow.	-	-	RJA_IS (b5, INTS0,)	RJA_IM (b5, INTM0,)
12	The FIFO of the TJA is overflow or underflow.	-	-	TJA_IS (b6, INTS0,)	TJA_IM (b6, INTM0,)
13	Waveform amplitude is overflow.	-	-	DAC_IS (b7, INTS0,)	DAC_IM (b7, INTM0,)
14	SBPV is detected.	-	-	SBPV_IS (b5, INTS2,)	SBPV_IM (b5, INTM2,)
15	LBPV is detected.	-	-	LBPV_IS (b4, INTS2,)	LBPV_IM (b4, INTM2,)
16	SEXZ is detected.	-	-	SEXZ_IS (b3, INTS2,)	SEXZ_IM (b3, INTM2,)
17	LEXZ is detected.	-	-	LEXZ_IS (b2, INTS2,)	LEXZ_IM (b2, INTM2,)
18	PRBS/ARB error is detected.	-	-	ERR_IS (b1, INTS2,)	ERR_IM (b1, INTM2,)
19	The ERRCH and ERRCL registers are overflowed.	-	-	CNTOV_IS (b0, INTS2,)	CNTOV_IM (b0, INTM2,)
20	One second time is over.	-	-	TMOV_IS (b0, INTTM)	TMOV_IM (b0, GCF)





Figure-42 Interrupt Service Process

ENESAS

# 4 MISCELLANEOUS

# 4.1 RESET

DT82P2521

The reset operation resets all registers, state machines as well as I/O pins to their default value or status.

The IDT82P2521 provides 4 kinds of reset:

- · Power-on reset;
- · Hardware reset;
- · Global software reset;
- Per-channel software reset.

The Power-on, Hardware and Global software reset operations reset all the common blocks (including clock generator/synthesizer and microprocessor interface) and channel-related parts. The Per-channel software reset operation resets the channel-related parts. Figure-43 shows a general overview of the reset options.

During reset, all the line interface pins (i.e., TTIPn/TRINGn and RTIPn/RRINGn) are in High-Z state.

After reset, all the items listed in Table-17 are true.

#### Table-17 After Reset Effect Summary



Figure-43 Reset

Effect On	Power-On Reset, Hardware Reset and Global Software Reset	Per-Channel Software Reset	
TTIPn/TRINGn & RTIPn/ RRINGn	All TTIPn/TRINGn & RTIPn/RRINGn pins are in High-Z state.	Only TTIPn/TRINGn & RTIPn/RRINGn in the corresponding chan- nel are in High-Z.	
Line Interface Mode	Not E1 mode.	Not E1 mode.	
System interface	All channels are in Dual Rail NRZ Format.	Only the corresponding channel is in Dual Rail NRZ Format.	
General I/O pins (i.e., D[7:0] and GPIO[1:0])	As input pins.	(No effect)	
INT	Open drain output.	(No effect)	
CLKE1, REFA, REFB	Output enable.	(No effect)	
LLOS, LLOS0	Output enable.	(No effect)	
TDO, SDO/ACK/RDY	High-Z.	(No effect)	
state machines	All state machines are reset.	The state machines in the corresponding channel are reset.	
Interrupt sources	All interrupt sources are masked.	The interrupt sources in the corresponding channel are masked.	
Registers	All registers are reset to their default value.	The registers in the corresponding channel are reset to their default value except that there is no effect on the E1 bit.	

#### 4.1.1 POWER-ON RESET

Power-on reset is initiated during power-up. When all VDD inputs (1.8V and 3.3V) reach approximately 60% of the standard value of VDD, power-on reset begins. If MCLK is applied, power-on reset will complete within 1 ms maximum; if MCLK is not applied, the device remains in reset state.

#### 4.1.2 HARDWARE RESET

Pulling the  $\overline{RST}$  pin to low will initiate hardware reset. The reset cycle should be more than 1 µs. If the  $\overline{RST}$  pin is held low continuously, the device remains in reset state.

#### 4.1.3 GLOBAL SOFTWARE RESET

Writing the RST register will initiate global software reset. Once initiated, global software reset completes in 1  $\mu$ s maximum.

#### 4.1.4 PER-CHANNEL SOFTWARE RESET

Writing a '1' to the CHRST bit (b1, CHCF,...) will initiate per-channel software reset. Once initiated, per-channel software reset completes in 1  $\mu$ s maximum and the CHRST bit (b1, CHCF,...) is self cleared.

#### **Table-18 Microprocessor Interface**

This reset is different from other resets, for:

- It does not reset the global registers, state machines and common pins (including the pins of clock generator, microprocessor interface and JTAG interface);
- · It does not reset the other channels.

### 4.2 MICROPROCESSOR INTERFACE

The microprocessor interface provides access to read and write the registers in the device. The interface consists of:

- · Serial microprocessor interface;
- Parallel Motorola Non-Multiplexed microprocessor interface;
- · Parallel Motorola Multiplexed microprocessor interface;
- · Parallel Intel Non-Multiplexed microprocessor interface;
- · Parallel Intel Multiplexed microprocessor interface.

The microprocessor interface is selected by the P/S, INT/MOT and IM pins, as shown in Table-18. The interfaced pins in different interfaces are also listed in Table-18. Refer to Section 8.11 Microprocessor Interface Timing for the timing characteristics.

P/S	INT/MOT	IM	Microprocessor Interface	Interfaced Pins
GNDD	Open	GNDD	Serial microprocessor interface	CS, SCLK, SDI, SDO
VDDIO	GNDD	GNDD	Parallel Motorola Non-Multiplexed microprocessor interface	CS, DS, R/W, ACK, D[7:0], A[10:0]
		Open	Parallel Motorola Multiplexed microprocessor interface	CS, AS, DS, R/W, ACK, D[7:0], A[10:8]
	Open	GNDD	Parallel Intel Non-Multiplexed microprocessor interface	CS, RD, WR, RDY, D[7:0], A[10:0]
		Open	Parallel Intel Multiplexed microprocessor interface	CS, ALE, RD, WR, RDY, D[7:0], A[10:8]

## 4.3 POWER UP

No power up sequencing for the VDD inputs (1.8 V and 3.3 V) has to be provided for the IDT82P2521. A Power-on reset will be initiated during power up. Refer to Section 4.1 Reset.

# 4.4 HITLESS PROTECTION SWITCHING (HPS) SUM-MARY

In today's telecommunication systems, ensuring no traffic loss is becoming increasingly important. To combat these problems, redundancy protection must be built into the systems carrying this traffic. There are many types of redundancy protection schemes, including 1+1 and 1:1 hardware protection without the use of external relays. Refer to

Figure-44, Figure-45 and Figure-46 for different protection schemes. The IDT82P2521 provides an enhanced architecture to support both protection schemes.

IDT82P2521 highlights for HPS support:

- Independent programmable receive and transmit high impedance for Tip and Ring inputs and outputs to support 1+1 and 1:1 redundancy
- Fully integrated receive termination, required to support 1:1 redundancy
- Enhanced internal architecture to guarantee High Impedance for Tip and Ring Inputs and Outputs during Power Off or Power Failure
- Asynchronous hardware control (OE, RIM) for fast global high impedance of receiver and transmitter (hot switching between working and backup board)



**Rx:** Partially Internal Impedance Matching mode. A fixed external 120  $\Omega$  resistor is placed on the backplane and provides a common termination for E1 applications. The R\_TERM[2:0] bits (b2~0, RCF0,...) setting is as follows: '010' for E1 120  $\Omega$  twisted pair cable and '011' for E1 75  $\Omega$  coaxial cable.

Tx: Internal Impedance Matching mode. The T\_TERM[2:0] bits (b2~0, TCF0,...) setting is as follows: '010' for E1 120  $\Omega$  twisted pair cable and '011' for E1 75  $\Omega$  coaxial cable.







**Rx:** Fully Internal Impedance Matching mode. In this mode, there is no external resistor required. The R\_TERM[2:0] bits (b2~0, RCF0,...) setting is as follows: '010' for E1 120  $\Omega$  twisted pair cable and '011' for E1 75  $\Omega$  coaxial cable. **Tx:** Internal Impedance Matching mode. The T\_TERM[2:0] bits (b2~0, TCF0,...) setting is as follows: '010' for E1 120  $\Omega$  twisted pair cable and '011' for E1 75  $\Omega$  coaxial cable.







**Rx:** 75  $\Omega$  External Impedance Matching mode. In this mode, there is no external resistor required. The RIM pin should be left open and the configuration of the R\_TERM[2:0] bits (b2~0, RCF0,...) is ignored.

Tx: 75 Ω Internal Impedance Matching mode. The T\_TERM[2:0] bits (b2~0, TCF0,...) should be set to '011'.

#### Figure-46 1+1 HPS Scheme, E1 75 ohm Single-Ended Interface (Shared Common Transformer)
# **5 PROGRAMMING INFORMATION**

## 5.1 REGISTER MAP

#### 5.1.1 GLOBAL REGISTER

Address (Hex)	Register Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reference Page
Common	Control					I		I		1
000	ID - Device ID Register	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0	P 77
040	RST - Global Reset Register	RST7	RST6	RST5	RST4	RST3	RST2	RST1	RST0	P 77
080	GCF - Global Configuration Register	-	-	-	COPY	INT_PIN1	INT_PIN0	GLB_IM	TMOV_IM	P 78
0C0	MON - G.772 Monitor Configura- tion Register	-	-	MON5	MON4	MON3	MON2	MON1	MON0	P 79
100	GPIO - General Purpose I/O Pin Definition Register	-	-	-	-	LEVEL1	LEVEL0	DIR1	DIR0	P 80
Reference	e Clock Timing Option		1		1	I		I	1	
1C0	CLKG - CLKE1 Generation Con- trol Register	-	-	-	-	CLKE1_EN	CLKE1	-	-	P 80
200	REFCF - REFA/B Output Con- figuration Register	-	JA_BYPAS	REFH	FS_BYPAS	FREE	FREQ2	FREQ1	FREQ0	P 81
240	REFA - REFA Clock Sources Configuration Register	-	REFA_EN	CKA_E1	REFA4	REFA3	REFA2	REFA1	REFA0	P 83
280	REFB - REFB Clock Sources Configuration Register	-	REFB_EN	CKB_E1	REFB4	REFB3	REFB2	REFB1	REFB0	P 83
Interrupt I	Indication		1		1	I		I	1	
2C0	INTCH1 - Interrupt Requisition Source Register 1	INT_CH8	INT_CH7	INT_CH6	INT_CH5	INT_CH4	INT_CH3	INT_CH2	INT_CH1	P 84
300	INTCH2 - Interrupt Requisition Source Register 2	INT_CH16	INT_CH15	INT_CH14	INT_CH13	INT_CH12	INT_CH11	INT_CH10	INT_CH9	P 84
340	INTCH3 - Interrupt Requisition Source Register 3	-	-	-	INT_CH21	INT_CH20	INT_CH19	INT_CH18	INT_CH17	P 84
380	INTCH4 - Interrupt Requisition Source Register 4	INT_CH0	-	-	-	-	-	-	-	P 85
3C0	INTTM - One Second Timer Interrupt Status Register	-	-	-	-	-	-	-	TMOV_IS	P 85

#### 5.1.2 PER-CHANNEL REGISTER

Except for registers 7E5~7E9, which are channel 0 related registers, only the address of channel 1 is listed in the 'Address (Hex)' column of the following table. For the addresses of the other channels, refer to the description of each register.

Address (Hex)	Register Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reference Page
Channel	Control		I	I			I	I	I	I
001	CHCF - Channel Configuration Register	-	-	-	-	-	-	CHRST	-	P 85
JA Config	guration		1	1			1	1	1	1
002	TJA - Transmit Jitter Attenuation Configuration Register	-	-	-	TJA_LIMT	TJA_EN	TJA_DP1	TJA_DP0	TJA_BW	P 86
003	RJA - Receive Jitter Attenuation Configuration Register				RJA_LIMT	RJA_EN	RJA_DP1	RJA_DP0	RJA_BW	P 87
Transmit	Path Configuration		L				L	•	•	
004	TCF0 - Transmit Configuration Register 0	-	OE	T_OFF	THZ_OC	T_SING	T_TERM2	T_TERM1	T_TERM0	P 88
005	TCF1 - Transmit Configuration Register 1	TMF_DEF2	TEM_DEF1	TMF_DEF0	TCK_ES	TD_INV	T_CODE	T_MD1	T_MD0	P 89
006	PULS - Transmit Pulse Configu- ration Register	-	-	-	-	PULS3	PULS2	PULS1	PULS0	P 90
007	SCAL - Amplitude Scaling Con- trol Register	-	-	SCAL5	SCAL4	SCAL3	SCAL2	SCAL1	SCAL0	P 91
008	AWG0 - Arbitrary Waveform Generation Control Register 0	-	DONE	RW	SAMP4	SAMP3	SAMP2	SAMP1	SAMP0	P 91
009	AWG1 - Arbitrary Waveform Generation Control Register 1	-	WDAT6	WDAT5	WDAT4	WDAT3	WDAT2	WDAT1	WDAT0	P 92
Receive I	Path Configuration									
00A	RCF0 - Receive Configuration Register 0	RCKH	RHZ	R_OFF	R120IN	R_SING	R_TERM2	R_TERM1	R_TERM0	P 93
00B	RCF1 - Receive Configuration Register 1	RMF_DEF2	RMF_DEF1	RMF_DEF0	RCK_ES	RD_INV	R_CODE	R_MD1	R_MD0	P 94
00C	RCF2 - Receive Configuration Register 2	-	-	-	-	-	-	MG1	MG0	P 95
Diagnosti	cs		L				L	l	l	L
00D	LOS - LOS Configuration Regis- ter	LAC	ALOS2	ALOS1	ALOS0	TALOS1	TALOS0	TDLOS1	TDLOS0	P 96
00E	ERR - Error Detection & Inser- tion Control Register	EXZ_DEF	BPV_INS	ERR_INS	CNT_SEL2	CNT_SEL1	CNT_SEL0	CNT_MD	CNT_STOP	P 97
00F	AISG - AIS Generation Control Register	-	-	-	-	ASAIS_SL OS	ASAIS_LLO S	ALAIS_SLO S	ALAIS_LLO S	P 98
010	PG - Pattern Generation Control Register	-	PG_CK	PG_EN1	PG_EN0	PG_POS	PAG_INV	PRBG_SEL 1	PRBG_SEL 0	P 99

# RENESAS

Address (Hex)	Register Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reference Page
011	PD - Pattern Detection Control Register	-	-	-	-	PD_POS	PAD_INV	PAD_SEL1	PAD_SEL0	P 100
012	ARBL - Arbitrary Pattern Gener- ation / Detection Low-Byte Reg- ister	ARB7	ARB6	ARB5	ARB4	ARB3	ARB2	ARB1	ARB0	P 101
013	ARBM - Arbitrary Pattern Gen- eration / Detection Middle-Byte Register	ARB15	ARB14	ARB13	ARB12	ARB11	ARB10	ARB9	ARB8	P 101
014	ARBH - Arbitrary Pattern Gener- ation / Detection High-Byte Reg- ister	ARB23	ARB22	ARB21	ARB20	ARB19	ARB18	ARB17	ARB16	P 101
015	IBL - Inband Loopback Control Register	-	-	IBGL1	IBGL0	IBAL1	IBAL0	IBDL1	IBDL0	P 102
016	IBG - Inband Loopback Genera- tion Code Definition Register	IBG7	IBG6	IBG5	IBG4	IBG3	IBG2	IBG1	IBG0	P 102
017	IBDA - Inband Loopback Detec- tion Target Activate Code Defini- tion Register	IBA7	IBA6	IBA5	IBA4	IBA3	IBA2	IBA1	IBA0	P 103
018	IBDD - Inband Loopback Detec- tion Target Deactivate Code Definition Register	IBD7	IBD6	IBD5	IBD4	IBD3	IBD2	IBD1	IBD0	P 103
019	LOOP - Loopback Control Reg- ister	-	-	-	-	AUTOLP	DLP	RLP	ALP	P 104
Interrupt	Edge Selection			•						
01A	INTES - Interrupt Trigger Edges Select Register	-	AIS_IES	PA_IES	TOC_IES	TCKLOS_I ES	TLOS_IES	LOS_IES	IB_IES	P 105
Interrupt	Mask			•	L	1		L	•	
01B	INTM0 - Interrupt Mask Register 0	DAC_IM	TJA_IM	RJA_IM	TOC_IM	TCKLOS_I M	TLOS_IM	SLOS_IM	LLOS_IM	P 106
01C	INTM1 - Interrupt Mask Register 1	SAIS_IM	LAIS_IM	PA_IM	-	-	-	IBA_IM	IBD_IM	P 107
01D	INTM2 - Interrupt Mask Register 2	-	-	SBPV_IM	LBPV_IM	SEXZ_IM	LEXZ_IM	ERR_IM	CNTOV_IM	P 108
Status Ind	dication			•						
01E	STAT0 - Status Register 0	AUTOLP_S	-	-	TOC_S	TCKLOS_S	TLOS_S	SLOS_S	LLOS_S	P 109
01F	STAT1 - Status Register 1	SAIS_S	LAIS_S	PA_S	-	-	-	IBA_S	IBD_S	P 110
Interrupt	Status Indication	· · · · ·								
020	INTS0 - Interrupt Status Regis- ter 0	DAC_IS	TJA_IS	RJA_IS	TOC_IS	TCKLOS_I S	TLOS_IS	SLOS_IS	LLOS_IS	P 111
021	INTS1 - Interrupt Status Regis- ter 1	SAIS_IS	LAIS_IS	PA_IS	-	-	-	IBA_IS	IBD_IS	P 112
022	INTS2 - Interrupt Status Regis- ter 2	-	-	SBPV_IS	LBPV_IS	SEXZ_IS	LEXZ_IS	ERR_IS	CNTOV_IS	P 113

# RENESAS

Address (Hex)	Register Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reference Page
Counter	·									
023	ERRCL - Error Counter Low- Byte Register	ERRC7	ERRC6	ERRC5	ERRC4	ERRC3	ERRC2	ERRC1	ERRC0	P 114
024	ERRCH - Error Counter High- Byte Register	ERRC15	ERRC14	ERRC13	ERRC12	ERRC11	ERRC10	ERRC9	ERRC8	P 114
Jitter Mea	asurement (channel 0 Only)								•	
7E5	JM - Jitter Measurement Config- uration For Channel 0 Register	-	-	-	-	-	JM_STOP	JM_MD	JM_BW	P 115
7E6	JIT_PL - Positive Peak Jitter Measurement Low-Byte Regis- ter	JIT_P7	JIT_P6	JIT_P5	JIT_P4	JIT_P3	JIT_P2	JIT_P1	JIT_P0	P 115
7E7	JIT_PH - Positive Peak Jitter Measurement High-Byte Regis- ter	-	-	-	-	JIT_P11	JIT_P10	JIT_P9	JIT_P8	P 115
7E8	JIT_NL - Negative Peak Jitter Measurement Low-Byte Regis- ter	JIT_N7	JIT_N6	JIT_N5	JIT_N4	JIT_N3	JIT_N2	JIT_N1	JIT_N0	P 116
7E9	JIT_NH - Negative Peak Jitter Measurement High-Byte Regis- ter	-	-	-	-	JIT_N11	JIT_N10	JIT_N9	JIT_N8	P 116

# 5.2 REGISTER DESCRIPTION

#### 5.2.1 GLOBAL REGISTER

#### ID - Device ID Register

Type:	ess: 000H Read It Value: 20	Н							
	7	6	5	4	3	2	1	0	
	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0	
	Bit	Name			Descri	ption			
	7 - 0	ID[7:0]	The ID[7:0] bits are pr version number ('0000	e-set. The ID[7:4] bits i' is for the first version)		e ID for the IDT82P2	2521. The ID[3:0] bit	ts represent the c	urrent

#### **RST - Global Reset Register**

Type:	ess: 040H : Write ult Value: 00I	Н								
	7	6	5	4	3	2	1	0		
	RST7	RST6	RST5	RST4	RST3	RST2	RST1	RST0		
	Bit Name Description									
	7 - 0	RST[7:0]	Writing this register will ir	iting this register will initiate global software reset. This reset completes in 1 μs maximum.						

## GCF - Global Configuration Register

7	6	5	4	3	2	1	0
-	•	•	COPY	INT_PIN1	INT_PIN0	GLB_IM	TMOV_IM
Bit	Name			Descri	ption		
7 - 5	-	Reserved.					
4	COPY	When the per-channel re ister of the other channel 0: Disable. (default) 1: Enable.		ei is written, this dit c	jetermines whether tr	ie written value is c	copied to the same
3 - 2	INT_PIN[1:0]	These two bits control the X0: Open drain, active lo 01: Push-pull, active low. 11: Push-pull, active high	w. (default)	pin.			
1	GLB_IM	This bit is a global config 0: The per-channel interr tus bit is '1'. 1: Mask all the per-chanr	upt will be generate	ed when the per-chan			esponding interrup
0	TMOV_IM	This bit controls whether 0: Enable. 1: Mask. (default)	the interrupt is gene	erated when one sec	ond time is over. This	one second timer	is locked to MCLK

## MON - G.772 Monitor Configuration Register

7	6	5	4	3	2	1	0
-	•	MON5	MON4	MON3	MON2	MON1	MON0
Bit	Name			Descrip	ption		
7 - 6	-	Reserved.					
		000000: No transmitter o 000001: The receiver of o 000010: The receiver of o 010100: The receiver of o 010110 ~ 011111: Reserv 100000: No transmitter o 100001: The transmitter o 100010: The transmitter o 110100: The transmitter o 110101: The transmitter o	channel 1 is monitor channel 2 is monitor channel 20 is monitor channel 21 is monitor ed. r receiver is monitor of channel 1 is mon of channel 2 is mon	red. pored. pored. red. itored. itored.			

#### GPIO - General Purpose I/O Pin Definition Register

7 - 4       -       Reserved.         3       LEVEL1       When the GPIO1 pin is defined as output, this bit determin 0: Output low level. (1: Output high level. (default) When the GPIO1 pin is defined as input, this bit indicates 0: Input low level. 1: Input low level. 1: Input high level. (default)         2       LEVEL0       When the GPIO0 pin is defined as output, this bit determined as output, this bit determine	Description es the output level on GF	
7 - 4       -       Reserved.         3       LEVEL1       When the GPIO1 pin is defined as output, this bit determin 0: Output low level. 1: Output high level. (default)         When the GPIO1 pin is defined as input, this bit indicates 1: Output low level. 1: Input low level. 1: Input high level. (default)         2       LEVEL0	es the output level on GF	
3       LEVEL1       When the GPIO1 pin is defined as output, this bit determin         0: Output low level.       1: Output high level. (default)         When the GPIO1 pin is defined as input, this bit indicates to 0: Input low level.         1: Input high level. (default)         2       LEVEL0		
0: Output low level.         1: Output high level. (default)         When the GPIO1 pin is defined as input, this bit indicates 0: Input low level.         1: Input high level. (default)         2       LEVEL0		
0: Output low level. 1: Output high level. When the GPIO0 pin is defined as input, this bit indicates 0: Input low level. 1: Input high level. (default)		
1 DIR1 This bit determines whether the GPIO1 pin is used as outp 0: Output. 1: Input. (default)	ut or input.	

## CLKG - CLKE1 Generation Control Register

ddress: 1C0H ype: Read / Wr efault Value: 0											
7	6	5		4	3		2		1	0	
·	-			-	-		-		-	-	
Bit	Name				De	scription	1				
7 - 4	-	Reserved.									
3	CLKE1_EN	This bit controls when 0: The output is disa 1: The output is ena	abled. CLk	KE1 is in High-Z	state.		e CLKE1 bit (	b2, CLKG	). (default)		
2	CLKE1	This bit is valid only 0: 8 KHz. 1: 2.048 MHz. (defa		CLKE1_EN bit	(b3, CLKG) is '	1'. This bi	t selects the c	lock freque	ency output	on the CLK	(E1 pin.
1	-	Reserved.									
0	-	Reserved.									

# **REFCF - REFA/B Output Configuration Register**

7	6		5	4		3	2	1	0	
-	JA_BYF	PAS	REFH	FS_BYPAS	FI	REE	FREQ2	FREQ1	FREQ0	
Bit	Name					Descrip	tion			
7	-	Rese	erved.							
6	JA_BYPAS	ing re 0: Th	bit is valid only when th eceiver. This bit determ he selected recovered on he selected recovered of	n the RJA.						
5	REFH	For F wher sourd For F 0: Ou 1: Ou	bit is valid only when the REFA, this bit, together in the selected clock so ce is CLKA. Refer to the REFB: utput free running clock utput high level. (defaul	r with the FS_l purce is the re e related table a. The frequence t)	BYPAS bit (b covered cloc in the descri cy is 2.048 M	94, REFCF) sk of one of ption of the Hz.	and the FREE bit the 22 channels; FREE bit (b3, REF	(b3, REFCF), contro this bit is ignored w CF).	then the selected	
4	FS_BYPAS		This bit determines whether the selected clock source for REFA passes through an internal Frequency Synthesizer. 0: The internal Frequency Synthesizer is enabled. 1: The internal Frequency Synthesizer is bypassed. (default)							
3	FREE	1: Th This In no	he internal Frequency S bit is valid only when the rmal operation:	Synthesizer is the selected clo	oypassed. (de ick source for	r REFA pass				
3	FREE	1: This This In no 0: Ou REF 1: Ou Whe	the internal Frequency S bit is valid only when the ormal operation: utput the clock which is CF). (default) utput free running clock in the selected clock so rols the output on REF/ Selected Clock	Synthesizer is the selected close locked to the subject to the subject to the subject is locked to the burce is lost, the subject is lost, the subject is lost at the subject to the subje	oypassed. (de ck source for selected clo ed to MCLK a nis bit, togeth	r REFA pass ck source a and the frequ her with the	nd the frequency is uency is programm	e programmed in the ed in the FREQ[2:0] , REFCF) and the	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, RI	
3	FREE	1: This This In no 0: Ou REF 1: Ou Whe	he internal Frequency S bit is valid only when the ormal operation: utput the clock which is CF). (default) utput free running clock in the selected clock so rols the output on REFA	Synthesizer is the selected clo s locked to the which is locked burce is lost, the	bypassed. (de ick source for selected clo ed to MCLK a	r REFA pass ck source a and the frequ	nd the frequency is uency is programm	programmed in the ed in the FREQ[2:0]	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, RI	
3	FREE	1: Th This In no 0: Ou REF 1: Ou Whe	the internal Frequency S bit is valid only when the ormal operation: utput the clock which is CF). (default) utput free running clock in the selected clock so rols the output on REF/ Selected Clock	Synthesizer is the selected close locked to the subject to the subject to the subject is locked to the burce is lost, the subject is lost, the subject is lost at the subject to the subje	oypassed. (de ck source for selected clo ed to MCLK a nis bit, togeth	r REFA pass ck source a and the frequ her with the <b>REFH</b>	nd the frequency is uency is programm	e programmed in the ed in the FREQ[2:0] , REFCF) and the	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, RI	
3	FREE	1: Th This In no 0: Ou REF 1: Ou Whe	the internal Frequency S bit is valid only when the ormal operation: utput the clock which is CF). (default) utput free running clock in the selected clock so rols the output on REF/ Selected Clock	Synthesizer is the selected close locked to the subject to the subject to the subject is locked to the burce is lost, the subject is lost, the subject is lost at the subject to the subje	pypassed. (de ck source for selected clo ed to MCLK a his bit, togeth FREE	r REFA pass ck source a and the frequ her with the	nd the frequency is uency is programm FS_BYPAS bit (b4 High level. Free running clo	e programmed in the ed in the FREQ[2:0] , REFCF) and the	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, RI	
3	FREE	1: Th This In no 0: Ou REF 1: Ou Whe	he internal Frequency S bit is valid only when the ormal operation: utput the clock which is CF). (default) utput free running clock on the selected clock so rols the output on REF/ Selected Clock Source	Synthesizer is the selected close locked to the subject to the sub	pypassed. (de ck source for selected clo ed to MCLK a nis bit, togeth FREE 0 1	r REFA pass ck source a and the frequ her with the <b>REFH</b> (don't-	nd the frequency is uency is programm FS_BYPAS bit (b4 High level. Free running clo	ed in the FREQ[2:0] , REFCF) and the <b>Output On REFA</b>	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, RI	
3	FREE	1: Th This In no 0: Ou REF 1: Ou Whe	he internal Frequency S bit is valid only when the ormal operation: utput the clock which is CF). (default) utput free running clock on the selected clock so rols the output on REF/ Selected Clock Source	ynthesizer is t he selected clo s locked to the which is locked burce is lost, th A: FS_BYPA S 0	pypassed. (de ck source for selected clo ed to MCLK a nis bit, togeth FREE 0 1	r REFA pass ck source a and the frequ her with the <b>REFH</b> (don't- care)	nd the frequency is uency is programm FS_BYPAS bit (b4 High level. Free running clo in the FREQ[2:0] High level. Free running clo	ed in the FREQ[2:0] , REFCF) and the <b>Output On REFA</b>	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, Ri cy is programme :).	
3	FREE	1: Th This In no 0: Ou REF 1: Ou Whe	the internal Frequency S bit is valid only when the formal operation: utput the clock which is CF). (default) utput free running clock of the selected clock so rols the output on REF/ Selected Clock Source CLKA	ynthesizer is t he selected clo s locked to the which is locked burce is lost, th A: FS_BYPA S 0	oypassed. (de ck source for selected clo ed to MCLK a nis bit, togeth FREE 0 1 (don't	r REFA pass ck source a and the frequ ner with the <b>REFH</b> (don't- care) -care)	nd the frequency is uency is programm FS_BYPAS bit (b4 High level. Free running clo in the FREQ[2:0] High level. Free running clo	b programmed in the ed in the FREQ[2:0] b, REFCF) and the <b>Output On REFA</b> ock, whose frequen bits (b2~0, REFCF	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, RI cy is programme :).	
3	FREE	1: Th This In no 0: Ou REF 1: Ou Whe	he internal Frequency S bit is valid only when the ormal operation: utput the clock which is CF). (default) utput free running clock on the selected clock so rols the output on REF/ Selected Clock Source	ynthesizer is t he selected clo s locked to the s which is locked purce is lost, th FS_BYPA S 0 1	oypassed. (de ck source for selected clo ed to MCLK a nis bit, togeth FREE 0 1 (don't	r REFA pass ck source a and the frequ ner with the <b>REFH</b> (don't- care) -care) 0	hd the frequency is Jency is programm FS_BYPAS bit (b4 High level. Free running clc in the FREQ[2:0] High level. Free running clc in the FREQ[2:0] High level. Free running clc	b programmed in the ed in the FREQ[2:0] b, REFCF) and the <b>Output On REFA</b> ock, whose frequen bits (b2~0, REFCF	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, RI cy is programme cy is programme cy is programme cy is programme	
3	FREE	1: Th This In no 0: Ou REF 1: Ou Whe	he internal Frequency S bit is valid only when the formal operation: utput the clock which is CF). (default) utput free running clock in the selected clock sc rols the output on REF/ Selected Clock Source CLKA Recovered clock of one of the 22 chan-	ynthesizer is t he selected clo s locked to the s which is locked purce is lost, th FS_BYPA S 0 1	oypassed. (de ck source for selected clo ed to MCLK a nis bit, togeth FREE 0 1 (don't 0	r REFA pass ck source a and the frequ ner with the <b>REFH</b> (don't- care) 0 1 (don't-	nd the frequency is Jency is programm FS_BYPAS bit (b4 High level. Free running clo in the FREQ[2:0] High level. Free running clo in the FREQ[2:0] High level. Free running clo in the FREQ[2:0]	b programmed in the ed in the FREQ[2:0] b, REFCF) and the <b>Output On REFA</b> ock, whose frequen bits (b2~0, REFCF ock, whose frequen bits (b2~0, REFCF	e FREQ[2:0] bits   bits (b2~0, REF REFH bit (b5, RI cy is programme -). cy is programme -). cy is programme -).	

# 21(+1) CHANNEL HIGH-DENSITY E1 LINE INTERFACE UNIT

FREQ[2:0]	Output when FS_BYPAS=0, FREE=0 and the Frequency Synthesizer uses RCLKn or CLKA as reference clock	Output when FS_BYPAS=0 and FREE=1 (the Frequency Synthesizer is free runnin
000	2.048 MHz	-
0 0 1	8 kHz	8 kHz
010	64 kHz	64 kHz
011	Reserved	-
100	4.096 MHz	4.096 MHz
101	8.192 MHz	8.192 MHz
1 1 0	19.44 MHz	19.44 MHz
111	32.768 MHz	32.768 MHz

ENESAS

IDT82P2521

## **REFA - REFA Clock Sources Configuration Register**

7	6	5	4	3	2	1	0		
•	REFA_	N CKA_E1	REFA4	REFA3	REFA2	REFA1	REFA0		
Bit	Name			Descrip	otion				
7	-	Reserved.							
6	REFA_EN	0: The output is disabled.	This bit controls whether the output on the REFA pin is enabled. 0: The output is disabled. REFA is in High-Z state. 1: The output is enabled. (default)						
5	CKA_E1	This bit defines the input of 0: Reserved. (default) 1: Input E1 clock.							
4 - 0	REFA[4:0]	These bits select the clock 00000: Recovered clock of 00001: Recovered clock of 00010: Recovered clock of  10100: Recovered clock of 10101: Recovered clock of 10110 ~ 11111: The input	f channel 0. f channel 1. (defaul f channel 2. f channel 20. f channel 21.	t)					

## **REFB - REFB Clock Sources Configuration Register**

Address: 280H Type: Read / Write Default Value: 41H							
7	6	5	4	3	2	1	0
-	REFB_EN	CKB_E1	REFB4	REFB3	REFB2	REFB1	REFB0

Bit	Name	Description
7	-	Reserved.
6	REFB_EN	This bit controls whether the output on the REFB pin is enabled. 0: The output is disabled. REFB is in High-Z state. 1: The output is enabled. (default)
5	CKB_E1	This bit defines the input clock frequency on the CLKB pin. 0: Reserved. (default) 1: Input E1 clock.
4 - 0	REFB[4:0]	These bits select the clock source for REFB. 00000: Recovered clock of channel 0. 00001: Recovered clock of channel 1. (default) 00010: Recovered clock of channel 2.  10100: Recovered clock of channel 20. 10101: Recovered clock of channel 21. 10110 ~ 11111: The input on CLKB.

#### **INTCH1 - Interrupt Requisition Source Register 1**

Address: 2 Type: Rea Default Va	ad / Write								
	7	6	5	4	3	2	1	0	
INT	NT_CH8 INT_CH7 INT_CH6 INT_CH5 INT_CH4 INT_CH3 INT_CH2							INT_CH1	
Bit		Name			Descri	iption			
7 - 0	)	INT_CH[8:1]	These bits indicate whether there is an interrupt generated in the corresponding channel. The INT_CH[8:1] bits correspond to channel 8 to 1 respectively. 0: No interrupt is generated or all the interrupts are cleared in the corresponding channel. (default) 1: At least one interrupt is generated in the corresponding channel.						

#### INTCH2 - Interrupt Requisition Source Register 2

Address: 300 Type: Read / Default Value:	Vrite								
7	6	5	4	3	2	1	0		
INT_CH	INT_CH16 INT_CH15 INT_CH14 INT_CH13 INT_CH12 INT_CH11 INT_CH10								
Bit	Name			Descrip	otion				
7 - 0	INT_CH[16:9]	channel 16 to 9 respective 0: No interrupt is generate	hese bits indicate whether there is an interrupt generated in the corresponding channel. The INT_CH[16:9] bits correspond to hannel 16 to 9 respectively. No interrupt is generated or all the interrupts are cleared in the corresponding channel. (default) : At least one interrupt is generated in the corresponding channel.						

## INTCH3 - Interrupt Requisition Source Register 3

Address: 340H Type: Read / W Default Value: (	/rite						
7	6	5	4	3	2	1	0
·	•	·	INT_CH21	INT_CH20	INT_CH19	INT_CH18	INT_CH17
Bit	Name			Descri	ption		
7 - 5	-	Reserved.					
4 - 0	INT_CH[21:17]	These bits indicate whet channel 21 to 17 respec 0: No interrupt is genera 1: At least one interrupt i	ively. ted or all the interrupt	s are cleared in the	corresponding chan	-	1:17] bits correspond to

#### **INTCH4 - Interrupt Requisition Source Register 4**

Address: 38 Type: Read Default Valu	/ Write									
7	,	6		5	4	3	2	1	0	
INT_	CH0	-		-		•				
Bit		Name				Descr	iption			
7		INT_CH0	0: No inter	nis bit indicates whether there is an interrupt generated in channel 0. No interrupt is generated or all the interrupts are cleared in channel 0. (default) At least one interrupt is generated in channel 0.						
6 - 0		-	Reserved							

#### INTTM - One Second Timer Interrupt Status Register

Address: 3C0H Type: Read / W Default Value: 0	/rite									
7	6	5	4	3	2	1	0			
-	-	•	·		•	·	TMOV_IS			
Bit	Name			Descrip	otion					
7 - 1	-	Reserved.								
0	TMOV_IS	0: No one second tim	This bit is valid only when the TMOV_IM bit (b0, GCF) is '0'. This bit indicates the interrupt status of one second time over. D: No one second time over interrupt is generated; or a '1' is written to this bit. (default) : One second time over interrupt is generated and is reported by the INT pin.							

#### 5.2.2 PER-CHANNEL REGISTER

#### **CHCF - Channel Configuration Register**

Address: 001H,	041H, 081H, 0C1	H, 101H, 141H, 181H, 1C1	H, (CH1~CH8)				
201H,	241H, 281H, 2C1	H, 301H, 341H, 381H, 3C1	H, (CH9~CH16)				
401H,	441H, 481H, 4C1	H, 501H, <i>(CH17~CH21)</i>					
7C1H	(CH0)						
Type: Read / Wr	ite						
Default Value: 0	0H						
7	6	5	4	3	2	1	0
	_	_				OUDOT	
· ·				-	-	CHRST	· ·
Bit	Name			Desc	ription		
7 - 2	-	Reserved.					
1	CHRST	Writing a '1' to this bit wil	I initiate per-channe	l software reset. O	nce initiated, per-cha	innel software reset c	completes in 1 µs maxi
		mum.					
		This bit is self cleared.					
0	-	Reserved.					
L	1						

## TJA - Transmit Jitter Attenuation Configuration Register

7	6	5	4	3	2	1	0
-			TJA_LIMT	TJA_EN	TJA_DP1	TJA_DP0	TJA_BW
Bit	Name			Descri	ption		
7 - 5	-	Reserved.					
4	TJA_LIMT	0: Disable. (default)	ether the JA-Limit funct			O in the TJA is 2-bit	close to its full
3	TJA_EN	This bit controls wheth 0: Disable. (default) 1: Enable.	er the TJA is enabled to	o use.			
2 - 1	TJA_DP[1:0]	These bits select the c 00: 128-bit. (default) 01: 64-bit. 1X: 32-bit.	epth of the TJA FIFO.				
0	TJA_BW		mer Frequency for the	TJA.			

## RJA - Receive Jitter Attenuation Configuration Register

7	6	5	4		2	1	0
-	· ·			3	2	1	U
		· ·	RJA_LIMT	RJA_EN	RJA_DP1	RJA_DP0	RJA_BW
Bit	Name			Descri	ption		
- 5	- Reserved.						
4	RJA_LIMT	This bit determines whe 0: Disable. (default) 1: Enable. The speed of emptiness.				FIFO in the RJA is	2-bit close to i
3	RJA_EN	This bit controls whethe 0: Disable. (default) 1: Enable.	er the RJA is enabled to	o use.			
- 1	RJA_DP[1:0]	These bits select the de 00: 128-bit. (default) 01: 64-bit. 1X: 32-bit.	epth of the RJA FIFO.				

# TCF0 - Transmit Configuration Register 0

204H, 2	244H, 284H, 2C4F 444H, 484H, 4C4F ( <i>CH0</i> ) ite	н, 104Н, 144Н, 184Н, 1С Н, 304Н, 344Н, 384Н, 3С Н, 504Н, <i>(CH17~CH21)</i> 5	.,	3	2	1	0			
· .	OE	T_OFF	THZ_OC	T_SING	T_TERM2	T_TERM1	T_TERM0			
Bit	Name			Descri	iption					
7	-	Reserved.								
6	OE	This bit determines the 0: High-Z. (default) 1: Normal operation.								
5	T_OFF		This bit determines whether the transmitter is powered down. 0: Normal operation. (default) 1: Power down.							
4	THZ_OC	This bit determines the 0: The output current is 1: The output current is when the TOC is detect	limited to 100 mAp-p limited to 100 mAp-p	(default) within the first 1 ms		·				
3	T_SING	This bit determines the 0: Transmit Differential 1: Transmit Single Ende	ine interface. Both TT ed line interface. Only	IPn and TRINGn ar TTIPn is used to tra	ansmit signal. TRING	n should be left ope				
2 - 0	T_TERM[2:0]	These bits select the im 010: The 120 $\Omega$ internal 011: The 75 $\Omega$ internal 110: The 120 $\Omega$ interna 111: The external imped Others: Reserved	I impedance matching impedance matching I impedance matching	g is selected for E1 is selected for E1 7 g is selected for E1 7	120 Ω twisted pair ca 5 Ω coaxial cable (wi 120 Ω twisted pair ca	ble (with transforme th transformer). ble (transformer-les	s).			

# TCF1 - Transmit Configuration Register 1

205H, 2 405H, 4 7C5H ( Type: Read / Wri Default Value: 01	245H, 285H, 2C5H 145H, 485H, 4C5H <i>CH0)</i> te H	I, 105H, 145H, 185H, 1C5I I, 305H, 345H, 385H, 3C5I I, 505H, <i>(CH17~CH21)</i>	н, (СН9~СН1́6)	2	2	4	0
7	6	5	4	3	2	1	0
TMF_DEF2	2 TMF_DE	F1 TMF_DEF0	TCK_ES	TD_INV	T_CODE	T_MD1	T_MD0
Bit	Name			Descrip	otion		
7 - 5	TMF_DEF[2:0]	These bits are valid only i indication on the TMFn pi 000: PRBS/ARB indicatio detection is switched to th 001: SAIS indication. 010: TOC indication. 011: TLOS indication. 100: SEXZ indication. 101: SBPV indication in T 110: SEXZ + SBPV indica 111: SLOS indication in T	n. n when the PRBS// ie receive path. (def ransmit Dual Rail R ation in Transmit Dua ransmit Dual Rail R2	ARB detection is swi ault) Z Format mode. Res al Rail RZ Format mo Z Format mode. Res	itched to the transm served in Transmit Si ode. Reserved in Tra	it path. Or reserved ingle Rail NRZ Form ansmit Single Rail N	d when the PRBS/ARB nat mode. RZ Format mode.
4	TCK_ES	This bit selects the active 0: Falling edge. (default) 1: Rising edge.	edge of the TCLKn	pin.			
3	TD_INV	This bit determines the ac 0: Active high. (default) 1: Active low.			pins.		
2	T_CODE	This bit selects the line co 0: HDB3. (default) 1: AMI.					
1 - 0	T_MD[1:0]	These bits determines the 00: Transmit Single Rail N TCLKn. 01: Transmit Dual Rail NF is input on TCLKn. (defau 10: Transmit Dual Rail R2 11: Reserved.	IRZ Format system RZ Format system in It)	interface. The data is terface. The data is i	nput on TDPn and T	DNn in NRZ format	

## PULS - Transmit Pulse Configuration Register

Type: Read / Wi Default Value: 0		5		4	3	2	1	0
•	·	•			PULS3	PULS2	PULS1	PULSO
Bit	Name				Descri	ption		
7 - 4 3 - 0	PULS[3:0]	Reserved. These bits select of waveform.	one of the eight p	preset waveform	templates for	r short haul application	or enable user-pr	ogrammable arbitra
		PULS[3:0]	Operation Mode	Transmit Clock	Ca	able Impedance	Cable Range	e Cable Loss
		0000	E1	2.048 MHz		D differential interface, pedance matching mode	-	0 ~ 12 dB
		0001	E1	2.048 MHz	Ot	her E1 interfaces	-	0 ~ 12 dB
		1XXX			User-progran	nmable arbitrary wavefor	m	
		others				Reserved.		

## SCAL - Amplitude Scaling Control Register

207H,	247H, 287H, 2C7H 447H, 487H, 4C7H <i>(CH0)</i> rite	I, 107H, 147H, 187H, 1C7 I, 307H, 347H, 387H, 3C7I I, 507H, <i>(CH17~CH21)</i>	. ,				
7	6	5	4	3	2	1	0
· ·	-	SCAL5	SCAL4	SCAL3	SCAL2	SCAL1	SCAL0
Bit	Name			Descrip	otion		
7 - 6	-	Reserved.					
5 - 0	SCAL[5:0]	These bits specify a scali The standard value is '10 will result in 3% scaling u <b>Note:</b> The default value f	0001' for the wavefo p or down against th	rm amplitude. If nec	essary, increasing o de. The scale range	r decreasing by '1' f is from +100% to -	100%.

## AWG0 - Arbitrary Waveform Generation Control Register 0

208H,	248H, 288H, 2C8H, 448H, 488H, 4C8H, ( <i>CH0)</i> ite	, 108H, 148H, 188H, 1C8 , 308H, 348H, 388H, 3C8 , 508H, <i>(CH17~CH21)</i>							
7	6	5	4	3	2	1	0		
	DONE	RW	SAMP4	SAMP3	SAMP2	SAMP1	SAMP0		
Bit	Name			Descrip	otion				
7	-	Reserved.							
6									
5		This bit is valid only when to '1XXX'). This bit deten 0: Write data to RAM. (de 1: Read data from RAM.	mines read/write dire		orm is enabled (i.e., t	the PULS[3:0] bits (	(b3~0, PULS,) are		
4 - 0		These bits are valid only are set to '1XXX'). These 00000: The RAM sample 00001: The RAM sample 00010: The RAM sample  10001: The RAM sample 10010: The RAM sample 10011 ~ 11111: The RAM	bits specify the RAM address is 0. (defau address is 1. address is 2. address is 17. address is 18.	I sample address. It)	waveform is enabled	d (i.e., the PULS[3:	0] bits (b3~0, PUL		

## AWG1 - Arbitrary Waveform Generation Control Register 1

209H,	249H, 289H, 2C9H 449H, 489H, 4C9H <i>(CH0)</i> ite	, 109Н, 149Н, 189Н, 1С9 , 309Н, 349Н, 389Н, 3С9 , 509Н, <i>(СН17~СН21)</i>	· ( )				
7	6	5	4	3	2	1	0
·	WDATE	WDAT5	WDAT4	WDAT3	WDAT2	WDAT1	WDAT0
Bit	Name			Descri	ption		
7	-	Reserved.					
6 - 0	WDAT[6:0]	These bits are valid only are set to '1XXX'). These bits contain the t AWG0,). They are not	emplate sample data	a to be stored in R	AM which address		,

## **RCF0 - Receive Configuration Register 0**

20AH, 1	24AH, 28AH, 2CA 44AH, 48AH, 4CA ( <i>CH0)</i> ite	н, 10ан, 14ан, 18ан, 1 н, 30ан, 34ан, 38ан, 3 н, 50ан, <i>(СН17~СН21)</i>					
7	6	5	4	3	2	1	0
RCKH	RHZ	R_OFF	R120IN	R_SING	R_TERM2	R_TERM1	R_TERM0
Bit	Name			Descri	ption		
7	RCKH	pattern generation is di 0: XCLK. (default) 1: High level.	sabled in the receive p	oath.			ected and the AIS and
6	RHZ	corresponding receiver 0: Low level. 1: High-Z. (default)	is powered down.		ns (including RDn, R	RDPn, RDNn, RMFn	and RCLKn) when the
5	R_OFF	This bit determines who 0: Normal operation. (d 1: Power down.		owered down.			
4	R120IN	configuration is enable	d. This bit selects the i bedance Matching mo	nternal impedance n de. An internal prog	natching mode. Irammable resistor (I	M) and a value-fixed	al impedance matching d external resistor (Rr)
3	R_SING	This bit determines the 0: Receive Differential 1: Receive Single Ende	ine interface. Both RT				
2 - 0	R_TERM[2:0]	These bits are valid o matching mode of the r In Receive Differential 010: The 120 $\Omega$ internal 011: The 75 $\Omega$ internal 1XX: External impedan In Receive Single End (default) Others: Reserved.	eceive path to match to node: Il impedance matching impedance matching ce matching is selecte	the cable impedance g is selected for E1 1 is selected for E1 75 ed for E1 120 $\Omega$ twis	20 Ω twisted pair ca 0 Ω coaxial cable. ted pair cable and E	able. 1 75 $\Omega$ coaxial cable	

## **RCF1 - Receive Configuration Register 1**

20BH,	24BH, 28BH, 2CB 44BH, 48BH, 4CB <i>(CH0)</i> ite	H, 10BH, 14BH, 18BH, 1C H, 30BH, 34BH, 38BH, 3C H, 50BH, <i>(CH17~CH21)</i>								
7	6	5	4	3	2	1	0			
RMF_DEF	2 RMF_DE	F1 RMF_DEF0	RCK_ES	RD_INV	R_CODE	R_MD1	R_MD0			
Bit	Name			Descri	ption					
7 - 5	RMF_DEF[2:0]	put on the RMFn pin. 000: PRBS/ARB indication detection is switched to the 001: LAIS indication. 010: XOR data of positive 011: Recovered clock (Re 100: LEXZ indication. 101: LBPV indication.	<ul> <li>00: PRBS/ARB indication when the PRBS/ARB detection is switched to the receive path. Or reserved when the PRBS/ etection is switched to the transmit path. (default)</li> <li>01: LAIS indication.</li> <li>10: XOR data of positive and negative sliced data.</li> <li>11: Recovered clock (RCLK).</li> <li>00: LEXZ indication.</li> <li>01: LBPV indication.</li> <li>10: LEXZ + LBPV indication.</li> </ul>							
4	RCK_ES	This bit selects the active 0: Rising edge. (default) 1: Falling edge.	edge of the RCLKn	pin.						
3	RD_INV	This bit determines the a 0: Active high. (default) 1: Active low.	ctive level on the RD	n, RDPn and RDNn	n pins.					
2	R_CODE	This bit selects the line c 0: HDB3. (default) 1: AMI.	ode rule for the recei	ive path.						
1 - 0	R_MD[1:0]	These bits determines th 00: Receive Single Rail clock is output on RCLKr 01: Receive Dual Rail N recovered clock is output 10: Receive Dual Rail RZ ered clock is output on R 11: Receive Dual Rail Sli the Slicer.	NRZ Format system RZ Format system in on RCLKn. (default) Format system inte CLKn.	interface. The data nterface. The data is ) rface. The data is ou	s output on RDPn a utput on RDPn and I	nd RDNn in NRZ fo RDNn in RZ format a	ormat and a 2.048 MHz and a 2.048 MHz recov-			

## RCF2 - Receive Configuration Register 2

20CH,	24CH, 28CH, 2C 44CH, 48CH, 4C <i>(CH0)</i> ite	СН, 10СН, 14СН, 18СН, 1С СН, 30СН, 34СН, 38СН, 3С СН, 50СН, <i>(СН17~СН21)</i>					
7	6	5	4	3	2	1	0
·	•		•	•	•	MG1	MG0
Bit	Name			Descrip	otion		
7 - 2	-	Reserved.					
1 - 0	MG[1:0]	These bits select the Mon 00: 0 dB. (default) 01: 20 dB. 10: 26 dB.	itor Gain.				

## LOS - LOS Configuration Register

7	6		5	4	3	2	1	0
LAC	ALOS	2 A	LOS1	ALOS0	TALOS1	TALOS0	TDLOS1	TDLOS0
<b>-</b>		1			-			
Bit 7	Name LAC	This hit soloo	ta tha LLOS	, SLOS and AIS c		cription		
I	LAC	0: G.775. (de 1: ETSI 3002	fault)	, 3203 and AI3 d	itena.			
6 - 4	ALOS[2:0]	vals, LLOS is	declared. T 0] settings f	he consecutive pu	Ise intervals (N) and mode and Line M	litude of the data is less re determined by the LA onitor mode are differer <b>re Mode</b>	C bit (b7, LOS,).	
				ALOS[2:0]	Q (Vpp)	vs. 6.0 Vpp (dB)	vs. 4.74 Vpp (dB)	
				000	0.5	21.58	19.54	-
			C	001 (default)	0.7	18.66	16.61	
				010	0.9	16.48	14.43	
				011	1.2	13.98	11.93	
				100	1.4	12.64	10.59	
				101	1.6	11.48	9.43	
				110	1.8	10.46	8.41	
				111	2.0	9.54	7.49	
			ALO	S[2:0] Setting ir	Line Monitor M	lode		
				ALOS[2:0]	Q (Vpp)	vs. 6.0 Vpp (dB)	vs. 4.74 Vpp (dB)	
				000	1.0	15.56	13.52	-
			(	001 (default)	1.4	12.64	10.59	-
				010	1.8	10.46	8.41	1
				011	2.2	8.71	6.67	
				1xx		reserved.		
3-2	TALOS[1:0]		e period is o red. al line interfa lefault) ided line inte	determined by the ace:		e of the data is less than ), LOS,). When the ar		

1 - 0	TDLOS[1:0]	These bits select the period. When the amplitude of the data is less than a certain voltage for the period, TLOS is declared. The voltage is determined by the TALOS bits (b3~2, LOS,).
		00: 16-pulse. 01: 32-pulse. (default) 1X: 64-pulse.

# ERR - Error Detection & Insertion Control Register

20EH, 40EH,	24EH, 28EH, 2CE 44EH, 48EH, 4CE <i>(CH0)</i> rite	H, 10EH, 14EH, 18EH, 1C H, 30EH, 34EH, 38EH, 3C H, 50EH, <i>(CH17~CH21)</i>							
7	6	5	4	3	2	1	0		
EXZ_DE	F BPV_IN	IS ERR_INS	ERR_INS     CNT_SEL2     CNT_SEL1     CNT_SEL0     CNT_MD     CNT_SEL1						
Bit	Name			Descri	ption				
7	EXZ_DEF	This bit selects the EXZ of 0: ANSI. (default) 1: FCC.	efinition standard.						
6	BPV_INS	Writing '1' to this bit will in	his bit controls whether to insert a bipolar violation (BPV) to the transmit path. Vriting '1' to this bit will insert a BPV on the next available mark in the data stream to be transmitted. his bit is cleared once the BPV insertion is completed.						
5	ERR_INS	This bit controls whether A transition from '0' to '1' This bit is cleared once th	on this bit will insert	a single bit error to	the generated PRBS				
4 - 2	CNT_SEL[2:0]	These bits select what kir 000: Disable. (default) 001: LBPV. 010: LEXZ. 011: LBPV + LEXZ. 100: SBPV. 101: SEXZ. 110: SBPV + SEXZ. 111: PRBS/ARB error.	: LBPV. : LEXZ. : LBPV + LEXZ. : SBPV. : SEXZ. : SBPV + SEXZ.						
1	CNT_MD	This bit determines wheth 0: Manually by setting the 1: Every-one second auto	CNT_STOP bit (b0		updated automaticall	y or manually.			
0	CNT_STOP	This bit is valid only wher A transition from '0' to '1' This bit must be cleared b	on this bit updates t	he ERRCH & ERRC	CL registers.				

## AISG - AIS Generation Control Register

20FH,	24FH, 28FH, 2CFI 44FH, 48FH, 4CFI <i>(CH0)</i> ite	H, 10FH, 14FH, 18FH, 1CH H, 30FH, 34FH, 38FH, 3CH H, 50FH, <i>(CH17~CH21)</i>								
7	6	5	4	3	2	1	0			
-	•	·	·	ASAIS_SLOS	ASAIS_LLOS	ALAIS_SLOS	ALAIS_LLOS			
Bit	Name		Description							
7 - 4	-	Reserved.								
3	ASAIS_SLOS	This bit controls the AIS ( 0: Disable. (default) 1: Enable.	generation in the rec	eive path once SLO	S is detected.					
2	ASAIS_LLOS	This bit controls the AIS ( 0: Disable. (default) 1: Enable.	generation in the rec	eive path once LLO	S is detected.					
1	ALAIS_SLOS	This bit controls the AIS ( 0: Disable. (default) 1: Enable.	bit controls the AIS generation in the transmit path once SLOS is detected. sable. (default)							
0	ALAIS_LLOS	This bit controls the AIS ( 0: Disable. (default) 1: Enable.	generation in the trai	nsmit path once LLC	OS is detected.					

## PG - Pattern Generation Control Register

Address: 010H, 050H, 090H, 0D0H, 110H, 150H, 190H, 1D0H, ( <i>CH1~CH8</i> ) 210H, 250H, 290H, 2D0H, 310H, 350H, 390H, 3D0H, ( <i>CH9~CH16</i> ) 410H, 450H, 490H, 4D0H, 510H, ( <i>CH17~CH21</i> ) 7D0H ( <i>CH0</i> ) Type: Read / Write Default Value: 00H												
7	6 5 4 3 2 1 0											
-	- PG_CK PG_EN1 PG_EN0 PG_POS PAG_INV PRBG_SEL1 PRBG_SEL0											
Bit	Name			Descrip	ption							
7	-	Reserved.										
6	PG_CK PG_EN[1:0]	This bit selects the refere When the pattern is gene 0: XCLK. (default) 1: Recovered clock from t When the pattern is gene 0: XCLK. (default) 1: Transmit clock, i.e., the mat mode) or the clock re These bits select the patt	rated in the receive the received signal. rated in the transmi e clock input on TCI ecovered from the da	path: t path: LKn (in Transmit Sing ata input on TDPn an	gle Rail NRZ Forma	t mode and in Trans						
		00: Disable. (default) 01: PRBS. 10: ARB. 11: IB.	·									
3	PG_POS	This bit selects the patter 0: Transmit path. (default 1: Receive path.	)	, .								
	2 PAG_INV This bit controls whether to invert the generated PRBS/ARB pattern. 0: Normal. (default) 1: Invert.											
1 - 0	PRBG_SEL[1:0]	These bits are valid only 00: 2 <sup>20</sup> - 1 QRSS. (defaul 01: 2 <sup>15</sup> - 1 PRBS. 1X: 2 <sup>11</sup> - 1 PRBS.		tern is generated. Th	ey select the PRBS	pattern.						

## PD - Pattern Detection Control Register

211H, 2	251H, 291H, 2D1H 451H, 491H, 4D11I <i>(CH0)</i> ite	, 111Н, 151Н, 191Н, 1D1ŀ , 311Н, 351Н, 391Н, 3D1ŀ Н, 511Н, <i>(CH17~CH21)</i>									
7	6	5	4	3	2	1	0				
·	PD_POS PAD_INV PAD_SEL1 PAD_SEL0										
Bit	Name			Descrip	otion						
7 - 4	-	Reserved.									
3	PD_POS	This bit selects the patter 0: Receive path. (default) 1: Transmit path.		ARB & IB) detection	direction.						
2	PAD_INV	This bit controls whether 0: Normal. (default) 1: Invert.	to invert the data be	fore PRBS/ARB dete	ection.						
1 - 0	PAD_SEL[1:0]	These bits select the des 00: 2 <sup>20</sup> - 1 QRSS. 01: 2 <sup>15</sup> - 1 PRBS. 10: 2 <sup>11</sup> - 1 PRBS. 11: ARB. (default)	ired PRBS/ARB patt	ern to be detected.							

#### ARBL - Arbitrary Pattern Generation / Detection Low-Byte Register

212H, 2	252H, 292H, 2D2H 452H, 492H, 4D2H ( <i>CH0)</i> ite	I, 112H, 152H, 192H, 1D2 I, 312H, 352H, 392H, 3D2 I, 512H, <i>(CH17~CH21)</i>									
7	7 6 5 4 3 2 1 0										
ARB7	ARB6	ARB5	ARB4	ARB3	ARB2	ARB1	ARB0				
Bit	Bit Name Description										
7 - 0	ARB[7:0]	These bits, together with the ARB[23:8] bits, define the ARB pattern to be generated or detected. The ARB23 bit is the first bit to be generated or detected and the ARB0 bit is the last bit to be generated or detected.									

#### ARBM - Arbitrary Pattern Generation / Detection Middle-Byte Register

213H, 2 413H, 4 7D3H ( Type: Read / Wri	Address: 013H, 053H, 093H, 0D3H, 113H, 153H, 193H, 1D3H, <i>(CH1~CH8)</i> 213H, 253H, 293H, 2D3H, 313H, 353H, 393H, 3D3H, <i>(CH9~CH16)</i> 413H, 453H, 493H, 4D3H, 513H, <i>(CH17~CH21)</i> 7D3H <i>(CH0)</i> Type: Read / Write Default Value: 55H										
7	7 6 5 4 3 2 1 0										
ARB15	ARB14	ARB13	ARB12	ARB11	ARB10	ARB9	ARB8				
Bit	Bit Name Description										
7 - 0	ARB[15:8]	8] (Refer to the description of the ARBL register.)									

#### ARBH - Arbitrary Pattern Generation / Detection High-Byte Register

214H, 2	254H, 294H, 2D4H 154H, 494H, 4D4H C <i>H0)</i> te	, 114H, 154H, 194H, 1D4H , 314H, 354H, 394H, 3D4H , 514H, <i>(CH17~CH21)</i>									
7	7 6 5 4 3 2 1 0										
ARB23	ARB22	ARB21	ARB20	ARB19	ARB18	ARB17	ARB16				
<b>Bit</b>	Name ARB[23:16]	(Refer to the description o	f the ARBL register.)	Descri	ption						

## IBL - Inband Loopback Control Register

215H, 2	255H, 295H, 2D5H 155H, 495H, 4D5H C <i>H0)</i> te	H, 315H,	155H, 195H, 1D5H 355H, 395H, 3D5H <i>(CH17~CH21)</i>						
7	6		5	4	3	2	1	0	
-	-		IBGL1	IBGL0	IBAL1	IBAL0	IBDL1	IBDL0	
Bit	Name	1			Descrip	ation			
7 - 6	-	Reserv	red		Descrip				
5 - 4	IBGL[1:0]	These 1 00: 5-b 01: 6-b 10: 7-b	bits define the leng it long in the IBG[4 it long in the IBG[5 it long in the IBG[6	th of the valid IB ger :0] bits (b4~0, IBG, :0] bits (b5~0, IBG, :0] bits (b6~0, IBG, :0] bits (b6~0, IBG,	.). (default) .). .).	ammed in the IBG[7:	0] bits (b7~0, IBG,	.).	
3 - 2	<ul> <li>3 - 2</li> <li>IBAL[1:0] These bits define the length of the valid target activate IB detection code programmed in the IBA[7:0] bits (b7~0, IBDA,).</li> <li>00: 5-bit long in the IBA[4:0] bits (b4~0, IBDA,). (default)</li> <li>01: 6-bit long in the IBA[5:0] bits (b5~0, IBDA,).</li> <li>10: 7-bit long in the IBA[6:0] bits (b6~0, IBDA,).</li> <li>11: 8-bit long in the IBA[7:0] bits (b7~0, IBDA,).</li> </ul>								
1 - 0									

#### IBG - Inband Loopback Generation Code Definition Register

216H, 2	256H, 296H, 2D6H 156H, 496H, 4D6H C <i>H0)</i> te	, 116H, 156H, 196H, 1D6H , 316H, 356H, 396H, 3D6H , 516H, <i>(CH17~CH21)</i>	. (									
7	6 5 4 3 2 1 0											
IBG7	IBG6	IBG5	IBG5 IBG4 IBG3 IBG2 IBG1 IBG0									
Bit	Bit Name Description											
7 - 0	IBG[7:0]	he IBG[X:0] bits define the content of the IB generation code. The 'X' is determined by the IBGL[1:0] bits (b5~4, IBL,). The 3G0 bit is the last bit to be generated. The code is generated repeatedly until the IB generation is stopped.										

#### IBDA - Inband Loopback Detection Target Activate Code Definition Register

217H, 2	257H, 297H, 2D7H 157H, 497H, 4D7H CH0) te	I, 117H, 157H, 197H, 1D7H I, 317H, 357H, 397H, 3D7I I, 517H, <i>(CH17~CH21)</i>	· · · · ·								
7	7 6 5 4 3 2 1 0										
IBA7	IBA6	IBA5	IBA4	IBA3	IBA2	IBA1	IBA0				
<b>Bit</b>											
7-0	ייזאמו	IBL,). The IBA0 bit is th		•		is determined by th					

#### IBDD - Inband Loopback Detection Target Deactivate Code Definition Register

Address: 018H, 058H, 098H, 0D8H, 118H, 158H, 198H, 1D8H, ( <i>CH1~CH8</i> ) 218H, 258H, 298H, 2D8H, 318H, 358H, 398H, 3D8H, ( <i>CH9~CH16</i> ) 418H, 458H, 498H, 4D8H, 518H, ( <i>CH17~CH21</i> )											
7D8H <i>(CH0)</i> Type: Read / Write											
Default Value: 09	H										
7	7 6 5 4 3 2 1 0										
IBD7	IBD6	IBD5	IBD4	IBD3	IBD2	IBD1	IBD0				
Bit Name Description											
7 - 0	7 - 0 IBD[7:0] The IBD[X:0] bits define the content of the target deactivate IB detection code. The 'X' is determined by the IBDL[1:0] bits (b1~0 IBL,). The IBD0 bit is the last bit to be detected.										

## LOOP - Loopback Control Register

219H, 2	259H, 299H, 2D9H 459H, 499H, 4D9H ( <i>CH0)</i> ite	, 119H, 159H, 199H, 1D9H , 319H, 359H, 399H, 3D9H , 519H, ( <i>CH17~CH21)</i>					
7	6	5	4	3	2	1	0
-	•	·	-	AUTOLP	DLP	RLP	ALP
Bit	Name			Descript	tion		
7 - 4	-	Reserved.					
3	AUTOLP	This bit determines wheth 0: Automatic Digital/Remu 1: Automatic Digital/Remu vate IB code is detected the deactivate IB code is	ote Loopback is disa ote Loopback is enal in the transmit/receiv	bled. (default) bled. The correspond ve path for more than	ing channel will ent 15.1 sec.; and will r		
2	DLP	This bit controls whether 0: Disable. (default) 1: Enable.	Digital Loopback is e	enabled.			
1	RLP	This bit controls whether 0: Disable. (default) 1: Enable.	Remote Loopback is	enabled.			
0	ALP	This bit controls whether 0: Disable. (default) 1: Enable.	Analog Loopback is	enabled.			

## INTES - Interrupt Trigger Edges Select Register

21AH,	25AH, 29AH, 2DA 45AH, 49AH, 4DA <i>(CH0)</i> ite	H, 11AH, 15AH, 19AH, 1E H, 31AH, 35AH, 39AH, 3E H, 51AH, <i>(CH17~CH21)</i>										
7	6	6 5 4 3 2 1 0										
· ·	AIS_IE	ES PA_IES TOC_IES TCKLOS_IES TLOS_IES LOS_IES IB_IES										
Bit	Name			Descrip	otion							
7	-	Reserved.										
6	AIS_IES	0: A transition from '0' INTS1,) / the SAIS_IS 1: Any transition from '0 LAIS_IS bit (b6, INTS1,.	This bit selects the transition edge of the LAIS_S bit (b6, STAT1,) and the SAIS_S bit (b7, STAT1,). 0: A transition from '0' to '1' on the LAIS_S bit (b6, STAT1,) / the SAIS_S bit (b7, STAT1,) will set the LAIS_IS bit (b6, INTS1,) / the SAIS_IS bit (b7, INTS1,) to '1' respectively. (default) 1: Any transition from '0' to '1' or from '1' to '0' on the LAIS_S bit (b6, STAT1,) / the SAIS_S bit (b7, STAT1,) will set the LAIS_IS bit the LAIS_IS bit (b6, INTS1,) / the SAIS_IS bit (b7, INTS1,) to '1' respectively. (default)									
5	PA_IES	This bit selects the trans 0: A transition from '0' to 1: Any transition from '0'	'1' on the PA_S bit (1 to '1' or from '1' to '0	b5, STAT1,) will se ' on the PA_S bit (b5	t the PA_IS bit (b5, I 5, STAT1,) will set t							
4	TOC_IES	This bit selects the trans 0: A transition from '0' to 1: Any transition from '0'	'1' on the TOC_S bit to '1' or from '1' to '0	t (b4, STAT0,) will s ' on the TOC_S bit (I	set the TOC_IS bit (b4, STAT0,) will se							
3	TCKLOS_IES	This bit selects the trans 0: A transition from '0' to 1: Any transition from '0' '1'.	'1' on the TCKLOS_	S bit (b3, STAT0,)	will set the TCKLOS							
2	TLOS_IES	This bit selects the trans 0: A transition from '0' to 1: Any transition from '0'	'1' on the TLOS_S b to '1' or from '1' to '0	it (b2, STAT0,) will ' on the TLOS_S bit	set the TLOS_IS bit (b2, STAT0,) will s	et the TLOS_IS bit						
1	LOS_IES	LOS_IES       This bit selects the transition edge of the LLOS_S bit (b0, STAT0,) and the SLOS_S bit (b1, STAT0,).         0: A transition from '0' to '1' on the LLOS_S bit (b0, STAT0,) / the SLOS_S bit (b1, STAT0,) will set the LLOS_IS bit (b0, INTS0,) / the SLOS_IS bit (b1, INTS0,) to '1' respectively. (default)         1: Any transition from '0' to '1' or from '1' to '0' on the LLOS_S bit (b0, STAT0,) / the SLOS_S bit (b1, STAT0,) will set the LLOS_IS bit (b0, INTS0,) / the SLOS_IS bit (b1, INTS0,) / the SLOS_IS bit (b1, INTS0,) / the SLOS_IS bit (b1, STAT0,) will set the LLOS_IS bit (b0, INTS0,) / the SLOS_IS bit (b1, INTS0,) / thE SLOS_IS										
0	IB_IES	This bit selects the trans 0: A transition from '0' to the IBD_IS bit (b0, INTS 1: Any transition from '0' bit (b1, INTS1,) / the IE	'1' on the IBA_S bit 1,) to '1' respective to '1' or from '1' to '0	(b1, STAT1,) / the I ly. (default) ' on the IBA_S bit (b	IBD_S bit (b0, STAT 01, STAT1,) / the II	1,) will set the IBA	<b>, , , ,</b>					

## INTM0 - Interrupt Mask Register 0

	5BH, 29BH, 2DB 5BH, 49BH, 4DB C <i>H0)</i> e	H, 31BH, 35BH,	39BH, 3DBH, (CH								
7	6 5 4 3 2 1 0										
DAC_IM	TJA_IN	1 RJA	_IM T	OC_IM	TCKLOS_IM	TLOS_IM	SLOS_IM	LLOS_IM			
Bit	Name				Descri	iption					
7	DAC_IM	0: Interrupt is er	aveform amplitud nabled. lasked. (default)	le overflow ir	nterrupt mask.						
6	TJA_IM	0: Interrupt is er		/ and underfl	ow interrupt mask.						
5	RJA_IM	0: Interrupt is er		v and underfl	low interrupt mask.						
4	TOC_IM	0: Interrupt is er	ine Driver TOC in nabled. ıasked. (default)	terrupt mask	Κ.						
3	TCKLOS_IM	0: Interrupt is er	CLKn missing inten nabled. asked. (default)	errupt mask.							
2	TLOS_IM	0: Interrupt is er	LOS interrupt ma nabled. ıasked. (default)	sk.							
1	SLOS_IM	0: Interrupt is er	LOS interrupt ma nabled. iasked. (default)	isk.							
0	LLOS_IM	0: Interrupt is er	LOS interrupt ma nabled. lasked. (default)	sk.							

## INTM1 - Interrupt Mask Register 1

7	6	5	4	3	2	1	0			
SAIS_IM	LAIS_		-	-	•	IBA_IM	IBD_IM			
Bit	Name	Description								
7	SAIS_IM	This bit is the SAIS interrupt mask. 0: Interrupt is enabled. 1: Interrupt is masked. (default)								
6	LAIS_IM	This bit is the LAIS interrupt mask. 0: Interrupt is enabled. 1: Interrupt is masked. (default)								
5	PA_IM	This bit is the PRBS/ARB pattern synchronization interrupt mask. 0: Interrupt is enabled. 1: Interrupt is masked. (default)								
		Reserved.								

## INTM2 - Interrupt Mask Register 2

21DH,	25DH, 29DH, 2DE 45DH, 49DH, 4DE <i>(CH0)</i> ite	DH, 11DH, 15DH, 19DH, 10 DH, 31DH, 35DH, 39DH, 30 DH, 51DH, <i>(CH17~CH21)</i>									
7	6	5	4	3	2	1	0				
· ·	-	SBPV_IM	LBPV_IM	SEXZ_IM	LEXZ_IM	ERR_IM	CNTOV_IM				
Bit	Name	Description									
7 - 6	-	Reserved.									
5	SBPV_IM	This bit is the SBPV interrupt mask. 0: Interrupt is enabled. 1: Interrupt is masked. (default)									
4	LBPV_IM	This bit is the LBPV interrupt mask. 0: Interrupt is enabled. 1: Interrupt is masked. (default)									
3	SEXZ_IM	This bit is the SEXZ interrupt mask. 0: Interrupt is enabled. 1: Interrupt is masked. (default)									
2	LEXZ_IM	This bit is the LEXZ interrupt mask. 0: Interrupt is enabled. 1: Interrupt is masked. (default)									
1	ERR_IM	This bit is the PRBS/ARB 0: Interrupt is enabled. 1: Interrupt is masked. (de	·	κ.							
0	CNTOV_IM	This bit is the ERRCH an 0: Interrupt is enabled. 1: Interrupt is masked. (do	· ·	overflow interrupt ma	sk.						
#### STAT0 - Status Register 0

Address: 01EH, 05EH, 09EH, 0DEH, 11EH, 15EH, 19EH, 1DEH, <i>(CH1~CH8)</i> 21EH, 25EH, 29EH, 2DEH, 31EH, 35EH, 39EH, 3DEH, <i>(CH9~CH16)</i> 41EH, 45EH, 49EH, 4DEH, 51EH, <i>(CH17~CH21)</i> 7DEH <i>(CH0)</i> Type: Read Default Value: 00H													
7	6	5	4	3	2	1	0						
AUTOLP_S	6 -	•	TOC_S	TCKLOS_S	TLOS_S	SLOS_S	LLOS_S						
Bit	Bit Name Description												
7	AUTOLP_S	This bit indicates the auto 0: Out of automatic Digita 1: In automatic Digital/Re	al/Remote Loopback										
6 - 5	-	Reserved.											
4	TOC_S	This bit indicates the TO 0: No TOC is detected. ( 1: TOC is detected.											
3	TCKLOS_S	This bit indicates the TCI 0: TCLKn is not missing. 1: TCLKn is missing.											
2	TLOS_S	This bit indicates the TLC 0: No TLOS is detected. 1: TLOS is detected.											
1	SLOS_S	This bit indicates the SLC 0: No SLOS is detected. 1: SLOS is detected.											
0	LLOS_S	This bit indicates the LLC 0: No LLOS is detected. 1: LLOS is detected.											

#### STAT1 - Status Register 1

Address: 01FH, 0	05FH, 09FH, 0DF	H. 11FH, 15FH, 19FH	H, 1DFH, (CH1~CH8)											
			H, 3DFH, (CH9~CH16)											
		H, 51FH, (CH17~CH												
7DFH (	CH0)		,											
Type: Read														
Default Value: 00	)H													
7	6	5	4	3	2	1	0							
SAIS_S	LAIS_S	S PA_S	· ·	•	·	IBA_S	IBD_S							
			Description											
Bit	Name		Description											
7	SAIS_S		dicates the SAIS status.											
		0: No SAIS is detec	· ,											
		1: SAIS is detected												
6	LAIS_S	This bit indicates th												
		0: No LAIS is detec	· · ·											
		1: LAIS is detected		I simplify status										
5	PA_S		ne PRBS/ARB pattern syn											
			pattern is out of synchron pattern is in synchronizat											
4 - 2		Reserved.		1011.										
4-2	- IBA_S		ne activate IB code status											
	IDA_0		ode is detected. (default)											
			is detected for more than	1 40 ms when the AL	JTOLP bit (b3. LOOF	P) is '0' or activate	B code is detected for							
			when the AUTOLP bit (b			,,								
0	IBD_S	This bit indicates th	ne deactivate IB code stat	us.										
			code is detected. (defaul											
			ode is detected for more			3, LOOP,) is '0' or	r deactivate IB code is							
		detected for more t	han 5.1 sec. when the AL	JTOLP bit (b3, LOOF	P,) is '1'.									

#### INTS0 - Interrupt Status Register 0

220H, 2	260H, 2A0H, 2E0I 460H, 4A0H, 4E0I <i>(CH0)</i> ite	H, 320H	I, 160H, 1A0H, 1E0 I, 360H, 3A0H, 3E0 I, ( <i>CH17~CH21)</i>										
7	6		5	4	3	2	1	0					
DAC_IS	TJA_IS	6	RJA_IS	TOC_IS	TCKLOS_IS	TLOS_IS	SLOS_IS	LLOS_IS					
Bit	Name				Descrip	tion							
7	(default)												
6	TJA_IS	0: No 1: TJ/	Waveform amplitude overflow interrupt is generated and is reported by the INT pin. is bit indicates the interrupt status of the TJA FIFO overflow or underflow. No TJA FIFO overflow or underflow interrupt is generated; or a '1' is written to this bit. (default) TJA FIFO overflow or underflow interrupt is generated and is reported by the INT pin.										
5	RJA_IS	0: No	RJA FIFO overflow	or underflow interru	JA FIFO overflow or or pt is generated; or a s generated and is re	'1' is written to this							
4	TOC_IS	0: No 1: TO '1' on	TOC interrupt is ge C interrupt is gener the TOC_S bit (b4,	ated and is reported	ritten to this bit. (defa by the INT pin. Whe it to '1'; when the TC	n the TOC_IES bit		', a transition from '0' to nsition (from '0' to '1' or					
3	TCKLOS_IS	0: No 1: TC tion fr	TCLKn missing internu LKn missing interru om '0' to '1' on the	pt is generated and i FCKLOS_S bit (b3, S	or a '1' is written to th s reported by the INT	<sup>■</sup> pin. When the TCł o '1'; when the TCK	LOS_IES bit (b3, IN	NTES,) is '0', a transi- NTES,) is '1', any tran-					
2	TLOS_IS	0: No 1: TL( to '1' (	TLOS interrupt is g OS interrupt is gene on the TLOS_S bit	erated and is reporte (b2, STAT0,) set th	written to this bit. (de d by the INT pin. Wh	en the TLOS_IES be TLOS_IES bit (b2		'0', a transition from '0' ny transition (from '0' to					
1	SLOS_IS			', a transition from '0' to Insition (from '0' to '1' or									
0	from '1' to '0') on the SLOS_S bit (b1, STAT0,) set this bit to '1'. O LLOS_IS This bit indicates the interrupt status of the LLOS. O: No LLOS interrupt is generated; or a '1' is written to this bit. (default) 1: LLOS interrupt is generated and is reported by the INT pin. When the LOS_IES bit (b1, INTES,) is '0', a transition '1' on the LLOS_S bit (b0, STAT0,) set this bit to '1'; when the LOS_IES bit (b1, INTES,) is '1', any transition (from from '1' to '0') on the LLOS_S bit (b0, STAT0,) set this bit to '1'.												

#### INTS1 - Interrupt Status Register 1

	61H, 4A1H, 4E1H CH0) e	I, 321H, 361H, 3A1H, 3E1I I, 521H, <i>(CH17~CH21)</i>											
7	6	5	4	3	2	1	0						
SAIS_IS	LAIS_IS	S PA_IS	-	•	•	IBA_IS	IBD_IS						
Bit	Name         Description												
7	SAIS_IS	0: No SAIS interrupt is ge 1: SAIS interrupt is generation on the SAIS_S bit (b7, ST	Description         This bit indicates the interrupt status of the SAIS.         0: No SAIS interrupt is generated; or a '1' is written to this bit. (default)         1: SAIS interrupt is generated and is reported by the INT pin. When the AIS_IES bit (b6, INTES,) is '0', a transition from '0' to on the SAIS_S bit (b7, STAT1,) set this bit to '1'; when the AIS_IES bit (b6, INTES,) is '1', any transition (from '0' to '1' or from '1' to '0') on the SAIS_S bit (b7, STAT1,) set this bit to '1'.										
6	LAIS_IS	0: No LAIS interrupt is ge 1: LAIS interrupt is genera on the LAIS_S bit (b6, ST	This bit indicates the interrupt status of the LAIS. D: No LAIS interrupt is generated; or a '1' is written to this bit. (default) 1: LAIS interrupt is generated and is reported by the INT pin. When the AIS_IES bit (b6, INTES,) is '0', a transition from '0' to ' on the LAIS_S bit (b6, STAT1,) set this bit to '1'; when the AIS_IES bit (b6, INTES,) is '1', any transition (from '0' to '1' or fro 1' to '0') on the LAIS_S bit (b6, STAT1,) set this bit to '1'.										
5	PA_IS	This bit indicates the inter 0: No PRBS/ARB pattern 1: PRBS/ARB pattern syr is '0', a transition from '0' transition (from '0' to '1' o	synchronization inter achronization interrup to '1' on the PA_S	errupt is generated; pt is generated and bit (b5, STAT1,) s	or a '1' is written to the is reported by the $\overline{IN}$ set this bit to '1'; whe	T pin. When the PA_ n the PA_IES bit (b5							
4 - 2	-	Reserved.											
1	IBA_IS	This bit indicates the inter 0: No activate IB code inter 1: Activate IB code intern from '0' to '1' on the IBA '1' or from '1' to '0') on the	errupt is generated; upt is generated and S bit (b1, STAT1,)	or a '1' is written to t d is reported by the set this bit to '1'; wh	INT pin. When the I nen the IB_IES bit (b0								
0	IBD_IS	This bit indicates the inter 0: No deactivate IB code 1: Deactivate IB code inter from '0' to '1' on the IBD_ '1' or from '1' to '0') on the	interrupt is generate errupt is generated a S bit (b0, STAT1,)	d; or a '1' is written t nd is reported by the set this bit to '1'; wh	e INT pin. When the nen the IB_IES bit (b0								

#### INTS2 - Interrupt Status Register 2

	462H, 4A2H, 4E2I <i>(CH0)</i> rite	н, 322н, 362н, 3A2н, 3E; н, 522н, <i>(CH17~CH21)</i>										
7	6	5	4	3	2	1	0					
-	•	SBPV_IS	LBPV_IS	SEXZ_IS	LEXZ_IS	ERR_IS	CNTOV_IS					
Bit	Name			Descrip	otion							
7 - 6	-	Reserved.										
5	SBPV_IS	0: No SBPV interrupt is	This bit indicates the interrupt status of the SBPV. I: No SBPV interrupt is generated; or a '1' is written to this bit. (default) : SBPV interrupt is generated and is reported by the INT pin.									
4	LBPV_IS	0: No LBPV interrupt is g	This bit indicates the interrupt status of the LBPV. It No LBPV interrupt is generated; or a '1' is written to this bit. (default) It LBPV interrupt is generated and is reported by the INT pin.									
3	SEXZ_IS	This bit indicates the inte 0: No SEXZ interrupt is g 1: SEXZ interrupt is gen	enerated; or a '1' is	written to this bit. (de	efault)							
2	LEXZ_IS	This bit indicates the inte 0: No LEXZ interrupt is g 1: LEXZ interrupt is gene	enerated; or a '1' is	written to this bit. (de	fault)							
1	ERR_IS	This bit indicates the inte 0: No PRBS/ARB error i 1: PRBS/ARB error inter	nterrupt is generated	; or a '1' is written to								
0	CNTOV_IS	This bit indicates the inte 0: No ERRCH or ERRCI 1: ERRCH and ERRCL	register overflow in	terrupt is generated;	or a '1' is written to th							

#### ERRCL - Error Counter Low-Byte Register

223H, 2	263H, 2A3H, 2E3H 163H, 4A3H, 4E3H <i>CH0)</i>	, 123H, 163H, 1A3H, 1E3H , 323H, 363H, 3A3H, 3E3H , 523H, <i>(CH17~CH21)</i>												
7	6	5	5 4 3 2 1 0											
ERRC7	ERRC6	ERRC5	ERRC5 ERRC4 ERRC3 ERRC2 ERRC1 ERRC0											
Bit	Name		Description											
7 - 0	ERRC[7:0]	updated automatically or	te bits, together with the ERRC[15:8] bits, reflect the accumulated error number in the internal Error Counter. They are ted automatically or manually, as determined by the CNT_MD bit (b1, ERR,). They should be read in the next round of counting; otherwise, they will be overwritten.											

#### ERRCH - Error Counter High-Byte Register

224H, 2 424H, 4 7E4H (1	264H, 2A4H, 2E4H 164H, 4A4H, 4E4H	I, 124H, 164H, 1A4H, 1E4H I, 324H, 364H, 3A4H, 3E4H I, 524H, <i>(CH17~CH21)</i>	. ,											
Default Value: 00	pe: Read ifault Value: 00H													
7	6	5	5 4 3 2 1 0											
ERRC15	ERRC14	4 ERRC13	ERRC12	ERRC11	ERRC10	ERRC9	ERRC8							
Bit	Name		Description											
7 - 0	ERRC[15:8]	(Refer to the description o	f the ERRCL registe	er.)										

#### JM - Jitter Measurement Configuration For Channel 0 Register

Address: 7E5H Type: Read / Wr Default Value: 0													
7	6	5	4	3	2	1	0						
•	•	JM_MD	JM_BW										
Bit	Name		Description										
7 - 3	-	Reserved.											
2	JM_STOP	This bit is valid only when A transition from '0' to '1' This bit must be cleared	on this bit updates the	he JIT_PH, JIT_PL	. and JIT_NH, JIT_NL	registers.							
1	JM_MD	0: The period is determin	is bit selects the jitter measurement period. The period is determined manually by setting the JM_STOP bit (b2, JM). (default) The period is one second automatically.										
0	JM_BW	This bit selects the band 0: 20 Hz ~ 100 KHz. (def 1: 18 KHz ~ 100 KHz.		d jitter.									

#### JIT\_PL - Positive Peak Jitter Measurement Low-Byte Register

Address: 7E6H Type: Read Default Value: 00	)H						
7	6	5	4	3	2	1	0
JIT_P7	JIT_P6	JIT_P5	JIT_P4	JIT_P3	JIT_P2	JIT_P1	JIT_P0
Bit	Name			Descrip	otion		
7 - 0	JIT_P[7:0]	These bits, together with measured by channel 0. T read in the next round of j The relationship between Positive Peak = [JIT_PH,	hey are updated au tter measurement; of the greatest positive	tomatically or manua otherwise, they will b	ally, as determined by be overwritten.	the JM_MD bit (b	

#### JIT\_PH - Positive Peak Jitter Measurement High-Byte Register

ddress: 7E7H ype: Read )efault Value: 0												
7	6		5	4	3	2	1	0				
•	-		·	-	JIT_P	11 JIT_P	10 JIT_P9	JIT_P8				
Bit	Name					Description						
7 - 4	-	Reserved.										
3 - 0	JIT_P[11:8]	(Refer to the	Refer to the description of the JIT_PL register.)									

#### JIT\_NL - Negative Peak Jitter Measurement Low-Byte Register

Address: 7E8H Type: Read Default Value: 0	0Н						
7	6	5	4	3	2	1	0
JIT_N7	JIT_N6	JIT_N5	JIT_N4	JIT_N3	JIT_N2	JIT_N1	JIT_N0
Bit	Name			Descri	ption		
7 - 0	JIT_N[7:0]	These bits, together with measured by channel 0. read in the next round of The relationship between Negative Peak = [JIT_NI	They are updated a jitter measurement the greatest negat	utomatically or manu ; otherwise, they will ive peak value and th	ually, as determined be overwritten.	by the JM_MD bit (b	

#### JIT\_NH - Negative Peak Jitter Measurement High-Byte Register

Address Type: Re Default	ead	ЭH														
	7		6		5		4		3		2		1		0	
	•		-		-		-		JIT_N11	Γ	JIT_N10	Ι	JIT_N9		JIT_N8	
В	lit	Nar	ne						Des	criptio	on					
7 -	- 4	-		Reserved.												
3 -	- 0	JIT_N	[11:8]	(Refer to t	er to the description of the JIT_NL register.)											



The IDT82P2521 supports the digital Boundary Scan Specification as described in the IEEE 1149.1 standards.

The boundary scan architecture consists of data and instruction registers plus a Test Access Port (TAP) controller. The control of the TAP is achieved through signals applied to the Test Mode Select (TMS) and Test Clock (TCK) input pins. Data is shifted into the registers via the Test

Data Input (TDI) pin, and shifted out of the registers via the Test Data Output (TDO) pin. Both TDI and TDO are clocked at a rate determined by TCK.

The JTAG boundary scan registers include BSR (Boundary Scan Register), DIR (Device Identification Register), BR (Bypass Register) and IR (Instruction Register). These will be described in the following pages. Refer to Figure-47 for architecture.



#### Figure-47 JTAG Architecture

#### 6.1 JTAG INSTRUCTION REGISTER (IR)

The IR with instruction decode block is used to select the test to be executed or the data register to be accessed or both.

The instructions include: EXTEST, SAMPLE/PRELOAD, IDCODE, BYPASS, CLAMP and HIGHZ.

#### 6.2 JTAG DATA REGISTER

#### 6.2.1 DEVICE IDENTIFICATION REGISTER (IDR)

The IDR can be set to define the Version, the Part Number, the Manufacturer Identity and a fixed bit.

#### 6.2.2 BYPASS REGISTER (BYP)

The BYP consists of a single bit. It can provide a serial path between the TDI input and the TDO output. Bypassing the BYR will reduce test access times.

#### 6.2.3 BOUNDARY SCAN REGISTER (BSR)

The bidirectional ports interface to 2 boundary scan cells:

- In cell: The input cell is observable only.
- Out cell: The output cell is controllable and observable.

#### 6.3 TEST ACCESS PORT (TAP) CONTROLLER

The TAP controller is a 16-state synchronous state machine. The states include: Test Logic Reset, Run-Test/Idle, Select-DR-Scan, Capture-DR, Shift-DR, Exit1-DR, Pause-DR, Exit2-DR, Update-DR, Select-IR-Scan, Capture-IR, Shift-IR, Exit1-IR, Pause-IR, Exit2-IR and Update-IR.

Figure-48 shows the state diagram. Note that the figure contains two main branches to access either the data or instruction registers. The value shown next to each state transition in this figure states the value present at TMS at each rising edge of TCK.

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Figure-48 JTAG State Diagram

#### 7 THERMAL MANAGEMENT

The device is designed to operate over the industry temperature range -40°C ~ +85°C. To ensure the functionality and reliability of the device, the maximum junction temperature,  $T_{jmax}$ , should not exceed 125°C. In some applications, the device will consume more power and a thermal solution should be provided to ensure the junction temperature  $T_j$  does not exceed  $T_{jmax}$ . Below is a table listing thermal data for the IDT82P2521.

Package	θ <sub>JC</sub> (°C/W) <sup>1</sup>	$\theta_{\text{JB}}$ (°C/W) <sup>2</sup>	θ <sub>JA</sub> (°C/W) <sup>3</sup>	Airflow (m/s)
		0.50	16.7	0
			12.8	1
640-pin	4.00		11.3	2
TEPBGA	4.90	8.50	10.5	3
			10.1	4
			9.9	5

Note:

1. Junction-to-Case Thermal Resistance

2. Junction-to-Board Thermal Resistance

3. Junction-to-Ambient Thermal Resistance

#### 7.1 JUNCTION TEMPERATURE

Junction temperature  $T_j$  is the temperature of package typically at the geographical center of the chip where the device's electrical circuits are. It can be calculated as follows:

**Equation 1:**  $T_i = T_A + P * \theta_{JA}$ 

Where:

 $\theta_{JA}$  = Junction-to-Ambient Thermal Resistance of the package

T<sub>i</sub> = Junction Temperature

T<sub>A</sub> = Ambient Temperature

*P* = Device Power Consumption

For the IDT82P2521, the above values are:

 $\theta_{\rm JA}$  = 16.7 °C/W (when airflow rate is 0 m/s. See the above table )

*T<sub>jmax</sub>* = 125 °C

$$T_A = -40 \,^{\circ}\text{C} \sim 85 \,^{\circ}\text{C}$$

*P* = Refer to Section 8.3 Device Power Consumption and Dissipation (Typical) 1

#### 7.2 EXAMPLE OF JUNCTION TEMPERATURE CAL-CULATION

Assume:

*T*<sub>A</sub> = 85 °C

 $\theta_{JA}$  = 12.8 °C/W (airflow: 1 m/s)

 $P = 1.95 W (E1 120 \Omega, 100\% \text{ ones}, External Impedance matching})$ 

The junction temperature T<sub>i</sub> can be calculated as follows:

 $T_i = T_A + P * \theta_{JA} = 85 \text{ °C} + 1.95 W X 12.8 \text{ °C/W} = 110.0 \text{ °C}$ 

The junction temperature of **110.0** °C is below the maximum junction temperature of 125 °C, so no extra heat enhancement is required.

In some operation environments, the calculated junction temperature might exceed the maximum junction temperature of 125 °C and an external thermal solution such as a heatsink is required.

#### 7.3 HEATSINK EVALUATION

A heatsink is expanding the surface area of the device to which it is attached.  $\theta_{JA}$  is now a combination of device case and heatsink thermal resistance, as the heat flowing from the die junction to ambient goes through the package and the heatsink.  $\theta_{JA}$  can be calculated as follows:

**Equation 2:** 
$$\theta_{JA} = \theta_{JC} + \theta_{HA}$$

Where:

 $\theta_{\rm JC}$  = Junction-to-Case (heatsink) Thermal Resistance

 $\theta_{\text{HA}}$  = Heatsink-to-Ambient Thermal Resistance

For the IDT82P2521, 0,IC is 4.90 °C/W.

 $\theta_{HA}$  determines which heatsink can be selected to ensure the junction temperature does not exceed  $T_{jmax}$ . According to Equation 1 and 2, the heatsink-to-ambient thermal resistance  $\theta_{HA}$  can be calculated as follows:

**Equation 3:**  $\theta_{HA} = (T_j - T_A) / P - \theta_{JC}$ 

Assume:

$$T_j = 125 \text{ °C} (T_{jmax})$$
  
 $T_A = 85 \text{ °C}$   
 $P = 3.53 W (E1 75 \Omega, 100\% \text{ ones}, Fully Internal Impedance matching})$   
 $\theta_{JC} = 4.90 \text{ °C/W}$ 

The Heatsink-to-Ambient thermal resistance  $\theta_{\text{HA}}$  can be calculated as follows:

θ<sub>HA</sub> = (125 °C - 85 °C ) / 3.53 W - 4.90 °C/W = 6.43 °C/W

That is, if a heatsink whose heatsink-to-ambient thermal resistance  $\theta_{HA}$  is below or equal to 6.43 °C/W is used in such operation environment, the junction temperature will not exceed the maximum junction temperature.

#### 8 PHYSICAL AND ELECTRICAL SPECIFICATIONS

#### 8.1 ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Min	Max	Unit
VDDD	Digital Core Power Supply	-0.5	2.2	V
VDDA	Analog Core Power Supply	-0.5	4.6	V
VDDIO	I/O Power Supply	-0.5	4.6	V
VDDT0~21	Power Supply for Transmitter Driver	-0.5	4.6	V
VDDR0~21	Power Supply for Receiver	-0.5	4.6	V
	Input Voltage, Any Digital Pin	GND - 0.5	6	V
V <sub>in</sub>	Input Voltage, Any RTIP and RRING pin <sup>1</sup>	GND - 0.5	VDDR + 0.5	V
	ESD Voltage, Any Pin <sup>2</sup>	2000		V
	Transient Latch-up Current, Any Pin		100	mA
l <sub>in</sub>	Input Current, Any Digital Pin <sup>3</sup>	-10	10	mA
	DC Input Current, Any Analog Pin <sup>3</sup>		±100	mA
Pd	Maximum Power Dissipation in Package		2.4 <sup>4</sup>	W
Тј	Junction Temperature		125	°C
Τ <sub>s</sub>	Storage Temperature	-65	+150	°C

#### Note:

1. Reference to ground.

2. Human body model.

3. Constant input current.

4. If device power consumption exceeds this value, a heatsink must be used. Refer to Chapter 7 Thermal Management.

#### Caution:

Exceeding the above values may cause permanent damage. Functional operation under these conditions is not implied. Exposure to absolute maximum rating conditions for extended period may affect device reliability.

#### 8.2 RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур.	Max	Unit
T <sub>op</sub>	Operating Temperature Range	-40		85 <sup>1</sup>	°C
VDDIO	Digital I/O Power Supply	3.13	3.3	3.47	V
VDDA	Analog Core Power Supply	3.13	3.3	3.47	V
VDDD	Digital Core Power Supply	1.71	1.8	1.89	V
VDDT	Power Supply for Transmitter Driver	3.13	3.3	3.47	V
VDDR	Power Supply for Receiver	3.13	3.3	3.47	V
V <sub>IL</sub>	Input Low Voltage	-0.5		0.8	V
V <sub>IH</sub>	Input High Voltage	2.0		VDDIO+0.5	V
ote:	- + +		<u>I</u>	<u> </u>	

1. An external thermal solution such as heatsink may be required depending on the mode of operation. Refer to Chapter 7 Thermal Management.

#### 8.3 DEVICE POWER CONSUMPTION AND DISSIPATION (TYPICAL)<sup>1</sup>

		Total Consumption (W)			Total Device Power Dissipation (for Thermal Consideration, W)			Per-Channel Power Down Saving (mW) <sup>2</sup>		
Mode	Parameter	1.8 V	3.3 V	Total	Fully Internal R120IN=1 <sup>3</sup>	Partially Internal R120IN=0 <sup>4</sup>	External <sup>5</sup>	Fully Internal R120IN=1 <sup>3</sup>	Partially Internal R120IN=0 <sup>4</sup>	External <sup>5</sup>
E1/120 Ω	PRBS	0.23	2.22	2.45	2.45	1.88	1.59	80	60	40
	100% ones	0.23	3.00	3.23	3.23	2.40	1.95	130	90	70
E1/75 Ω	PRBS	0.23	2.40	2.62	2.62	2.28	1.64	90	60	50
	100% ones	0.23	3.30	3.53	3.53	3.01	2.06	150	120	80

#### Note:

1. Test conditions: VDDx (typical) at 25 °C operating temperature (ambient).

2. The R\_OFF bit (b5, RCF0,...) and T\_OFF bit (b5, TCF0,...) are set to '1' to enable per-channel power down.

3. The transmitter is in Internal Impedance Matching mode and the receiver is in Fully Internal Impedance Matching mode. That is, the R120IN bit (b4, RCF0,...) is set to '1'. And the T\_TERM[2:0] bits (b2~0, TCF0,...) and R\_TERM[2:0] bits (b2~0, RCF0,...) are set according to different cable conditions.

4. The transmitter is in Internal Impedance Matching mode and the receiver is in Partially Internal Impedance Matching mode. That is, the R120IN bit (b4, RCF0,...) is set to '0'. And the T\_TERM[2:0] bits (b2~0, TCF0,...) and R\_TERM[2:0] bits (b2~0, RCF0,...) are set according to different cable conditions.

5. For E1 mode, both the transmitter and the receiver are in External Impedance Matching mode. That is, the T\_TERM[2:0] bits (b2~0, TCF0,...) are set to '111' and the R\_TERM[2:0] bits (b2~0, RCF0,...) are set to '1xx'.

### 8.4 DEVICE POWER CONSUMPTION AND DISSIPATION (MAXIMUM) <sup>1</sup>

Mode Parameter	Τα	otal Consumption (	V)	Total Device Power Dissipation (for Thermal Consideration, W)			
Mode	Parameter	1.89 V	3.47 V Total		Fully Internal R120IN=1 <sup>2</sup>	Partially Internal R120IN=0 <sup>3</sup>	External <sup>4</sup>
E1/120 Ω	PRBS	0.27	2.39	2.66	2.66	2.09	1.71
	100% ones	0.28	3.20	3.48	3.48	2.64	2.07
E1/75 Ω	PRBS	0.27	2.55	2.82	2.82	2.47	1.71
	100% ones	0.27	3.50	3.78	3.78	3.26	2.12

Note:

1. Test conditions: VDDx (maximum) at 85 °C operating temperature (ambient).

2. The transmitter is in Internal Impedance Matching mode and the receiver is in Fully Internal Impedance Matching mode. That is, the R120IN bit (b4, RCF0,...) is set to '1'. And the T\_TERM[2:0] bits (b2~0, TCF0,...) and R\_TERM[2:0] bits (b2~0, RCF0,...) are set according to different cable conditions.

3. The transmitter is in Internal Impedance Matching mode and the receiver is in Partially Internal Impedance Matching mode. That is, the R120IN bit (b4, RCF0,...) is set to '0'. And the T\_TERM[2:0] bits (b2~0, TCF0,...) and R\_TERM[2:0] bits (b2~0, RCF0,...) are set according to different cable conditions.

4. For E1 mode, both the transmitter and the receiver are in External Impedance Matching mode. That is, the T\_TERM[2:0] bits (b2~0, TCF0,...) are set to '111' and the R\_TERM[2:0] bits (b2~0, RCF0,...) are set to '1xx'.

#### 8.5 D.C. CHARACTERISTICS

@ TA = -40 to +85 °C, VDDIO =  $3.3 \text{ V} \pm 5\%$ , VDDD =  $1.8 \text{ V} \pm 5\%$ 

Symbol	Parameter	Min	Тур.	Max	Unit	Test Conditions
V <sub>OL</sub>	Output Low Voltage			0.40	V	VDDIO = 3.13 V, I <sub>OL</sub> = 4 mA, 8 mA
V <sub>OH</sub>	Output High Voltage	2.4		VDDIO	V	VDDIO = 3.13 V, I <sub>OH</sub> = 4 mA, 8 mA
V <sub>T+</sub>	Schmitt Trigger Input Low to High Threshold	1.8			V	
V <sub>T-</sub>	Schmitt Trigger Input High to Low Threshold			0.7	V	
R <sub>pu</sub>	Internal Pull-up /Pull-down Resistor	50	70	115	KΩ	
IIL	Input Low Current	-1	0	+1	μA	V <sub>IL</sub> = GNDD
IIH	Input High Current	-1	0	+1	μA	V <sub>IH</sub> = VDDIO
C <sub>in</sub>	Input Digital Pin Capacitance			10	pF	
C <sub>out</sub>	Output Load Capacitance			50	pF	
C <sub>out</sub>	Output Load Capacitance (bus pins)			100	pF	
I <sub>ZL</sub>	Leakage Current of Digital Output in High-Z mode	-10		10	μA	GNDIO < V <sub>O</sub> < VDDIO
Z <sub>OH</sub>	Output High-Z on TTIPn, TRINGn pins	10			KΩ	

#### 8.6 E1 RECEIVER ELECTRICAL CHARACTERISTICS

Paran	neter	Min	Тур.	Max	Unit	Test Conditions
Receiver Sensitivity tial mode with Cable I			15		dB	with Nominal Pulse Amplitude of 3.0 V for 120 $\Omega$
Receiver Sensitivity Ended mode with C kHz			12		dB	and 2.37 V for 75 $\Omega$ termination, adding -18 dB interference signal.
Signal to Noise Interfe	erence Margin	-14			dB	@cable loss 0-6 dB
Analog LOS Level (Normal Mode)	ALOS[2:0] 000 001 (default) 010 011 100 101 110 111		0.5 0.7 0.9 1.2 1.4 1.6 1.8 2.0		V <sub>pp</sub>	In Differential mode, measured between RTIP and RRING pins. In Singled Ended mode, measured between RTIP and GNDA pins Refer to Table-9 for LLOS Criteria Declare and Clear.
	LOS hysteresis		0.25			
Analog LOS Level (Line Monitor Mode)	log LOS Level ALOS[2:0]		1.0 1.4 1.8 2.2		V <sub>pp</sub>	Measured on the line with the monitor gain set by the MG[1:0] bits (b1~0, RCF2,) equal to the resistive attenuation. Refer to Table-9 for LLOS Cri- teria Declare and Clear.
	LOS hysteresis		0.41		-	
Allowable Consecutiv G.775 I.431 / ETSI300233			32 2048			
LOS Reset		12.5			% ones	G.775, ETSI 300233
Receive Intrinsic Jitte	r			0.05	U.I.	JA disabled; wide band
Input Jitter Tolerance: 1 Hz ~ 20 Hz 20 Hz ~ 2.4 KHz 18 KHz ~ 100 KHz		37 5 2			U.I. U.I. U.I.	G.823, with 6 dB Cable Attenuation
Receiver Differential I	nput Impedance		2.6		KΩ	
Receiver Common ance to GND	Mode Input Imped-		1.6		KΩ	─ @1024 KHz; Rx port is high-Z
Receiver Single Ended mode Input Impedance to GND			3.1		KΩ	The RRINGn pins are open.
Receive Return Loss: 51 KHz ~ 102 KHz 102 KHz ~ 2.048 M 2.048 MHz ~ 3.072	<u>z</u> 1Hz	12 18 14			dB dB dB	G.703
Receive Path Delay: Single Rail Dual Rail NRZ Dual Rail RZ				6.6 1.8 1.5	U.I. U.I. U.I.	JA Disabled

#### 8.7 E1 TRANSMITTER ELECTRICAL CHARACTERISTICS

Parameter		Min	Тур.	Max	Unit	Test Conditions
Output Pulse Amplitude: E1, 75 $\Omega$ load E1, 120 $\Omega$ load		2.14 2.7	2.37 3.0	2.60 3.3	V V	Differential Line Inter- face mode
Zero (Space) Level: E1, 75 $\Omega$ load E1, 120 $\Omega$ load		-0.237 -0.3		+0.237 0.3	V V	Differential Line Inter- face mode
Transmit Amplitude Variation with Supp	bly	-1		+1	%	
Difference between Pulse Sequences f (T1.102)	or 17 consecutive pulses			200	mV	
Output Pulse Width at 50% of Nominal	Amplitude	232	244	256	ns	
Ratio of the Amplitudes of Positive and Negative Pulses at the Center of the Pulse Interval (G.703)		0.95		1.05		
Ratio of the Width of Positive and Negative Pulses at the Center of the Pulse Interval (G.703)		0.95		1.05		
Transmit Analog LOS Level (TALOS) (Differential line interface)	TALOS[1:0] 00 01 (default) 10 11		1.2 0.9 0.6 0.4		Vp	Measured on the TTIP and TRING pins.
	TALOS hysteresis		0.08			
Transmit Analog LOS Level (TALOS) (Single Ended line interface)	TALOS[1:0] 00 01 (default) 10 11		0.61 0.48 0.32 0.24		V <sub>p</sub>	Measured on the TTIP pin.
	TALOS hysteresis		0.04			
Transmit Return Loss (G.703): 51 KHz ~ 102 KHz 102 KHz ~ 2.048 MHz 2.048 MHz ~ 3.072 MHz		8 14 10			dB dB dB	
Intrinsic Transmit Jitter 20 Hz ~ 100 KHz				0.050	U.I.	TCLK is jitter free
Transmit Path Delay: Single Rail Dual Rail NRZ Dual Rail RZ			8.5 4.5 4.4		U.I. U.I. U.I.	JA is disabled
Line Short Circuit Current			100	1	mAp	Measured on pin

#### 8.8 TRANSMITTER AND RECEIVER TIMING CHARACTERISTICS

Symbol	Parameter	Min	Тур.	Мах	Unit
	MCLK Frequency: E1		2.048 X n (n = 1 ~ 8)		MHz
	MCLK Tolerance	-100		100	ppm
	MCLK Duty Cycle	30		70	%
Transmit Path					
	TCLK Frequency: E1		2.048		MHz
	TCLK Tolerance	-50		+50	ppm
	TCLK Duty Cycle	10		90	%
t1	Transmit Data Setup Time	40			ns
t2	Transmit Data Hold Time	40			ns
	Delay Time of OE low to Driver High-Z			1	μs
	Delay Time of TCLK low to Driver High-Z		TBD		μs
Receive Path	- <b>·</b>				
	Clock Recovery Capture Range <sup>1</sup> : E1		+80 / -80		ppm
	RCLK Duty Cycle <sup>2</sup>	40	50	60	%
t4	RCLK Pulse Width <sup>2</sup> : E1	457	488	519	ns
t5	RCLK Pulse Width Low Time: E1	203	244	285	ns
t6	RCLK Pulse Width High Time: E1	203	244	285	ns
	Rise/Fall Time <sup>3</sup>	20			ns
t7	Receive Data Setup Time: E1	200	244		ns
t8	Receive Data Hold Time: E1	200	244		ns

Note:

1. Relative to nominal frequency, MCLK = +100 or -100 ppm.

2. RCLK duty cycle width will vary depending on extent of the received pulse jitter displacement. Maximum and minimum RCLK duty cycles are for worst case jitter conditions (0.2 UI displacement for E1 per ITU G.823).

**3.** For all digital outputs.  $C_{load}$  = 15 pF.







Figure-50 Receive Clock Timing Diagram

IESAS

DT82P2521

#### 8.9 CLKE1 TIMING CHARACTERISTICS

Symbol	Parameter	Min	Тур.	Max	Unit
CLKE1 outputs 2.0	48 MHz clock		1	I	-
t1	CLKE1 Pulse Width		488		ns
t2	CLKE1 Pulse Width High Time	232	244	256	ns
t3	CLKE1 Pulse Width Low Time	232	244	256	ns
t4	LLOS Data Setup Time	217	244	271	ns
t5	LLOS Data Hold Time	217	244	271	ns
CLKE1 outputs 8kl	Hz clock			I	1
t1	CLKE1 Pulse Width		125		μs
t2	CLKE1 Pulse Width High Time	62.4	62.5	62.6	μs
t3	CLKE1 Pulse Width Low Time	62.4	62.5	62.6	μs
t4	LLOS Data Setup Time	62.38	62.5	62.62	μs
t5	LLOS Data Hold Time	62.38	62.5	62.62	μs



#### Figure-51 CLKE1 Clock Timing Diagram

#### 8.10 JITTER ATTENUATION CHARACTERISTICS

Parameter		Min	Тур.	Мах	Unit
Jitter Transfer Function Corner (-3 dB) Frequency: E1, 32/64/128-bit FIFO	JA_BW = 0 JA_BW = 1		6.63 0.87		Hz Hz



	Parameter	Min	Тур.	Max	Unit
Jitter Attenuator:					
E1 (G.736)	@ 3 Hz	-0.5			dB
	@ 40 Hz	-0.5			dB
	@ 400 Hz	+19.5			dB
	@ 100 KHz	+19.5			dB
Jitter Attenuator Latency Delay:					
32-bit FIFO			16		U.I.
64-bit FIFO			32		U.I.
128-bit FIFO			64		U.I.
Input Jitter Tolerance before FIF	O Overflow or				
Underflow:			28		U.I.
32-bit FIFO			56		U.I.
64-bit FIFO			120		U.I.
128-bit FIFO					



Figure-52 E1 Jitter Tolerance Performance





Figure-53 E1 Jitter Transfer Performance

#### 8.11 MICROPROCESSOR INTERFACE TIMING

#### 8.11.1 SERIAL MICROPROCESSOR INTERFACE

A falling transition on  $\overline{CS}$  indicates the start of a read/write operation, and a rising transition indicates the end of the operation. After  $\overline{CS}$  is set to low, a 5-bit instruction on SDI is input to the device on the rising edge of SCLK. If the MSB is '1', it is a read operation. If the MSB is '0', it is a write operation. Following the instruction, an 11-bit address is clocked in on SDI to specify the register. If the device is in a read operation, the data read from the specified register is output on SDO on the falling edge of SCLK (refer to Figure-54). If the device is in a write operation, the data written to the specified register is input on SDI following the address byte (refer to Figure-55).



Figure-55 Write Operation in Serial Microprocessor Interface

High-Z

SDO

Symbol	Description	Min.	Max.	Units
f <sub>OP</sub>	SCLK Frequency		2.0	MHz
t <sub>CSH</sub>	Minimum CS High Time	100		ns
t <sub>CSS</sub>	CS Setup Time	50		ns
t <sub>CSD</sub>	CS Hold Time	100		ns
t <sub>CLD</sub>	Clock Disable Time	50		ns
t <sub>CLH</sub>	Clock High Time	205		ns
t <sub>CLL</sub>	Clock Low Time	205		ns
t <sub>DIS</sub>	Data Setup Time	50		ns
t <sub>DIH</sub>	Data Hold Time	150		ns
t <sub>PD</sub>	Output Delay		150	ns
t <sub>DF</sub>	Output Disable Time		50	ns



Figure-56 Timing Diagram

#### 8.11.2 PARALLEL MOTOROLA NON-MULTIPLEXED MICROPROCESSOR INTERFACE

#### 8.11.2.1 Read Cycle Specification

Symbol	Parameter	Min	MAX	Units
t <sub>SAR</sub>	Address to valid read setup time	5		ns
t <sub>RSW</sub>	Valid read signal width	38 or wait until ACK activated		ns
t <sub>HAR</sub>	Address to valid read hold time	0		ns
t <sub>RWV</sub>	$R/\overline{W}$ available time after valid $\overline{CS} + \overline{DS}$ signal falling edge	0		ns
t <sub>RWH</sub>	$R/\overline{W}$ hold time after valid $\overline{CS} + \overline{DS}$ signal falling edge	33		ns
t <sub>PRD</sub>	Data propagation delay after valid $\overline{CS} + \overline{DS}$ signal falling edge		33	ns
t <sub>ZRD</sub>	Valid read negated to output High-Z	5	20	ns



Figure-57 Parallel Motorola Non-Multiplexed Microprocessor Interface Read Cycle

#### 8.11.2.2 Write Cycle Specification

Symbol	Parameter	Min	MAX	Units
t <sub>SAW</sub>	Address to valid write setup time	0		ns
t <sub>WSW</sub>	Valid write signal width	5 or wait until ACK activated		ns
t <sub>HAW</sub>	Address to valid write hold time	35		ns
t <sub>RWV</sub>	$R/\overline{W}$ available time after valid write signal falling edge	0		ns
t <sub>RWH</sub>	$R/\overline{W}$ hold time after valid write signal falling edge	5 or wait until ACK activated		ns
t <sub>DV</sub>	Data available time before valid write signal rising edge	5		ns
t <sub>DH</sub>	Valid data hold time after valid write signal rising edge	5		ns
t <sub>REC</sub>	Recovery time from write cycle	5		ns



Figure-58 Parallel Motorola Non-Multiplexed Microprocessor Interface Write Cycle

#### 8.11.3 PARALLEL INTEL NON-MULTIPLEXED MICROPROCESSOR INTERFACE

#### 8.11.3.1 Read Cycle Specification

Symbol	Parameter	Min	MAX	Units
t <sub>SAR</sub>	Address to valid read setup time	5		ns
t <sub>RSW</sub>	Valid read signal width	33 or wait until RDY activated		ns
t <sub>HAR</sub>	Address to valid read hold time	0		ns
t <sub>PRD</sub>	Data propagation delay after valid read signal falling edge		28	ns
t <sub>ZRD</sub>	Valid read negated to output High-Z	5	20	ns



Note: WR shall be tied to high.

Figure-59 Parallel Intel Non-Multiplexed Microprocessor Interface Read Cycle

#### 8.11.3.2 Write Cycle Specification

Symbol	Parameter	Min	MAX	Units
t <sub>SAW</sub>	Address to valid write setup time	0		ns
t <sub>WSW</sub>	Valid write signal width	5 or wait until RDY activated		ns
t <sub>HAW</sub>	Address to valid write hold time	35		ns
t <sub>DV</sub>	Data available time before valid write signal rising edge	5		ns
t <sub>DH</sub>	Valid data hold time after valid write signal rising edge	5		ns
t <sub>REC</sub>	Recovery time from write cycle	5		ns



Note:  $\overline{\text{RD}}$  shall be tied to high.

Figure-60 Parallel Intel Non-Multiplexed Microprocessor Interface Write Cycle

#### 8.11.4 PARALLEL MOTOROLA MULTIPLEXED MICROPROCESSOR INTERFACE

#### 8.11.4.1 Read Cycle Specification

Symbol	Parameter	Min	MAX	Units
t <sub>ASW</sub>	Valid AS signal width	5		ns
t <sub>RSW</sub>	Valid read signal width	38 or wait until ACK activated		ns
t <sub>CSD</sub>	Valid $\overline{\text{DS}}$ + $\overline{\text{CS}}$ falling edge delay after AS	0		ns
t <sub>RWV</sub>	$R/\overline{W}$ available time after valid $\overline{DS} + \overline{CS}$ signal falling edge	0		ns
t <sub>RWH</sub>	$R/\overline{W}$ hold time after valid $\overline{DS} + \overline{CS}$ signal falling edge	33		ns
t <sub>VAS</sub>	Valid address to AS setup time	5		ns
t <sub>VAH</sub>	Valid address to AS hold time	5		ns
t <sub>PRD</sub>	Data propagation delay after valid $\overline{\text{DS}}$ + $\overline{\text{CS}}$ signal falling edge		33	ns
t <sub>ZRD</sub>	Valid read negated to output High-Z before valid AS rising edge	5	20	ns



Figure-61 Parallel Motorola Multiplexed Microprocessor Interface Read Cycle

#### 8.11.4.2 Write Cycle Specification

Symbol	Parameter	Min	MAX	Units
t <sub>ASW</sub>	Valid AS signal width	5		ns
t <sub>WSW</sub>	Valid write signal width	5 or wait until ACK acti- vated		ns
t <sub>HCW</sub>	$\overline{\text{DS}}$ + $\overline{\text{CS}}$ to valid hold time	35		ns
t <sub>RWV</sub>	$R/\overline{W}$ available time after valid write signal falling edge	0		ns
t <sub>RWH</sub>	$R/\overline{W}$ hold time after valid write signal falling edge	5		ns
t <sub>CSD</sub>	Valid $\overline{\text{DS}}$ + $\overline{\text{CS}}$ falling edge delay after AS	0		ns
t <sub>VAS</sub>	Valid address to AS setup time	5		ns
t <sub>VAH</sub>	Valid address to AS hold time	5		ns
t <sub>ASD</sub>	Valid AS rising edge delay after $\overline{\text{DS}}$ + $\overline{\text{CS}}$ rising edge	5		ns
t <sub>DV</sub>	Data available time before valid write signal rising edge	5		ns
t <sub>DH</sub>	Valid data hold time after valid write signal rising edge before the next AS rising edge	5		ns



Figure-62 Parallel Motorola Multiplexed Microprocessor Interface Write Cycle

#### 8.11.5 PARALLEL INTEL MULTIPLEXED MICROPROCESSOR INTERFACE

#### 8.11.5.1 Read Cycle Specification

Symbol	Parameter	Min	MAX	Units
t <sub>AEW</sub>	Valid ALE signal width	5		ns
t <sub>RSW</sub>	Valid read signal width	33 or wait until RDY activated		ns
t <sub>CSD</sub>	Valid $\overline{RD}$ + $\overline{CS}$ falling edge delay after ALE falling edge	0		ns
t <sub>VAS</sub>	Valid address to ALE setup time	5		ns
t <sub>VAH</sub>	Valid address to ALE hold time	5		ns
t <sub>PRD</sub>	Data propagation delay after valid read signal falling edge		28	ns
t <sub>ZRD</sub>	Valid read negated to output High-Z before valid ALE rising edge	5	20	ns



Note: WR shall be tied to high.

#### Figure-63 Parallel Intel Multiplexed Microprocessor Interface Read Cycle

#### 8.11.5.2 Write Cycle Specification

Symbol	Parameter	Min	MAX	Units
t <sub>AEW</sub>	Valid ALE signal width	5		ns
t <sub>WSW</sub>	Valid write signal width	5 or wait until RDY acti- vated		ns
t <sub>HCW</sub>	WR + CS to valid hold time	35		ns
t <sub>CSD</sub>	Valid $\overline{WR} + \overline{CS}$ falling edge delay after ALE falling edge	0		ns
t <sub>VAS</sub>	Valid address to ALE setup time	5		ns
t <sub>VAH</sub>	Valid address to ALE hold time	5		ns
t <sub>AED</sub>	Valid ALE rising edge delay after WR + CS rising edge	5		ns
t <sub>DV</sub>	Data available time before valid write signal rising edge	5		ns
t <sub>DH</sub>	Valid data hold time after valid write signal rising edge before the next AS rising edge	5		ns



Note:  $\overline{\text{RD}}$  shall be tied to high.

#### Figure-64 Parallel Intel Multiplexed Microprocessor Interface Write Cycle

#### 8.12 JTAG TIMING CHARACTERISTICS

Symbol	Parameter	Min	Тур.	Мах	Unit
t1	TCK Period	100			ns
t2	TMS to TCK Setup Time; TDI to TCK Setup Time	25			ns
t3	TCK to TMS Hold Time; TCK to TDI Hold Time	25			ns
t4	TCK to TDO Delay Time			50	ns





# RENESAS



# Glossary

AIS	_	Alarm Indication Signal
AMI	_	Alternate Mark Inversion
ARB	_	Arbitrary Pattern
BPV	_	Bipolar Violation
CF	_	Corner Frequency
CV	_	Code Violation
DPLL	_	Digital Phase Locked Loop
EXZ	_	Excessive Zeroes
FIFO	_	First In First Out
HDB3	_	High Density Bipolar 3
HPS	_	Hitless Protection Switching
IB	_	Inband Loopback
LAIS	_	Line Alarm Indication Signal
LBPV	_	Line Bipolar Violation
LEXZ	_	Line Excessive Zeroes
LLOS	_	Line Loss of Signal
LOS	_	Loss Of Signal
NRZ	_	Non-Return to Zero
PBX	_	Private Branch Exchange
PRBS	_	Pseudo Random Bit Sequence
QRSS	_	Quasi-Random Signal Source
RJA	_	Receive Jitter Attenuator
RZ	_	Return to Zero
SAIS	_	System Alarm Indication Signal
SBPV	_	System Bipolar Violation
SDH	_	Synchronous Digital Hierarchy
SEXZ	_	System Excessive Zeroes

#### RENESAS IDT82P2521

SLOS	_	System LOS
SONET	_	Synchronous Optical Network
TEPBGA	_	Thermally Enhanced Plastic Ball Grid Array
TJA	_	Transmit Jitter Attenuator
TLOS	_	Transmit Loss of Signal
тос	_	Transmit Over Current

# RENESAS

# 

#### A

Alarm Indication Signal (AIS)	46

#### В

Bipolar Violation (BPV)	

#### С

cable coaxial cable
clock input MCLK
clock output
CLKE1
REFA/REFB61
CLKA/CLKB61
MCLK61
recovery clock61
Code Violation (CV)42
common control
Corner Frequency (CF)41

#### D

#### Ε

encoder	. 35
error counter	. 49
Excessive Zeroes (EXZ)	. 42

#### F

free running	;1
--------------	----

#### G

G.772 Monitoring	
------------------	--

#### Η

Index

heatsink	119
high impedance	18, 29, 34, 38, 40
Hitless Protection Switch (HPS)	

#### 

#### L

impedance matching	
receive	
External Impedance Matching	
Fully Internal Impedance Matching	
Partially Internal Impedance Matching	29
transmit	
External Impedance Matching	38
Internal Impedance Matching	
Interrupt	66

#### J

JA-Limit	
Jitter Measurement (JM)	
JTAG	

#### L

line interface
Differential
Single Ended
transmit
Differential
Single Ended
line monitor
loopback
Analog Loopback
Digital Loopback
Dual Loopback
Manual Remote Loopback + Automatic Digital Loopback
Manual Remote Loopback + Manual Digital Loopback
Remote Loopback
Loss of Signal (LOS)
Line LOS (LLOS)
System LOS (SLOS) 44
Transmit LOS (TLOS)

#### М

microprocessor interface	 59
monitoring	

# Index

# RENESAS

21(+1) CHANNEL HIGH-DENSITY E1 LINE INTERFACE UNIT
--

G.772 monitoring	58
line monitor	32

#### Ρ

pattern	
ARB	47, 48
Inband Loopback (IB)	
PRBS	
power down	34 40
receiver	
•	

#### R

receive sensitivity	
reset	
global software reset	
hardware reset	
power-on reset	

#### S

slicer	33
system interface	34
receive	
Dual Rail NRZ Format	33
Dual Rail RZ Format	33
Dual Rail Sliced	33
Single Rail NRZ Format	33
transmit	
Dual Rail NRZ Format	
Dual Rail RZ Format	
Single Rail NRZ Format	34
т	
Transmit Over Current (TOC)	52

#### W

waveform template	
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#### **ORDERING INFORMATION**



#### **Data Sheet Document History**

12/07/2005 Pages 10, 20, 23, 43, 70, 71, 72, 119, 120, 125, 132

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